

Intel[®] Xeon[®] Processor 5500 Series

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Revision History

Reference Number	Revision Number	Description	Date
321322	001	Public release	March 2009
321322	002	Added Chapter 3 "DIMM Population Requirements"	April 2009







1 Introduction

The Intel® Xeon® Processor 5500 Series is the first generation DP server/workstation processor to implement key new technologies:

- · Integrated Memory Controller
- Point-to-point link interface based on Intel® QuickPath Interconnect (Intel® QPI).
 Reference to this interface may sometimes be abbreviated with Intel QPI throughout this document.

The processor is optimized for performance with the power efficiencies of a low-power microarchitecture to enable smaller, quieter systems.

This document provides register documentation and functional description of major functional areas of the processor non-core design such as the memory controller and Intel QPI logic, and additional features pertinent to implementation and operation of the processor.

The Intel Xeon Processor 5500 Series are multi-core processors, based on 45 nm process technology. Processor features vary by SKU and include up to two Intel QuickPath Interconnect point to point links capable of up to 6.4 GT/s, up to 8 MB of shared cache, and an integrated memory controller. The processors support all the existing Streaming SIMD Extensions 2 (SSE2), Streaming SIMD Extensions 3 (SSE3) and Streaming SIMD Extensions 4 (SSE4). The processor supports several Advanced Technologies: Execute Disable Bit, Intel® 64 Technology, Enhanced Intel® SpeedStep Technology, Intel® Virtualization Technology (Intel® VT), and Intel® Hyper-Threading Technology.

1.1 Terminology

A '#' symbol after a signal name refers to an active low signal, indicating a signal is in the active state when driven to a low level. For example, when RESET# is low, a reset has been requested.

1.1.1 Processor Terminology

Commonly used terms are explained here for clarification:

- DDR3 Double Data Rate 3 synchronous dynamic random access memory (SDRAM) is the name of the new DDR memory standard that is being developed as the successor to DDR2 SDRAM.
- Enhanced Intel SpeedStep® Technology Enhanced Intel SpeedStep Technology allows trade-offs to be made between performance and power consumption.
- Execute Disable Bit Execute Disable allows memory to be marked as executable or non-executable, when combined with a supporting operating system. If code attempts to run in non-executable memory the processor raises an error to the operating system. This feature can prevent some classes of viruses or worms that exploit buffer over run vulnerabilities and can thus help improve the overall security of the system. See the Intel® 64 and IA-32 Architectures Software Developer's Manual for more detailed information. Refer to http://developer.intel.com/ for future reference on up to date nomenclatures.



- **Eye Definitions** The eye at any point along the data channel is defined to be the creation of overlapping of a large number of Unit Interval of the data signal and timing width measured with respect to the edges of a separate clock signal at any other point. Each differential signal pair by combining the D+ and D- signals produces a signal eye.
- 1366-land LGA package The processor is available in a Land Grid Array (LGA) package, consisting of the processor die mounted on a land grid array substrate with an integrated heat spreader (IHS).
- Functional Operation Refers to the normal operating conditions in which all processor specifications, including DC, AC, system bus, signal quality, mechanical, and thermal, are satisfied.
- Integrated Memory Controller (IMC) A memory controller that is integrated in the processor silicon.
- Integrated Heat Spreader (IHS) A component of the processor package used to enhance the thermal performance of the package. Component thermal solutions interface with the processor at the IHS surface.
- Intel® 64 Architecture An enhancement to Intel's IA-32 architecture, allowing the processor to execute operating systems and applications written to take advantage of Intel 64. Further details on Intel 64 architecture and programming model can be found at http://developer.intel.com/technology/intel64/.
- Intel[®] QuickPath Interconnect A cache-coherent, link-based interconnect specification for Intel processor, chipset, and I/O bridge components. Sometimes abbreviated as Intel OPI.
- Intel® QPI Abbreviation for Intel® QuickPath Interconnect.
- Intel® Virtualization Technology (Intel® VT) A set of hardware enhancements to Intel server and client platforms that can improve virtualization solutions. Intel VT provides a foundation for widely-deployed virtualization solutions and enables more robust hardware assisted virtualization solutions. More information can be found at: http://www.intel.com/technology/virtualization/
- Jitter Any timing variation of a transition edge or edges from the defined Unit Interval.
- LGA1366 Socket The processor (in the LGA-1366 package) mates with the system board through this surface mount, 1366-contact socket.
- Mirror Port Pads located on the top side of the processor package used to provide logic analyzer probing access for Intel QPI signal analysis.
- Non-core The portion of the processor comprising the shared cache, IMC and Intel QPI Link interface.
- **OEM** Original Equipment Manufacturer.
- Storage Conditions Refers to a non-operational state. The processor may be installed in a platform, in a tray, or loose. Processors may be sealed in packaging or exposed to free air. Under these conditions, processor lands should not be connected to any supply voltages, have any I/Os biased, or receive any clocks.
- Intel Xeon Processor 5500 Series The 2S server/workstation product, including processor substrate and integrated heat spreader (IHS).



Unit Interval (UI) — Signaling convention that is binary and unidirectional. In
this binary signaling, one bit is sent for every edge of the forwarded clock, whether
it be a rising edge or a falling edge. If a number of edges are collected at instances
t₁, t₂, t_n,...., t_k then the UI at instance "n" is defined as:

$$UI_n = t_n - t_{n-1}$$

1.2 References

Material and concepts available in the following documents may be beneficial when reading this document:

Table 1-1. References

Document	Reference #	Notes
Intel® 64 and IA-32 Architectures Software Developer's Manual		1
Volume 1: Basic Architecture	253665	
Volume 2A: Instruction Set Reference, A-M	253666	
Volume 2B: Instruction Set Reference, N-Z	253667	
Volume 3A: System Programming Guide, Part 1	253668	
Volume 3B: Systems Programming Guide, Part 2	253669	
Intel® 64 and IA-32 Architectures Optimization Reference Manual	248966	1
Intel® Xeon® Processor 5500 Series Specification Update 321324		
Intel® Xeon® Processor 5500 Series Datasheet, Volume 1	321321	1

Notes:

1. Document is available publicly at http://www.intel.com.







2 Register Description

The processor supports PCI configuration space accesses using the mechanism denoted as Configuration Mechanism in the PCI specification as defined in the PCI Local Bus Specification, as well as the PCI Express enhanced configuration mechanism as specified in the PCI Express Base Specification. All the registers are organized by bus, device, function, etc. as defined in the PCI Express Base Specification. All processor registers appear on the PCI bus assigned for the processor socket. Bus number is derived by the max bus range setting and processor socket number. All multi-byte numeric fields use "little-endian" ordering (i.e., lower addresses contain the least significant parts of the field).

As processor features vary by SKU, not all of the register descriptions in this document apply to all processors. This document highlights registers which do not apply to all processor SKUs. Refer to the particular processor's Specification Update for a list of features supported.

2.1 Register Terminology

Registers and register bits are assigned one or more of the following attributes. These attributes define the behavior of register and the bit(s) that are contained with in. All bits are set to default values by hard reset. Sticky bits retain their states between hard resets.

Term	Description
RO	Read Only . If a register bit is read only, the hardware sets its state. The bit may be read by software. Writes to this bit have no effect.
WO	Write Only. The register bit is not implemented as a bit. The write causes some hardware event to take place.
RW	Read/Write. A register bit with this attribute can be read and written by software.
RC	Read Clear: The bit or bits can be read by software, but the act of reading causes the value to be cleared.
RCW	Read Clear/Write: A register bit with this attribute will get cleared after the read. The register bit can be written.
RW1C	Read/Write 1 Clear. A register bit with this attribute can be read or cleared by software. In order to clear this bit, a one must be written to it. Writing a zero will have no effect.
RW0C	Read/Write O Clear. A register bit with this attribute can be read or cleared by software. In order to clear this bit, a zero must be written to it. Writing a one will have no effect.
RW1S	Read/Write 1 Set: A register bit can be either read or set by software. In order to set this bit, a one must be written to it. Writing a zero to this bit has no effect. Hardware will clear this bit.
RW0S	Read/Write O Set: A register bit can be either read or set by software. In order to set this bit, a zero must be written to it. Writing a one to this bit has no effect. Hardware will clear this bit.
RWL	Read/Write/Lock. A register bit with this attribute can be read or written by software. Hardware or a configuration bit can lock the bit and prevent it from being updated.
RWO	Read/Write Once. A register bit with this attribute can be written to only once after power up. After the first write, the bit becomes read only. This attribute is applied on a bit by bit basis. For example, if the RWO attribute is applied to a 2 bit field, and only one bit is written, then the written bit cannot be rewritten (unless reset). The unwritten bit, of the field, may still be written once. This is special case of RWL.
RRW	Read/Restricted Write. This bit can be read and written by software. However, only supported values will be written. Writes of non supported values will have no effect.
L	Lock. A register bit with this attribute becomes Read Only after a lock bit is set.



Term	Description
RSVD	Reserved Bit. This bit is reserved for future expansion and must not be written. The <i>PCI Local Bus Specification</i> requires that reserved bits must be preserved. Any software that modifies a register that contains a reserved bit is responsible for reading the register, modifying the desired bits, and writing back the result.
Reserved Bits	Some of the processor registers described in this section contain reserved bits. These bits are labeled "Reserved". Software must deal correctly with fields that are reserved. On reads, software must use appropriate masks to extract the defined bits and not rely on reserved bits being any particular value. On writes, software must ensure that the values of reserved bit positions are preserved. That is, the values of reserved bit positions must first be read, merged with the new values for other bit positions and then written back. Note that software does not need to perform a read-merge-write operation for the Configuration Address (CONFIG_ADDRESS) register.
Reserved Registers	In addition to reserved bits within a register, the processor contains address locations in the configuration space that are marked either "Reserved" or "Intel Reserved". The processor responds to accesses to "Reserved" address locations by completing the host cycle. When a "Reserved" register location is read, a zero value is returned. ("Reserved" registers can be 8, 16, or 32 bits in size). Writes to "Reserved" registers have no effect on the processor. Registers that are marked as "Intel Reserved" must not be modified by system software. Writes to "Intel Reserved" registers may cause system failure. Reads to "Intel Reserved" registers may return a non-zero value.
Default Value upon a Reset	Upon a reset, the processor sets all of its internal configuration registers to predetermined default states. Some register values at reset are determined by external strapping options. The default state represents the minimum functionality feature set required to successfully bring up the system. Hence, it does not represent the optimal system configuration. It is the responsibility of the system initialization software (usually BIOS) to properly determine the DRAM configurations, operating parameters and optional system features that are applicable, and to program the processor registers accordingly.
"ST" appended to the end of a bit name	The bit is "sticky" or unchanged by a hard reset. These bits can only be cleared by a PWRGOOD reset.

2.2 Platform Configuration Structure

The processor contains 6 PCI devices within a single physical component. The configuration registers for these devices are mapped as devices residing on the PCI bus assigned for the processor socket. Bus number is derived by the max bus range setting and processor socket number.

- **Device 0:** Generic processor non-core. Device 0, Function 0 contains the generic non-core configuration registers for the processor and resides at DID (Device ID) of 2C40h. Device 0, Function 1 contains the System Address Decode registers and resides at DID of 2C01h.
- Device 2: Intel QPI. Device 2, Function 0 contains the Intel® QuickPath Interconnect configuration registers for Intel QPI Link 0 and resides at DID of 2C10h. Device 2, Function 1 contains the physical layer registers for Intel QPI Link 0 and resides at DID of 2C11h. Device 2, Function 4 contains the Intel® QuickPath configuration registers for Intel® QuickPath Interconnect Link 1 and resides at DID of 2C14h. Device 2, Function 5 contains the physical layer registers for Intel QPI Link 1 and resides at DID of 2C15h. Functions 4 and 5 only apply to processors with two Intel QPI links.
- Device 3: Integrated Memory Controller. Device 3, Function 0 contains the general registers for the Integrated Memory Controller and resides at DID of 2C18h. Device 3, Function 1 contains the Target Address Decode registers for the Integrated Memory Controller and resides at DID of 2C19h. Device 3, Function 2 contains the RAS registers for the Integrated Memory Controller and resides at DID of 2C1Ah. Device 3, Function 4 contains the test registers for the Integrated Memory Controller and resides at DID of 2C1Ch. Function 2 only applies to processors supporting registered DIMMs.
- **Device 4:** Integrated Memory Controller Channel 0. Device 4, Function 0 contains the control registers for Integrated Memory Controller Channel 0 and resides at



DID of 2C20h. Device 4, Function 1 contains the address registers for Integrated Memory Controller Channel 0 and resides at DID of 2C21h. Device 4, Function 2 contains the rank registers for Integrated Memory Controller Channel 0 and resides at DID of 2C22h. Device 4, Function 3 contains the thermal control registers for Integrated Memory Controller Channel 0 and resides at DID of 2C23h.

- Device 5: Integrated Memory Controller Channel 1. Device 5, Function 0 contains the control registers for Integrated Memory Controller Channel 1 and resides at DID of 2C28h. Device 5, Function 1 contains the address registers for Integrated Memory Controller Channel 1 and resides at DID of 2C29h. Device 5, Function 2 contains the rank registers for Integrated Memory Controller Channel 1 and resides at DID of 2C2Ah. Device 5, Function 3 contains the thermal control registers for Integrated Memory Controller Channel 1 and resides at DID of 2C2Bh.
- Device 6: Integrated Memory Controller Channel 2. Device 6, Function 0 contains the control registers for Integrated Memory Controller Channel 2 and resides at DID of 2C30h. Device 6, Function 1 contains the address registers for Integrated Memory Controller Channel 2 and resides at DID of 2C31h. Device 6, Function 2 contains the rank registers for Integrated Memory Controller Channel 2 and resides at DID of 2C32h. Device 6, Function 3 contains the thermal control registers for Integrated Memory Controller Channel 2 and resides at DID of 2C33h.

2.3 Device Mapping

Each component in the processor is uniquely identified by a PCI bus address consisting of Bus Number, Device Number and Function Number. Device configuration is based on the PCI Type 0 configuration conventions. All processor registers appear on the PCI bus assigned for the processor socket. Bus number is derived by the max bus range setting and processor socket number.



Table 2-1. Functions Specifically Handled by the Processor

Component	Register Group	DID	Device	Function
Processor	Intel® QuickPath Architecture Generic Non-core Registers	2C40h	0	0
	Intel® QuickPath Architecture System Address Decoder	2C01h		1
	Intel QPI Link 0	2C10h	2	0
	Intel QPI Physical 0	2C11		1
	Intel QPI Link 1	2C14h		4 ¹
	Intel QPI Physical 1	2C15h		5 ¹
	Integrated Memory Controller Registers	2C18h	3	0
	Integrated Memory Controller Target Address Decoder	2C19h		1
	Integrated Memory Controller RAS Registers	2C1Ah		2 ²
	Integrated Memory Controller Test Registers	2C1Ch		4
	Integrated Memory Controller Channel 0 Control	2C20h	4	0
	Integrated Memory Controller Channel 0 Address	2C21h		1
	Integrated Memory Controller Channel 0 Rank	2C22h		2
	Integrated Memory Controller Channel 0 Thermal Control	2C23h		3
	Integrated Memory Controller Channel 1 Control	2C28h	5	0
	Integrated Memory Controller Channel 1 Address	2C29h		1
	Integrated Memory Controller Channel 1 Rank	2C2Ah		2
	Integrated Memory Controller Channel 1 Thermal Control	2C2Bh		3
	Integrated Memory Controller Channel 2 Control	2C30h	6	0
	Integrated Memory Controller Channel 2 Address	2C31h		1
	Integrated Memory Controller Channel 2 Rank	2C32h		2
	Integrated Memory Controller Channel 2 Thermal Control	2C33h		3

Notes:

- Applies only to processors with two Intel QPI links.
 Applies only to processors supporting mirroring and scrubbing RAS features.



2.4 Detailed Configuration Space Maps

Table 2-2. Device 0, Function 0: Generic Non-core Registers

DID	DID	VID	1 001	DECIDED CODEC	7 001
CCR	DID	VID	00h	DESIRED_CORES	80h
HDR			_		
10h		RID		MEMLOCK_STATUS	
14h 18h 18h 16h 20h 24h 28h SID SVID 26h 30h 34h 38h 36h 36h 36h 37h 38h 38h 38h 38h 38h 38h 38h 38h 38h 38	HDR				
18h 1Ch 20h 24h 28h 28h 28h 26h 30h 24h 38h 38h 38h 38h 38h 38h 36h 26h 26h				MC_CFG_CONTROL	
1Ch 20h A0h A4h A4h A8h A8h					
20h 24h 28h A8h B8h B8h A8h A8h					
24h					
SID					
SID					
30h					
34h 38h 36h 36h	SID	SVID			
38h 3Ch B8h B8h B8h B8h B8h B6h BCh BCh				POWER_CNTRL_ERR_STATUS	B0h
3Ch			34h		B4h
MAXREQUEST_LC 40h CURRENT_UCLK_RATIO C0h MAXREQUEST_LS 44h C4h C4h MAXREQUEST_LL 48h C8h CCh 50h MIRROR_PORT_CTL D0h 54h D4h D8h 5Ch DCh DCh 60h MIP_PH_CTR_LO E0h 64h MIP_PH_PRT_LO E4h 68h 6Ch ECh 70h MIP_PH_CTR_L1 F0h 74h MIP_PH_PRT_L1 F4h 78h F8h					B8h
MAXREQUEST_LL 44h C4h MAXREQUEST_LL 48h C8h 4Ch CCh 50h MIRROR_PORT_CTL D0h 54h D4h 58h D8h 5Ch DCh 60h MIP_PH_CTR_LO E0h 64h MIP_PH_PRT_LO E4h 68h E8h 6Ch ECh 70h MIP_PH_CTR_L1 F0h 74h MIP_PH_PRT_L1 F4h 78h F8h			3Ch		BCh
MAXREQUEST_LL 48h C8h 4Ch 50h MIRROR_PORT_CTL D0h 54h D4h 58h D8h 5Ch DCh MAX_RTIDS 60h MIP_PH_CTR_L0 E0h 64h MIP_PH_PRT_L0 E4h 68h E8h E6h 6Ch MIP_PH_CTR_L1 F0h 74h MIP_PH_PRT_L1 F4h 78h MIP_PH_PRT_L1 F4h			1	CURRENT_UCLK_RATIO	
4Ch 50h MIRROR_PORT_CTL Doh 54h 58h D8h D2h D5h D5h					
50h MIRROR_PORT_CTL D0h 54h D4h 58h D8h 50h MIP_PH_CTR_L0 60h MIP_PH_PRT_L0 E4h 68h 66h 66h E8h 60h MIP_PH_CTR_L1 68h 60h 70h MIP_PH_CTR_L1 78h F8h 78h F8h 78h F8h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h 78h	MAXREC	NUEST_LL			
54h 58h D8h D8h D6h D6h					
58h D8h 5Ch DCh MAX_RTIDS 60h MIP_PH_CTR_L0 E0h 64h MIP_PH_PRT_L0 E4h 68h E8h ECh 70h MIP_PH_CTR_L1 F0h 74h MIP_PH_PRT_L1 F4h 78h F8h				MIRROR_PORT_CTL	
5Ch					
MAX_RTIDS 60h MIP_PH_CTR_L0 E0h 64h MIP_PH_PRT_L0 E4h 68h E8h 6Ch ECh 70h MIP_PH_CTR_L1 F0h 74h MIP_PH_PRT_L1 F4h 78h F8h					
64h MIP_PH_PRT_LO E4h 68h E8h 6Ch ECh 70h MIP_PH_CTR_L1 F0h 74h MIP_PH_PRT_L1 F4h 78h F8h					
68h 6Ch 70h MIP_PH_CTR_L1 F0h 74h MIP_PH_PRT_L1 F4h 78h	MAX_	RTIDS			
6Ch ECh 70h MIP_PH_CTR_L1 F0h 74h MIP_PH_PRT_L1 F4h 78h F8h				MIP_PH_PRT_L0	
70h MIP_PH_CTR_L1 F0h 74h MIP_PH_PRT_L1 F4h 78h F8h					
74h MIP_PH_PRT_L1 F4h 78h F8h					
78h F8h					
				MIP_PH_PRT_L1	
7Ch FCh					
			7Ch		FCh



Table 2-3. Device 0, Function 1: System Address Decoder Registers

DID	VID	00h	SAD_DRAM_RULE_0	80h
PCISTS	PCICMD	04h	SAD_DRAM_RULE_1	84h
CCR	RID	08h	SAD_DRAM_RULE_2	88h
HDR		0Ch	SAD_DRAM_RULE_3	8Ch
		10h	SAD_DRAM_RULE_4	90h
		14h	SAD_DRAM_RULE_5	94h
		18h	SAD_DRAM_RULE_6	98h
		1Ch	SAD_DRAM_RULE_7	9Ch
		20h		A0h
		24h		A4h
		28h		A8h
SID	SVID	2Ch		ACh
		30h		B0h
		34h		B4h
		38h		B8h
		3Ch		BCh
SAD_PA	M0123	40h	SAD_INTERLEAVE_LIST_0	C0h
SAD_PA	AM456	44h	SAD_INTERLEAVE_LIST_1	C4h
SAD_	HEN	48h	SAD_INTERLEAVE_LIST_2	C8h
SAD_SI	MRAM	4Ch	SAD_INTERLEAVE_LIST_3	CCh
SAD_PC	IEXBAR	50h	SAD_INTERLEAVE_LIST_4	D0h
		54h	SAD_INTERLEAVE_LIST_5	D4h
		58h	SAD_INTERLEAVE_LIST_6	D8h
		5Ch	SAD_INTERLEAVE_LIST_7	DCh
		60h		E0h
		64h		E4h
		68h		E8h
		6Ch		ECh
		70h		F0h
		74h		F4h
		78h		F8h
		7Ch		FCh



Table 2-4. Device 2, Function 0: Intel QPI Link 0 Registers

DID	VID)	00h		80h
PCISTS	PCICN	ИD	04h		84h
CCR	•	RID	08h		88h
HDR			0Ch		8Ch
	7		10h		90h
			14h		94h
			18h		98h
			1Ch		9Ch
			20h		A0h
			24h		A4h
			28h		A8h
SID	SVII	D	2Ch		ACh
			30h		B0h
			34h		B4h
			38h		B8h
			3Ch		BCh
QPI_QP	ILCP_LO		40h	QPI_RMT_QPILPO_STAT_L0	C0h
			44h	QPI_RMT_QPILP1_STAT_L0	C4h
QPI_QP	ILCL_LO		48h	QPI_RMT_QPILP2_STAT_L0	C8h
			4Ch	QPI_RMT_QPILP3_STAT_L0	CCh
QPI_QF	PILS_L0		50h		D0h
			54h		D4h
QPI_DEF_RMT_'	VN_CREDITS_L0		58h		D8h
			5Ch		DCh
			60h		E0h
			64h		E4h
			68h		E8h
			6Ch		ECh
			70h		F0h
			74h		F4h
			78h		F8h
			7Ch		FCh



Table 2-5. Device 2, Function 1: Intel QPI Physical 0 Registers

PCISTS PCICMD 04h CCR RID 08h OCh 10h 14h OPI_O_PH_PTV 18h 1Ch 20h 24h QPI_O_PH_LDC 20h 30h 34h 38h 3Ch 40h 44h 48h 4Ch OPI_O_PLL_STATUS OPI_O_PLL_RATIO 54h 58h 5Ch OPI_O_PH_CPR OPI_O_PH_CPR OPI_O_PH_CRR	DID	VID	00h	QPI_0_PH_PIS	80h
HDR	PCISTS	PCICMD	04h		84h
10h	CCR	RID	08h		88h
14h	HDR		0Ch		8Ch
18h 1Ch QPI_O_PH_LDC 20h 24h QPI_O_PH_PRT 28h 28h 30h 34h 38h 3Ch 40h 44h 48h 4Ch QPI_O_PLL_STATUS 50h QPI_O_PLL_RATIO 54h 56h 5Ch 60h QPI_O_PH_CPR 68h QPI_O_PH_CPR 68h QPI_O_PH_CTR 66h			10h		90h
1Ch			14h	QPI_0_PH_PTV	94h
20h 24h 28h 28h 30h 34h 38h 33ch 40h 44h 48h 4Ch QPI_O_PLL_STATUS OPI_O_PLL_RATIO SBh 5Ch 60h QPI_O_PH_CPR GPI_O_PH_CPR GPI_O_PH_CTR 68h QPI_O_PH_CTR 68h QPI_O_PH_CTR 68h QPI_O_PH_CTR			18h		98h
SID SVID 2Ch 30h 34h 38h 3Ch 40h 44h 48h 4Ch 50h QPI_O_PH_PMRO 54h 58h 5Ch 60h 64h QPI_O_PH_CPR 68h QPI_O_PH_CPR 68h QPI_O_PH_CTR 6Ch Constant of the property of the proper			1Ch	QPI_0_PH_LDC	9Ch
SID SVID 2Ch 30h 34h 38h 38h 36h 40h 44h 48h 4Ch 46h 46h			20h		A0h
SID SVID 2Ch 30h 34h 38h 3Ch 40h 44h 48h 4Ch 58h 5Ch 60h 60h QPI_O_PH_CPR 68h QPI_O_PH_CTR 6Ch Ch Ch Ch Ch Ch Ch C			24h	QPI_0_PH_PRT	A4h
30h 34h 38h 38h 3Ch 40h 44h 48h 4Ch OPI_O_PLL_STATUS 50h OPI_O_PLL_RATIO 54h 58h 5Ch 60h 64h OPI_O_PH_CPR OPI_O_PH_CPR OPI_O_PH_CTR 68h OPI_O_PH_CTR					A8h
34h 38h 3Ch 40h 44h 48h 4Ch 50h QPI_O_PH_PMRO	SID	SVID			ACh
38h 3Ch 40h 44h 48h 4Ch					B0h
3Ch 40h 44h 48h 4Ch					B4h
40h 44h 48h 4Ch					B8h
44h 48h 4Ch QPI_O_PLL_STATUS 50h QPI_O_PH_PMR0 54h 58h 5Ch 60h QPI_O_EP_SR 44h 48h 4Ch OPI_O_PH_CPR 68h QPI_O_PH_CTR 6Ch					BCh
48h 4Ch QPI_O_PLL_STATUS 50h QPI_O_PH_PMR0 54h 58h 5Ch 60h QPI_O_EP_SR QPI_O_PH_CPR 68h QPI_O_PH_CTR 68h 6Ch					COh
4Ch					C4h C8h
QPI_O_PLL_STATUS 50h QPI_O_PH_PMR0 QPI_O_PLL_RATIO 54h 58h 5Ch 60h QPI_O_EP_SR 64h 68h QPI_O_PH_CPR 68h QPI_O_PH_CTR 6Ch					CCh
QPI_O_PLL_RATIO 54h 58h 5Ch 60h QPI_O_EP_SR 64h 68h QPI_O_PH_CPR 68h QPI_O_PH_CTR 6Ch	OPL O PL	I STATUS		OPL O PH PMRO	DOh
58h 5Ch 60h QPI_O_EP_SR 64h 68h GPI_O_PH_CTR 66h 6Ch 6Ch 6Ch 65h 6Ch 65h 6Ch 65h 6Ch 65h 6Ch 65h				Q11_0_111_1 WIKO	D4h
5Ch 60h QPI_O_EP_SR	Q11_0_11	LL_IKATIO			D8h
60h QPI_0_EP_SR					DCh
QPI_O_PH_CPR 68h 6Ch 6Ch				QPI O EP SR	E0h
QPI_O_PH_CTR 6Ch					E4h
	QPI_0_	PH_CPR	68h		E8h
70h	QPI_O_	PH_CTR	6Ch		ECh
			70h		F0h
74h QPI_O_EP_MCTR			74h	QPI_0_EP_MCTR	F4h
78h			78h		F8h
7Ch			7Ch		FCh



Table 2-6. Device 2, Function 4: Intel QPI Link 1 Registers¹

D	ID	VI	D	00h		80h
PCI	STS	PCIO	CMD	04h		84h
	CCR	l .	RID	08h		88h
BIST	HDR			0Ch		8Ch
		ı		10h		90h
				14h		94h
				18h		98h
				1Ch		9Ch
				20h		A0h
				24h		A4h
				28h		A8h
S	ID	SV	'ID	2Ch		ACh
				30h		B0h
				34h		B4h
				38h		B8h
				3Ch		BCh
	QPI_QP	ILCP_L1		40h	QPI_RMT_QPILPO_STAT_L1	C0h
				44h	QPI_RMT_QPILP1_STAT_L1	C4h
	QPI_QP	ILCL_L1		48h	QPI_RMT_QPILP2_STAT_L1	C8h
				4Ch	QPI_RMT_QPILP3_STAT_L1	CCh
	QPI_QF	PILS_L1		50h		D0h
	DI DEE DMT I	WI CDEDITO I	1	54h		D4h
	PI_DEF_RMT_	VN_CREDITS_L	-1	58h 5Ch		D8h DCh
				60h		E0h
				64h		E4h
				68h		E8h
				6Ch		ECh
				70h		FOh
				74h		F4h
				78h		F8h
				7Ch		FCh
				J		J

Note:1. Applies only to processors with two Intel QPI links.



Table 2-7. Device 2, Function 5: Intel QPI Physical 1 Registers

DID	VID	00h	QPI_1_PH_PIS	80h
PCISTS	PCICMD	04h		84h
CCR	RID	08h		88h
HDR		0Ch		8Ch
		10h		90h
		14h	QPI_1_PH_PTV	94h
		18h		98h
		1Ch	QPI_1_PH_LDC	9Ch
		20h		A0h
		24h	QPI_1_PH_PRT	A4h
		28h		A8h
SID	SVID	2Ch		ACh
		30h		B0h
		34h		B4h
		38h		B8h
		3Ch		BCh
		40h		COh
		44h		C4h
		48h		C8h
		4Ch		CCh
	L_STATUS	50h	QPI_1_PH_PMR0	D0h
QPI_1_P	LL_RATIO	54h		D4h
		58h		D8h
		5Ch	001.4.50.00	DCh
		60h	QPI_1_EP_SR	E0h
ODL 1	DIL CDD	64h 68h		E4h E8h
	PH_CPR PH_CTR	6Ch		ECh
QPI_I_	_FII_CIK	70h		FOh
		74h	QPI_1_EP_MCTR	F4h
		7411 78h	QII_I_LI_NICIN	F8h
		7011 7Ch		FCh
] , ((1)		



Table 2-8. Device 3, Function 0: Integrated Memory Controller Registers

DID	VI	D	00h	
PCISTS	PCIC	MD	04h	
CCR		RID	08h	
HDR			0Ch	
			10h	
			14h	
			18h	
			1Ch	
			20h	
			24h	
			28h	
SID	SV	ID	2Ch	
			30h	
			34h	
			38h	
			3Ch	
			40h	
			44h	
	ONTROL		48h	
	STATUS		4Ch	
	1_ERROR_STATU	S	50h	
MC_SI	MI_CNTRL		54h	
			58h	
	T_CONTROL		5Ch	
	NEL_MAPPER		60h	
MC_N	AX_DOD		64h	
			68h	
M2 22	ODDT INIT		6Ch	
	CRDT_INIT		70h	
	T_WR_THLD		74h	
	JBADDR_LO		78h	
MC_SCR	JBADDR_HI		7Ch	



 Table 2-9.
 Device 3, Function 1: Target Address Decoder Registers

DID	VID	00h	TAD_DRAM_RULE_0	80h
PCISTS	PCICMD	04h	TAD_DRAM_RULE_1	84h
CCR	RID	08h	TAD_DRAM_RULE_2	88h
HDR		0Ch	TAD_DRAM_RULE_3	8Ch
		10h	TAD_DRAM_RULE_4	90h
		14h	TAD_DRAM_RULE_5	94h
		18h	TAD_DRAM_RULE_6	98h
		1Ch	TAD_DRAM_RULE_7	9Ch
		20h		A0h
		24h		A4h
		28h		A8h
SID	SVID	2Ch		ACh
		30h		B0h
		34h		B4h
		38h		B8h
		3Ch		BCh
		40h	TAD_INTERLEAVE_LIST_0	C0h
		44h	TAD_INTERLEAVE_LIST_1	C4h
		48h	TAD_INTERLEAVE_LIST_2	C8h
		4Ch	TAD_INTERLEAVE_LIST_3	CCh
		50h	TAD_INTERLEAVE_LIST_4	D0h
		54h	TAD_INTERLEAVE_LIST_5	D4h
		58h	TAD_INTERLEAVE_LIST_6	D8h
		5Ch	TAD_INTERLEAVE_LIST_7	DCh
		60h		EOh
		64h		E4h
		68h		E8h
		6Ch		ECh
		70h		F0h
		74h		F4h
		78h		F8h
		7Ch		FCh



Table 2-10. Device 3, Function 2: Integrated Memory Controller RAS Registers¹

DID	VID	00h	MC_COR_ECC_CNT_0	80h
PCISTS	PCICMD	04h	MC_COR_ECC_CNT_1	84h
CCR	RID	08h	MC_COR_ECC_CNT_2	88h
HDR		0Ch	MC_COR_ECC_CNT_3	8Ch
	_	10h	MC_COR_ECC_CNT_4	90h
		14h	MC_COR_ECC_CNT_5	94h
		18h		98h
		1Ch		9Ch
		20h		A0h
		24h		A4h
		28h		A8h
SID	SVID	2Ch		ACh
		30h		B0h
		34h		B4h
		38h		B8h
		3Ch		BCh
		40h		COh
		44h		C4h
	CONTROL	48h		C8h
	3_CONTROL	4Ch		CCh
	ENABLES	50h		D0h
MC_RAS	S_STATUS	54h		D4h
		58h		D8h
140,000	DOTATILO	5Ch		DCh
MC_SSF	RSTATUS	60h		E0h E4h
		64h		
		68h		E8h
		6Ch 70h		ECh F0h
		70n 74h		F4h
		74f1 78h		F8h
		7011 7Ch		FCh
		J /CII		FUII

Notes:

1. Applies only to processors supporting registered DIMMs.



Table 2-11. Device 3, Function 4: Integrated Memory Controller Test Registers

DID	VID	00h	MC_TEST_PH_PIS	80h
PCISTS	PCICMD	04h		84h
CCR	RID	08h		88h
HDR		0Ch		8Ch
		10h		90h
		14h		94h
		18h		98h
		1Ch		9Ch
		20h		A0h
		24h		A4h
		28h	MC_TEST_PAT_GCTR	A8h
SID	SVID	2Ch		ACh
		30h	MC_TEST_PAT_BA	B0h
		34h		B4h
		38h		B8h
		3Ch	MC_TEST_PAT_IS	BCh
		40h	MC_TEST_PAT_DCD	C0h
		44h		C4h
		48h		C8h
		4Ch		CCh
MC_DIMM_CLK_	_RATIO_STATUS	50h		D0h
MC_DIMM_	CLK_RATIO	54h		D4h
		58h		D8h
		5Ch		DCh
MC_TEST_	ERR_RCV1	60h		E0h
MC_TEST_	ERR_RCV0	64h		E4h
		68h		E8h
MC_TEST	_PH_CTR	6Ch		ECh
		70h		F0h
		74h		F4h
		78h		F8h
		7Ch		FCh



Table 2-12. Device 4, Function 0: Integrated Memory Controller Channel 0 Control Registers

DID	VID	00h	MC_CHANNEL_O_RANK_TIMING_A	8
PCISTS	PCICMD	04h	MC_CHANNEL_O_RANK_TIMING_B	8
CCR	RID	08h	MC_CHANNEL_O_BANK_TIMING	8
HDR		0Ch	MC_CHANNEL_O_REFRESH_TIMING	8
	•	10h	MC_CHANNEL_O_CKE_TIMING	9
		14h	MC_CHANNEL_0_ZQ_TIMING	9
		18h	MC_CHANNEL_O_RCOMP_PARAMS	9
		1Ch	MC_CHANNEL_0_ODT_PARAMS1	9
		20h	MC_CHANNEL_0_ODT_PARAMS2	Α
		24h	MC_CHANNEL_O_ODT_MATRIX_RANK_O_3_RD	Α
		28h	MC_CHANNEL_O_ODT_MATRIX_RANK_4_7_RD	Α
SID	SVID	2Ch	MC_CHANNEL_0_ODT_MATRIX_RANK_0_3_WR	Α
		30h	MC_CHANNEL_0_ODT_MATRIX_RANK_4_7_WR	В
		34h	MC_CHANNEL_0_WAQ_PARAMS	В
		38h	MC_CHANNEL_O_SCHEDULER_PARAMS	В
		3Ch	MC_CHANNEL_O_MAINTENANCE_OPS	В
		40h	MC_CHANNEL_O_TX_BG_SETTINGS	C
		44h		С
		48h	MC_CHANNEL_O_RX_BGF_SETTINGS	C
		4Ch	MC_CHANNEL_O_EW_BGF_SETTINGS	С
MC_CHANNEL_O_DIMM_RESET_CMD		50h	MC_CHANNEL_O_EW_BGF_OFFSET_SETTINGS	D
MC_CHANNEL_0	_DIMM_INIT_CMD	54h	MC_CHANNEL_O_ROUND_TRIP_LATENCY	С
MC_CHANNEL_O_DIMM_INIT_PARAMS		58h	MC_CHANNEL_O_PAGETABLE_PARAMS1	С
MC_CHANNEL_O_E	DIMM_INIT_STATUS	5Ch		
MC_CHANNEL	_O_DDR3CMD	60h	MC_TX_BG_CMD_DATA_RATIO_SETTING_CH0	E
		64h	MC_TX_BG_CMD_OFFSET_SETTINGS_CH0	Е
MC_CHANNEL_O_REFRESH_THROTTLE_SUPPORT		68h	MC_TX_BG_DATA_OFFSET_SETTINGS_CH0	Е
		6Ch		E
MC_CHANNEL_O	_MRS_VALUE_0_1	70h	MC_CHANNEL_O_ADDR_MATCH	F
MC_CHANNEL_0_MRS_VALUE_2		74h		F
		78h	MC_CHANNEL_0_ECC_ERROR_MASK	F
MC_CHANNEL_0	_RANK_PRESENT	7Ch	MC_CHANNEL_O_ECC_ERROR_INJECT	F



Table 2-13. Device 4, Function 1: Integrated Memory Controller Channel 0 Address Registers

DID	VID	00h	MC_SAG_CH0_0	80h
PCISTS PCICMD		04h	MC_SAG_CH0_1	84h
CCR	RID	08h	MC_SAG_CH0_2	88h
HDR		0Ch	MC_SAG_CHO_3	8Ch
		10h	MC_SAG_CHO_4	90h
		14h	MC_SAG_CHO_5	94h
		18h	MC_SAG_CHO_6	98h
		1Ch	MC_SAG_CHO_7	9Ch
		20h		A0h
		24h		A4h
		28h		A8h
SID	SVID	2Ch		ACh
		30h		B0h
		34h		B4h
		38h		B8h
		3Ch		BCh
		40h		COh
		44h		C4h
	D_CH0_0	48h		C8h
MC_DOD_CH0_1		4Ch 50h		CCh
MC_DC	MC_DOD_CH0_2			D0h
		54h		D4h
		58h		D8h
		5Ch		DCh
		60h		E0h
		64h		E4h
		68h		E8h
		6Ch		ECh
		70h		F0h
		74h		F4h
		78h		F8h
		7Ch		FCh



Table 2-14. Device 4, Function 2: Integrated Memory Controller Channel 0 Rank Registers

DID	VID	00h	MC_RIR_WAY_CHO_0	80h
PCISTS	PCICMD	04h	MC_RIR_WAY_CHO_1	84h
CCR	RID	08h	MC_RIR_WAY_CHO_2	88h
HDR		0Ch	MC_RIR_WAY_CHO_3	8Ch
	•	10h	MC_RIR_WAY_CHO_4	90h
		14h	MC_RIR_WAY_CH0_5	94h
		18h	MC_RIR_WAY_CHO_6	98h
		1Ch	MC_RIR_WAY_CHO_7	9Ch
		20h	MC_RIR_WAY_CHO_8	A0h
		24h	MC_RIR_WAY_CHO_9	A4h
		28h	MC_RIR_WAY_CH0_10	A8h
SID	SVID	2Ch	MC_RIR_WAY_CH0_11	ACh
		30h	MC_RIR_WAY_CH0_12	B0h
		34h	MC_RIR_WAY_CH0_13	B4h
		38h	MC_RIR_WAY_CH0_14	B8h
		3Ch	MC_RIR_WAY_CH0_15	BCh
MC_RIR_LIMIT_CH0_0		40h	MC_RIR_WAY_CH0_16	C0h
MC_RIR_LIMIT_CHO_1		44h	MC_RIR_WAY_CHO_17	C4h
MC_RIR_LIMIT_CH0_2		48h	MC_RIR_WAY_CH0_18	C8h
MC_RIR_LIMIT_CH0_3		4Ch	MC_RIR_WAY_CH0_19	CCh
MC_RIR_LIMIT_CH0_4		50h	MC_RIR_WAY_CH0_20	D0h
MC_RIR_LIMIT_CH0_5		54h	MC_RIR_WAY_CH0_21	D4h
MC_RIR_LIMIT_CH0_6		58h	MC_RIR_WAY_CH0_22	D8h
MC_RIR_LI	MIT_CH0_7	5Ch	MC_RIR_WAY_CH0_23	DCh
		60h	MC_RIR_WAY_CH0_24	E0h
		64h	MC_RIR_WAY_CH0_25	E4h
		68h	MC_RIR_WAY_CH0_26	E8h
		6Ch	MC_RIR_WAY_CH0_27	ECh
		70h	MC_RIR_WAY_CHO_28	F0h
		74h	MC_RIR_WAY_CH0_29	F4h
		78h	MC_RIR_WAY_CH0_30	F8h
		7Ch	MC_RIR_WAY_CH0_31	FCh



Table 2-15. Device 4, Function 3: Integrated Memory Controller Channel 0
Thermal Control Registers

DID	VID		00h	MC_COOLING_COEF0	80h
PCISTS	PCICMD		04h	MC_CLOSED_LOOP0	84h
CCR		RID	08h	MC_THROTTLE_OFFSET0	88h
HDR	1		0Ch		8Ch
			10h		90h
			14h		94h
			18h	MC_RANK_VIRTUAL_TEMPO	98h
			1Ch	MC_DDR_THERM_COMMAND0	9Ch
			20h		A0h
			24h	MC_DDR_THERM_STATUS0	A4h
			28h		A8h
SID	SVI	D	2Ch		ACh
			30h		B0h
			34h		B4h
			38h		B8h
			3Ch		BCh
			40h		C0h
			44h		C4h
MC_THERMAL_CONTROL0		48h		C8h	
MC_THERMAL_STATUS0		4Ch		CCh	
MC_THERMAL_	_DEFEATURE0		50h		D0h
			54h		D4h
			58h		D8h
			5Ch		DCh
MC_THERMAL_PARAMS_A0		60h		E0h	
MC_THERMAL_PARAMS_B0		64h		E4h	
			68h		E8h
			6Ch		ECh
			70h		F0h
			74h		F4h
			78h		F8h
			7Ch		FCh



Table 2-16. Device 5, Function 0: Integrated Memory Controller Channel 1 Control Registers

DID	VID	00h	MC_CHANNEL_1_RANK_TIMING_A	8
PCISTS	PCICMD	04h	MC_CHANNEL_1_RANK_TIMING_B	8
CCR	RID	08h	MC_CHANNEL_1_BANK_TIMING	8
HDR		0Ch	MC_CHANNEL_1_REFRESH_TIMING	8
		10h	MC_CHANNEL_1_CKE_TIMING	ç
		14h	MC_CHANNEL_1_ZQ_TIMING	9
		18h	MC_CHANNEL_1_RCOMP_PARAMS	9
		1Ch	MC_CHANNEL_1_ODT_PARAMS1	ç
		20h	MC_CHANNEL_1_ODT_PARAMS2	1
		24h	MC_CHANNEL_1_ODT_MATRIX_RANK_0_3_RD	1
		28h	MC_CHANNEL_1_ODT_MATRIX_RANK_4_7_RD	P
SID	SVID	2Ch	MC_CHANNEL_1_ODT_MATRIX_RANK_0_3_WR	1
		30h	MC_CHANNEL_1_ODT_MATRIX_RANK_4_7_WR	E
		34h	MC_CHANNEL_1_WAQ_PARAMS	1
		38h	MC_CHANNEL_1_SCHEDULER_PARAMS	
		3Ch	MC_CHANNEL_1_MAINTENANCE_OPS	
		40h	MC_CHANNEL_1_TX_BG_SETTINGS	
		44h		
		48h	MC_CHANNEL_1_RX_BGF_SETTINGS	
		4Ch	MC_CHANNEL_1_EW_BGF_SETTINGS	
MC_CHANNEL_1_D	IMM_RESET_CMD	50h	MC_CHANNEL_1_EW_BGF_OFFSET_SETTINGS	
MC_CHANNEL_1_E	DIMM_INIT_CMD	54h	MC_CHANNEL_1_ROUND_TRIP_LATENCY	
MC_CHANNEL_1_DI	MM_INIT_PARAMS	58h	MC_CHANNEL_1_PAGETABLE_PARAMS1	
MC_CHANNEL_1_DI	MM_INIT_STATUS	5Ch		
MC_CHANNEL_	1_DDR3CMD	60h	MC_TX_BG_CMD_DATA_RATIO_SETTING_CH1	
		64h	MC_TX_BG_CMD_OFFSET_SETTINGS_CH1	
MC_CHANNEL_1_REFRES	H_THROTTLE_SUPPORT	68h	MC_TX_BG_DATA_OFFSET_SETTINGS_CH1	
		6Ch		
MC_CHANNEL_1_N	MRS_VALUE_0_1	70h	MC_CHANNEL_1_ADDR_MATCH	
MC_CHANNEL_1_	MRS_VALUE_2	74h		
		78h	MC_CHANNEL_1_ECC_ERROR_MASK	
MC_CHANNEL_1_	RANK_PRESENT	7Ch	MC_CHANNEL_1_ECC_ERROR_INJECT	



Table 2-17. Device 5, Function 1: Integrated Memory Controller Channel 1
Address Registers

DID	VID	00h	MC_SAG_CH1_0	80h
PCISTS	PCICMD	04h	MC_SAG_CH1_1	84h
CCR	RID	08h	MC_SAG_CH1_2	88h
HDR	<u>.</u>	0Ch	MC_SAG_CH1_3	8Ch
		10h	MC_SAG_CH1_4	90h
		14h	MC_SAG_CH1_5	94h
		18h	MC_SAG_CH1_6	98h
		1Ch	MC_SAG_CH1_7	9Ch
		20h		A0h
		24h		A4h
		28h		A8h
SID	SVID	2Ch		ACh
		30h		B0h
		34h		B4h
		38h		B8h
		3Ch		BCh
		40h		COh
		44h		C4h
MC_DOD_	_CH1_0	48h		C8h
MC_DOD_	_CH1_1	4Ch		CCh
MC_DOD_	_CH1_2	50h		D0h
		54h		D4h
		58h		D8h
		5Ch		DCh
		60h		E0h
		64h		E4h
		68h		E8h
		6Ch		ECh
		70h		F0h
		74h		F4h
		78h		F8h
		7Ch		FCh



Table 2-18. Device 5, Function 2: Integrated Memory Controller Channel 1 Rank Registers

DID	VID	00h	MC_RIR_WAY_CH1_0	80h
PCISTS	PCISTS PCICMD		MC_RIR_WAY_CH1_1	84h
CCR	RID	08h	MC_RIR_WAY_CH1_2	88h
HDR	<u>.</u>	0Ch	MC_RIR_WAY_CH1_3	8Ch
		10h	MC_RIR_WAY_CH1_4	90h
		14h	MC_RIR_WAY_CH1_5	94h
		18h	MC_RIR_WAY_CH1_6	98h
		1Ch	MC_RIR_WAY_CH1_7	9Ch
		20h	MC_RIR_WAY_CH1_8	A0h
		24h	MC_RIR_WAY_CH1_9	A4h
		28h	MC_RIR_WAY_CH1_10	A8h
SID	SVID	2Ch	MC_RIR_WAY_CH1_11	ACh
		30h	MC_RIR_WAY_CH1_12	B0h
		34h	MC_RIR_WAY_CH1_13	B4h
		38h	MC_RIR_WAY_CH1_14	B8h
		3Ch	MC_RIR_WAY_CH1_15	BCh
MC_RIR_LIN	MIT_CH1_0	40h	MC_RIR_WAY_CH1_16	C0h
MC_RIR_LIN	MIT_CH1_1	44h	MC_RIR_WAY_CH1_17	C4h
MC_RIR_LIN	MIT_CH1_2	48h	MC_RIR_WAY_CH1_18	C8h
MC_RIR_LIN	MIT_CH1_3	4Ch	MC_RIR_WAY_CH1_19	CCh
MC_RIR_LIN	MIT_CH1_4	50h	MC_RIR_WAY_CH1_20	D0h
MC_RIR_LIN	MIT_CH1_5	54h	MC_RIR_WAY_CH1_21	D4h
MC_RIR_LIN	MIT_CH1_6	58h	MC_RIR_WAY_CH1_22	D8h
MC_RIR_LIN	MIT_CH1_7	5Ch	MC_RIR_WAY_CH1_23	DCh
		60h	MC_RIR_WAY_CH1_24	E0h
		64h	MC_RIR_WAY_CH1_25	E4h
		68h	MC_RIR_WAY_CH1_26	E8h
		6Ch	MC_RIR_WAY_CH1_27	ECh
		70h	MC_RIR_WAY_CH1_28	F0h
		74h	MC_RIR_WAY_CH1_29	F4h
		78h	MC_RIR_WAY_CH1_30	F8h
		7Ch	MC_RIR_WAY_CH1_31	FCh



Table 2-19. Device 5, Function 3: Integrated Memory Controller Channel 1
Thermal Control Registers

DID	VID	00h	MC_COOLING_COEF1	80h
PCISTS	PCICMD	04h	MC_CLOSED_LOOP1	84h
CCR	RID	08h	MC_THROTTLE_OFFSET1	88h
HDR		0Ch		8Ch
		10h		90h
		14h		94h
		18h	MC_RANK_VIRTUAL_TEMP1	98h
		1Ch	MC_DDR_THERM_COMMAND1	9Ch
		20h		A0h
		24h	MC_DDR_THERM_STATUS1	A4h
		28h		A8h
SID	SVID	2Ch		ACh
		30h		B0h
		34h		B4h
		38h		B8h
		3Ch		BCh
		40h		C0h
		44h		C4h
MC_THERMAL_	CONTROL1	48h		C8h
MC_THERMAL	_STATUS1	4Ch		CCh
MC_THERMAL_D	DEFEATURE1	50h		D0h
		54h		D4h
		58h		D8h
		5Ch		DCh
MC_THERMAL_F	PARAMS_A1	60h		E0h
MC_THERMAL_F	PARAMS_B1	64h		E4h
		68h		E8h
		6Ch		ECh
		70h		F0h
		74h		F4h
		78h		F8h
		7Ch		FCh



Table 2-20. Device 6, Function 0: Integrated Memory Controller Channel 2 Control Registers

DID	VID	00h	MC_CHANNEL_2_RANK_TIMING_A	8
PCISTS	PCICMD	04h	MC_CHANNEL_2_RANK_TIMING_B	8
CCR	RID	08h	MC_CHANNEL_2_BANK_TIMING	8
HDR		0Ch	MC_CHANNEL_2_REFRESH_TIMING	8
		10h	MC_CHANNEL_2_CKE_TIMING	9
		14h	MC_CHANNEL_2_ZQ_TIMING	9
		18h	MC_CHANNEL_2_RCOMP_PARAMS	9
		1Ch	MC_CHANNEL_2_ODT_PARAMS1	9
		20h	MC_CHANNEL_2_ODT_PARAMS2	Α
		24h	MC_CHANNEL_2_ODT_MATRIX_RANK_0_3_RD	Α
		28h	MC_CHANNEL_2_ODT_MATRIX_RANK_4_7_RD	Α
SID	SVID	2Ch	MC_CHANNEL_2_ODT_MATRIX_RANK_0_3_WR	Α
		30h	MC_CHANNEL_2_ODT_MATRIX_RANK_4_7_WR	E
		34h	MC_CHANNEL_2_WAQ_PARAMS	E
		38h	MC_CHANNEL_2_SCHEDULER_PARAMS	-
		3Ch	MC_CHANNEL_2_MAINTENANCE_OPS	ı
		40h	MC_CHANNEL_2_TX_BG_SETTINGS	-
		44h		(
		48h	MC_CHANNEL_2_RX_BGF_SETTINGS	-
		4Ch	MC_CHANNEL_2_EW_BGF_SETTINGS	(
MC_CHANNEL_2_[DIMM_RESET_CMD	50h	MC_CHANNEL_2_EW_BGF_OFFSET_SETTINGS	[
MC_CHANNEL_2_	DIMM_INIT_CMD	54h	MC_CHANNEL_2_ROUND_TRIP_LATENCY	[
MC_CHANNEL_2_D	IMM_INIT_PARAMS	58h	MC_CHANNEL_2_PAGETABLE_PARAMS1	1
MC_CHANNEL_2_D	IMM_INIT_STATUS	5Ch		[
MC_CHANNEL	_2_DDR3CMD	60h	MC_TX_BG_CMD_DATA_RATIO_SETTING_CH2	1
		64h	MC_TX_BG_CMD_OFFSET_SETTINGS_CH2	
MC_CHANNEL_2_REFRE	SH_THROTTLE_SUPPORT	68h	MC_TX_BG_DATA_OFFSET_SETTINGS_CH2	
		6Ch		
MC_CHANNEL_2_	MRS_VALUE_0_1	70h	MC_CHANNEL_2_ADDR_MATCH	
MC_CHANNEL_2	_MRS_VALUE_2	74h		
		78h	MC_CHANNEL_2_ECC_ERROR_MASK	
MC_CHANNEL 2	_RANK_PRESENT	7Ch	MC_CHANNEL_2_ECC_ERROR_INJECT	



Table 2-21. Device 6, Function 1: Integrated Memory Controller Channel 2 Address Registers

DID	VID	00h	MC_SAG_CH2_0	80h
PCISTS	PCICMD	04h	MC_SAG_CH2_1	84h
CCR	RID	08h	MC_SAG_CH2_2	88h
HDR		0Ch	MC_SAG_CH2_3	8Ch
		10h	MC_SAG_CH2_4	90h
		14h	MC_SAG_CH2_5	94h
		18h	MC_SAG_CH2_6	98h
		1Ch	MC_SAG_CH2_7	9Ch
		20h		A0h
		24h		A4h
		28h		A8h
SID	SVID	2Ch		ACh
		30h		B0h
		34h		B4h
		38h		B8h
		3Ch		BCh
		40h		C0h
		44h		C4h
MC_DOD_	CH2_0	48h		C8h
MC_DOD_	CH2_1	4Ch		CCh
MC_DOD_	CH2_2	50h		D0h
		54h		D4h
		58h		D8h
		5Ch		DCh
		60h		E0h
		64h		E4h
		68h		E8h
		6Ch		ECh
		70h		F0h
		74h		F4h
		78h		F8h
		7Ch		FCh



Table 2-22. Device 6, Function 2: Integrated Memory Controller Channel 2 Rank Registers

DID	VID	00h	MC_RIR_WAY_CH2_0	80h
PCISTS	PCICMD	04h	MC_RIR_WAY_CH2_1	84h
CCR		RID 08h	MC_RIR_WAY_CH2_2	88h
HDR		OCF	MC_RIR_WAY_CH2_3	8Ch
	4	10h	MC_RIR_WAY_CH2_4	90h
		141	MC_RIR_WAY_CH2_5	94h
		18h	MC_RIR_WAY_CH2_6	98h
		1Ch	MC_RIR_WAY_CH2_7	9Ch
		20h	MC_RIR_WAY_CH2_8	A0h
		24h	MC_RIR_WAY_CH2_9	A4h
		28h	MC_RIR_WAY_CH2_10	A8h
SID	SVID	2Ch	MC_RIR_WAY_CH2_11	ACh
		30h	MC_RIR_WAY_CH2_12	B0h
		34h	MC_RIR_WAY_CH2_13	B4h
		38h	MC_RIR_WAY_CH2_14	B8h
		3Ch	MC_RIR_WAY_CH2_15	BCh
MC_RIR_LI	MIT_CH2_0	40h	MC_RIR_WAY_CH2_16	C0h
MC_RIR_LI	MIT_CH2_1	44h	MC_RIR_WAY_CH2_17	C4h
MC_RIR_LI	MIT_CH2_2	48h	MC_RIR_WAY_CH2_18	C8h
MC_RIR_LI	MIT_CH2_3	4Ch	MC_RIR_WAY_CH2_19	CCh
MC_RIR_LI	MIT_CH2_4	50h	MC_RIR_WAY_CH2_20	D0h
MC_RIR_LI	MIT_CH2_5	54h	MC_RIR_WAY_CH2_21	D4h
MC_RIR_LI	MIT_CH2_6	58h	MC_RIR_WAY_CH2_22	D8h
MC_RIR_LI	MIT_CH2_7	5Ch		DCh
		60h		E0h
		64h	MC_RIR_WAY_CH2_25	E4h
		68h	MC_RIR_WAY_CH2_26	E8h
		6Ch		ECh
		70h		F0h
		74h	MC_RIR_WAY_CH2_29	F4h
		78h	MC_RIR_WAY_CH2_30	F8h
		7Ch	MC_RIR_WAY_CH2_31	FCh



Table 2-23. Device 6, Function 3: Integrated Memory Controller Channel 2
Thermal Control Registers

DID	VI	D	00h	MC_COOLING_COEF2	80h
PCISTS	PCIC	MD	04h	MC_CLOSED_LOOP2	84h
CCR		RID	08h	MC_THROTTLE_OFFSET2	88h
HDR			0Ch		8Ch
	_		10h		90h
			14h		94h
			18h	MC_RANK_VIRTUAL_TEMP2	98h
			1Ch	MC_DDR_THERM_COMMAND2	9Ch
			20h		A0h
			24h	MC_DDR_THERM_STATUS2	A4h
			28h		A8h
SID	SV	ID	2Ch		ACh
			30h		B0h
			34h		B4h
			38h		B8h
			3Ch		BCh
			40h		COh
			44h		C4h
MC_THERMA	L_CONTROL2		48h		C8h
MC_THERM	AL_STATUS2		4Ch		CCh
MC_THERMAL	DEFEATURE2		50h		D0h
			54h		D4h
			58h		D8h
			5Ch		DCh
	L_PARAMS_A2		60h		E0h
MC_THERMAI	L_PARAMS_B2		64h		E4h
			68h		E8h
			6Ch		ECh
			70h		F0h
			74h		F4h
			78h		F8h
			7Ch		FCh



2.5 PCI Standard Registers

These registers appear in every function for every device.

2.5.1 VID - Vendor Identification Register

The VID Register contains the vendor identification number. This 16-bit register, combined with the Device Identification Register uniquely identifies the manufacturer of the function within the processor. Writes to this register have no effect.

Device: Function Offset:	0 n: 0-1 00l		
Device: Function Offset:	2 n: 0-1 00l	, 4-5 า	
Device: Function Offset:	3 n: 0-2 00l		
Device: Function Offset:	4- <i>6</i> n: 0-3 00l		
Bit	Туре	Reset Value	Description
15:0	RO	8086h	Vendor I dentification Number The value assigned to Intel.

2.5.2 DID - Device Identification Register

This 16-bit register combined with the Vendor Identification register uniquely identifies the Function within the processor. Writes to this register have no effect. See Table 2-1 for the DID of each processor function.

Device: Function Offset:	0 i: 0-1 02h	1	
Device: Function Offset:	2 n: 0-1 02h	, 4-5	
Device: Function Offset: Device: Function Offset:	02h 4-6	i	
Bit	Туре	Reset Value	Description
15:0	RO	*See Table 2-1	Device I dentification Number Identifies each function of the processor.



2.5.3 RID - Revision Identification Register

This register contains the revision number of the processor. The Revision ID (RID) is a traditional 8-bit Read Only (RO) register located at offset 08h in the standard PCI header of every PCI/PCI Express compatible device and function.

Device: Function: 0-1 Offset: 08h Device: Function: 0-1, 4-5 Offset: 08h Device: 0-2, 4 Function: Offset: 08h Device: 4-6 Function: 0-3 Offset: 08h Reset Bit **Type** Description Value 7:0 RO 0h **Revision Identification Number** 0: A Stepping 1: A Stepping 2: B Stepping 4: C Stepping 5: D Stepping Others: RSVD

2.5.4 CCR - Class Code Register

This register contains the Class Code for the device. Writes to this register have no effect.

Device: **Function:** 0-1 09h Offset: Device: 0-1, 4-5 Function: Offset: 09h Device: Function: 0-2, 4 Offset: 09h Device: 4-6 **Function:** 0-3 Offset: 09h Reset Bit **Type** Description **Value** 23:16 RO 06h Base Class. This field indicates the general device category. For the processor, this field is hardwired to 06h, indicating it is a "Bridge Device". 15:8 RO 0 This field qualifies the Base Class, providing a more detailed specification of the device function. For all devices the default is 00h, indicating "Host Bridge". 7:0 RO Register-Level Programming Interface. 0 This field identifies a specific programming interface (if any), that device independent software can use to interact with the device. There are no such interfaces defined for "Host Bridge" types, and this field is hardwired to 00h.



2.5.5 HDR - Header Type Register

This register identifies the header layout of the configuration space.

Device: **Function:** 0-1 Offset: 0Eh Device: 0-1, 4-5 **Function:** 0Eh Offset: Device: 0-2, 4 **Function:** Offset: 0Eh Device: 4-6 **Function:** 0-3 Offset: **OEh** Reset Bit Туре Description Value RO Multi-function Device. Selects whether this is a multi-function device, that may have alternative configuration layouts. This bit is hardwired to '1' for devices in the processor. RO 0 Configuration Layout. This field identifies the format of the configuration header layout for a PCI-to-PCI bridge from bytes 10h through 3Fh. For all devices the default is 00h, indicating a conventional type 00h PCI header.

2.5.6 SID/SVID - Subsystem Identity/Subsystem Vendor Identification Register

This register identifies the manufacturer of the system. This 32-bit register uniquely identifies any PCI device.

Device: Function: 0-1 Offset: 2Ch, 2Eh Device: 0-1, 4-5 Function: Offset: 2Ch, 2Eh Device: 0-2, 4 **Function:** Offset: 2Ch, 2Eh 4-6 Device: Function: 0-3 2Ch, 2Eh Offset: Access as a Dword Reset Type Description Value 31:16 **RWO** 8086h Subsystem Identification Number: The default value specifies Intel 15:0 **RWO** 8086h Vendor Identification Number. The default value specifies Intel.



2.5.7 PCICMD - Command Register

This register defines the PCI 3.0 compatible command register values applicable to PCI Express space.

Device: 0
Function: 0-1
Offset: 04h

Device: 2
Function: 0-1, 4-5
Offset: 04h

Device: 3
Function: 0-2, 4
Offset: 04h

Device: 4-6
Function: 0-3
Offset: 04h

Bit	Туре	Reset Value	Description
15:11	RV	0	Reserved. (by PCI SIG)
10	RO	0	INTxDisable: Interrupt Disable Controls the ability of the PCI Express port to generate INTx messages. If this device does not generate interrupts then this bit is not implemented and is RO. If this device generates interrupts then this bit is RW and this bit disables the device/function from asserting INTx#. A value of 0 enables the assertion of its INTx# signal. A value of 1 disables the assertion of its INTx# signal. 1: Legacy Interrupt mode is disabled 0: Legacy Interrupt mode is enabled
9	RO	0	FB2B: Fast Back-to-Back Enable This bit controls whether or not the master can do fast back-to-back writes. Since this device is strictly a target this bit is not implemented. This bit is hardwired to 0. Writes to this bit position have no effect.
8	RO	0	SERRE: SERR Message Enable This bit is a global enable bit for this devices SERR messaging. This host bridge will not implement SERR messaging. This bit is hardwired to 0. Writes to this bit position have no effect.If SERR is used for error generation, then this bit must be RW and enable/disable SERR signaling.
7	RO	0	IDSELWCC: IDSEL Stepping/Wait Cycle Control Per PCI 2.3 spec this bit is hardwired to 0. Writes to this bit position have no effect.
6	RO	0	PERRE: Parity Error Response Enable Parity error is not implemented in this host bridge. This bit is hardwired to "0". Writes to this bit position have no effect.
5	RO	0	VGAPSE: VGA palette snoop Enable This host bridge does not implement this bit. This bit is hardwired to a "0". Writes to this bit position have no effect.
4	RO	0	MWIEN: Memory Write and Invalidate Enable This host bridge will never issue memory write and invalidate commands. This bit is therefore hardwired to "0". Writers to this bit position will have no effect.
3	RO	0	SCE: Special Cycle Enable This host bridge does not implement this bit. This bit is hardwired to a "0". Writers to this bit position will have no effect.
2	RO	1	BME: Bus Master Enable This host bridge is always enabled as a master. This bit is hardwired to a "1". Writes to this bit position have no effect.
1	RO	1	MSE: Memory Space Enable This host bridge always allows access to main memory. This bit is not implemented and is hardwired to "1". Writes to this bit position have no effect.
0	RO	0	IOAE: Access Enable This bit is not implemented in this host bridge and is hardwired to "0". Writes to this bit position have no effect.



2.5.8 PCISTS - PCI Status Register

The PCI Status register is a 16-bit status register that reports the occurrence of various error events on this device's PCI interface.

Device: 0
Function: 0-1
Offset: 06h

Device: 2
Function: 0-1, 4-5
Offset: 06h

Device: 3
Function: 0-2, 4
Offset: 06h

Device: 4-6 Function: 0-3 Offset: 06h

Offset:	06h		
Bit	Туре	Reset Value	Description
15	RO	0	Detect Parity Error (DPE) The host bridge does not implement this bit and is hardwired to a "O". Writes to this bit position have no effect.
14	RO	0	Signaled System Error (SSE) This bit is set to 1 when this device generates an SERR message over the bus for any enabled error condition. If the host bridge does not signal errors using this bit, this bit is hardwired to a "0" and is read-only. Writes to this bit position have no effect.
13	RO	0	Received Master Abort Status (RMAS) This bit is set when this device generates request that receives an Unsupported Request completion packet. Software clears the bit by writing 1 to it. If this device does not receive Unsupported Request completion packets, the bit is hardwired to "0" and is read-only. Writes to this bit position have no effect.
12	RO	0	Received Target Abort Status (RTAS) This bit is set when this device generates a request that receives a Completer Abort completion packet. Software clears this bit by writing a 1 to it. If this device does not receive Completer Abort completion packets, this bit is hardwired to "0" and read-only. Writes to this bit position have no effect.
11	RO	0	Signaled Target Abort Status (STAS) This device will not generate a Target Abort completion or Special Cycle. This bit is not implemented in this device and is hardwired to a "0". Writes to this bit position have no effect.
10:9	RO	0	DEVSEL Timing (DEVT) These bits are hardwired to "00". Writes to these bit positions have no effect. This device does not physically connect to PCI bus X. These bits are set to "00" (fast decode) so that optimum DEVSEL timing for PCI bus X is not limited by this device.
8	RO	0	Master Data Parity Error Detected (DPD) PERR signaling and messaging are not implemented by this bridge, therefore this bit is hardwired to "0". Writes to this bit position have no effect.
7	RO	1	Fast Back-to-Back (FB2B) This bit is hardwired to "1". Writes to this bit position have no effect. This device is not physically connected to a PCI bus. This bit is set to 1 (indicating back-to-back capabilities) so that the optimum setting for this PCI bus is not limited by this device.
6	RO	0	Reserved
5	RO	0	66 MHz Capable Does not apply to PCI Express. Must be hardwired to "0".



Device: Function: 0-1 Offset: 06h Device: 0-1, 4-5 Function: Offset: 06h Device: 3 0-2, 4 Function: Offset: 06h Device: 4-6 0-3 Function: Offset: 06h

Bit	Туре	Reset Value	Description
4	RO	TBD	Capability List (CLIST) This bit is hardwired to "1" to indicate to the configuration software that this device/function implements a list of new capabilities. A list of new capabilities is accessed via registers CAPPTR at the configuration address offset 34h from the start of the PCI configuration space header of this function. Register CAPPTR contains the offset pointing to the start address with configuration space of this device where the capability register resides. This bit must be set for a PCI Express device or if the VSEC capability. If no capability structures are implemented, this bit is hardwired to 0.
3	RO	0	Interrupt Status: If this device generates an interrupt, then this read-only bit reflects the state of the interrupt in the device/function. Only when the Interrupt Disable bit in the command register is a 0 and this Interrupt Status bit is a 1, will the device's/function's INTx# signal be asserted. Setting the Interrupt Disable bit to a 1 has no effect on the state of this bit. If this device does not generate interrupts, then this bit is not implemented (RO and reads returns 0).
2:0	RO	0	Reserved

2.6 Generic Non-core Registers

2.6.1 MAXREQUEST_LC

Maximum requests expected from the chipset (number of TAD home trackers allocated to chipset). The maximum RTID value that may be used is one less than this number. Home trackers are allocated in groups of 8, so bits 2:0 of the register may not be written, and bits 5:3 indicate how many groups of 8 are allocated.

Device: 0
Function: 0
Offset: 40h
Access as a Dword

Bit Type Reset Value Description

5:3 RW 3 VALUE. Maximum TAD requests from chipset (allocated in groups of 8).



2.6.2 MAXREQUEST_LS

Maximum requests expected from the sibling (number of TAD home trackers allocated to sibling). The maximum RTID value that may be used is one less than this number. Home Trackers are allocated in groups of 8, so bits 2:0 of the register may not be written, and bits 5:3 indicate how many groups of 8 are allocated.

Function: Offset:	Device: 0 Function: 0 Offset: 44h Access as a Dword				
Bit	Туре	Reset Value	Description		
5:3	RW	2	VALUE. Maximum TAD requests from sibling (allocated in groups of 8).		

2.6.3 MAXREQUEST_LL

Maximum requests expected from local accesses (number of TAD home trackers allocated to the local queue). The maximum RTID value that may be used is one less than this number. Home Trackers are allocated in groups of 8, so bits 2:0 of the register may not be written, and bits 5:3 indicate how many groups of 8 are allocated.

Function: Offset:	Device: 0 Function: 0 Offset: 48h Access as a Dword			
Bit	Туре	Reset Value	Description	
5:3	RW	3	VALUE. Maximum TAD requests from local accesses (allocated in groups of 8).	

2.6.4 MAX_RTIDS

Maximum number of RTIDs other homes have. How many requests can this caching agent send to the other home agents. This number is one more than the highest numbered RTID to use. Note these values reset to 2, and need to be increased by BIOS to whatever the home agents can support.

Device: 0 Function: 0 Offset: 60h Access as a Dword				
Bit	Туре	Reset Value	Description	
21:16	RW	2	LOCAL_MC. Maximum number of RTIDs for the local home agent.	
13:8	RW	2	SIBLING. Maximum number of RTIDs for the sibling home agent.	
5:0	RW	2	CHIPSET. Maximum number of RTIDs for the IOH home agent.	



2.6.5 DESIRED_CORES

Number of cores, threads BIOS wants to exist on the next reset. A processor reset must be used for this register to take affect. Note programing this register to a value higher than the product has cores, should not be done. Which cores are removed is not defined and is implementation dependent. This does not result in all of the power savings of a reduced number of core product, but does save more power than even the deepest sleep state.

Function: Offset:	Function: 0					
Bit	Туре	Reset Value	Description			
16	RW1S	0	LOCK. Once written to 1, changes to this register cannot be made.			
8	RWL	0	MT_DISABLE. Disables multi-threading (2 logical threads per core) in all cores if set to 1.			
1:0	RWL	0	CORE_COUNT. 00: max number (default value) 01 - 1 core 10 - 2 cores			

2.6.6 MEMLOCK_STATUS

Status register for various Memory and Control Register functions that can be locked down.

Functio Offset:	Device: 0 Function: 0 Offset: 88h Access as a Dword					
Bit	Туре	Reset Value	Description			
9	RO	-	MEM_LOCKED_REMOTE. Any access to local memory from another agent (i.e. everybody but this processor) is aborted. Can only be unlocked when in Authenticated Code Mode.			
8	RO	-	MEM_LOCKED_LOCAL. Any Access to local memory from this processor is aborted. Can only be unlocked when in Authenticated Code Mode.			
1	RO	-	MEM_CFG_USER_LOCKED. Locks same as MEM_CFG_LOCKED but user controlled lockable by MC_CFG_CONTROL; unlockable via MC_CFG_CONTROL csr(0x0090).			
0	RO	-	MEM_CFG_LOCKED. All Configuration registers dealing with memory and address programming are locked down and cannot be changed. This includes all registers in Device 3 Function [0,1], Device 4,5,6 Function 0, Device 4,5,6 Function 1, Device 4,5,6 Function 2, and most registers in Device 0 Function 1. But does not include the memory controller thermal registers, or SAD_PAM0123, SAD_PAM456, SAD_SMRAM registers.			



2.6.7 MC_CFG_CONTROL

This register locks and unlocks write access to the Uncore configuration. BIOS must write a "1" to the MC_CFG_LOCK bit after reset to allow the Integrated Memory Controller to start accepting requests. It may subsequently be unlocked by writing a "1" to the MC_CFG_UNLOCK bit and a "0" to the MC_CFG_LOCK bit without affecting memory traffic.

Device: 0 Function: 0 Offset: 90h Access as a Dword				
Bit	Туре	Reset Value	Description	
1	WO	0	MC_CFG_UNLOCK. Unlocks Integrated Memory Controller configuration registers without CPU reset. This bit does NOT unlock any other lock type without a CPU reset.	
0	WO	0	MC_CFG_LOCK. Locks Integrated Memory Controller configuration registers. Writes are no longer allowed to the configuration registers.	

2.6.8 POWER_CNTRL_ERR_STATUS

Power management Error Status register.

Device: Function: Offset: Access as	B0h		
Bit	Туре	Reset Value	Description
63	RO	-	VAL. MC7_STATUS Register Valid. Indicates if the register is valid.
			0: Not Valid 1: Valid
62	RO		OVER. Machine Check Overflow Flag. Indicates (when set) that a machine-check error occurred while the results of a previous error were still in the error-reporting register bank (that is, the VAL bit was already set in the IA32_MC7_STATUS register). The processor sets the OVER flag and software is responsible for clearing it. In general, enabled errors are written over disabled errors, and uncorrected errors are written over corrected errors. Uncorrected errors are not written over previous valid uncorrected errors. 0: No Overflow 1: Overflow
61	RO	-	UC. Error Uncorrected Flag. Indicates (when set) that the processor did not or was not able to correct the error condition. When cleared, this flag indicates that the processor was able to correct the error condition. O: Corrected 1: Uncorrected
60	RO	-	EN. Error Enabled Flag. Indicates (when set) that the error was enabled by the associated EEj bit of the IA32_MC7_CTL register. O: Not Enabled 1: Enabled



Device: Function: Offset: Access as	B0h		
59	RO	-	MISCV. IA32_MC7_MISC. Register Valid Flag. Indicates (when set) that the IA32_MC7_MISC register contains additional information regarding the error. When clear, this flag indicates that the IA32_MC7_MISC register is either not implemented or does not contain additional information regarding the error. Do not read these registers if they are not implemented in the processor.
58	RO	-	ADDRV. IA32_MC7_ADDR. Register Valid Flag. Indicates (when set) that the IA32_MC7_ADDR register contains the address where the error occurred. When clear , this flag indicates that the IA32_MC7_ADDR register is either not implemented or does not contain the address where the error occurred. Do not read these registers if they are not implemented in the processor.
57	RO	-	PCC. Processor context corrupt flag. Indicates (when set) that the state of the processor might have been corrupted by the error condition detected and that reliable restarting of the processor may not be possible. When cleared, this flag indicates that the error did not affect the processor's state. 0: Not Corrupt 1: Corrupt
56:32	-	-	RSVD.
31:16	RO	-	MODEL SPECIFIC ERROR CODE. Specifies the model specific error code that uniquely identifies the machine-check error condition detected. The following list describes the error codes that may be found on the processor. OX0000: No Error OX0300: Unexpected reset error. Processor boot failed. OX0800: PMReq or CmpD received was illegal in the current context. OX0A00: Illegal PMReq request detected under S3, S4 or S5. OX0D00: Invalid S-state transition requested. OX1100: Platform / CPU VID controller mismatch. Processor boot failed. OX1A00: Platform / CPU MSID mismatch. Processor boot failed. OX2000: QPI training error.
15:0	RO	-	MCA ERROR CODE FIELD. Specifies the machine-check architecture-defined error code for the machine-check error condition detected. The machine-check architecture-defined error codes are guaranteed to be the

2.6.9 CURRENT_UCLK_RATIO

Status Register reporting the current Uncore Clk Ratio relative to BCLK (133Mhz). This is the clock in which the Last Level Cache (LLC) runs.

Function Offset:	Device: 0 Function: 0 Offset: COh Access as a Dword				
Bit	Туре	Reset Value	Description		
15	RW	0	RSVD.		
14:8	RW	12	RSVD.		
6:0	RO	-	UCLK. The current UCLK ratio		



2.6.10 MIRROR_PORT_CTL

Mirror Port physical layer control register.

Device: 0 Function: 0 Offset: D0h Access as a Dword					
Bit	Туре	Reset Value	Description		
7	RW	0	SPARE. Spare MiP control register bits.		
6	RW	0	DSBL_ENH_MPRX_SYNC. When set, it disables the enhancing synchronization scheme for the MiP_Rx.		
5	RW	0	MIP_GO_10. When set, the Mip_Tx and Mip_Rx go to L0 directly from Config_FlitLock.		
4	RW	0	MIP_RX_CRC_SQUASH. When set, replaces CRC errors with CRC special packet on MiP Rx.		
3	RW	0	MIP_RX_PORT_SEL. Port select for MiP RxPORT_SEL0=QPI Port 0PORT_SEL1=QPI Port 1.		
2	RW	0	MIP_TX_PORT_SEL. Port select for MiP TxPORT_SEL0=QPI Port 0PORT_SEL1=QPI Port 1.		
1	RW	1	MIP_RX_ENABLE. Enables the Rx portion of the mirror port.		
0	RW	1	MIP_TX_ENABLE. Enables the Tx portion of the mirror port.		

2.6.11 MIP_PH_CTR_L0 MIP_PH_CTR_L1

Mirror Port Physical Layer Control Register.

Device: Function: Offset: Access as	E0h, F0h		
Bit	Туре	Reset Value	Description
27	RW	0	LA_LOAD_DISABLE. Disables the loading of the effective values of the Intel® QuickPath CSRs when set.
23	RW	0	ENABLE_PRBS. Enables LFSR pattern during bitlock/training.
22	RW	0	ENABLE_SCRAMBLE. Enables data scrambling through LFSR.
14	RW	1	DETERMINISM_MODE. Sets determinism mode of operation.
13	RW	1	DISABLE_AUTO_COMP. Disables automatic entry into compliance.
12	RW	0	INIT_FREEZE. When set, freezes the FSM when initialization aborts.
10:8	RW	0	INIT_MODE. Initialization mode that determines altered initialization modes.
7	RW	0	LINK_SPEED . Identifies slow speed or at-speed operation for the Intel QPI port.
5	RW	1	PHYINITBEGIN. Instructs the port to start initialization.
4	RW	0	SINGLE_STEP. Enables single step mode.
3	RW	0	LAT_FIX_CTL. If set, instructs the remote agent to fix the latency.
2	RW	0	BYPASS_CALIBRATION. Indicates the physical layer to bypass calibration.



Device: Function: Offset: Access as			
Bit	Туре	Reset Value	Description
1	RW	0	RESET_MODIFIER. Modifies soft reset to default reset when set.
0	RW1S	0	PHY_RESET. Physical Layer Reset. Note while this register is locked after going to FAST speed L0, this bit is not locked.

2.6.12 MIP_PH_PRT_L0 MIP_PH_PRT_L1

Mirror Port periodic retraining timing register.

Device: 0 Function: 0 Offset: E4h, F4h Access as a Dword				
Bit	Туре	Reset Value	Description	
21:16	RW	29	RETRAIN_PKT_CNT. Retraining packet count.	
13:10	RW	11	EXP_RETRAIN_INTERVAL. Exponential count for retraining interval.	
7:0	RW	3	RETRAIN_INTERVAL. Periodic retraining interval. A value of 0 indicates retraining is disabled.	

2.7 SAD - System Address Decoder Registers

2.7.1 SAD_PAM0123

Device: 0

Register for legacy dev0func0 90h-93h address space.

Offset:	Function: 1 Offset: 40h Access as a Dword					
Bit	Туре	Reset Value	Description			
29:28	RW	0	PAM3_HIENABLE. 0D4000-0D7FFF Attribute (HIENABLE) This field controls the steering of read and write cycles that address the BIOS area from 0D4000 to 0D7FFF. 00: DRAM Disabled: All accesses are directed to ESI. 01: Read Only: All reads are sent to DRAM. All writes are forwarded to ESI. 10: Write Only: All writes are send to DRAM. Reads are serviced by ESI. 11: Normal DRAM Operation: All reads and writes are serviced by DRAM.			
25:24	RW	0	PAM3_LOENABLE. 0D0000-0D3FFF Attribute (LOENABLE) This field controls the steering of read and write cycles that address the BIOS area from 0D0000 to 0D3FFF 00: DRAM Disabled: All accesses are directed to ESI. 01: Read Only: All reads are sent to DRAM. All writes are forwarded to ESI. 10: Write Only: All writes are send to DRAM. Reads are serviced by ESI. 11: Normal DRAM Operation: All reads and writes are serviced by DRAM.			



Device: 0 Function: 1 Offset: 40h Access as a Dword

Access a	Access as a Dword				
Bit	Туре	Reset Value	Description		
21:20	RW	0	PAM2_HIENABLE. OCC000-0CFFFF Attribute (HIENABLE) This field controls the steering of read and write cycles that address the BIOS area from OCC000 to 0CFFFF. OC: DRAM Disabled: All accesses are directed to ESI. O1: Read Only: All reads are sent to DRAM. All writes are forwarded to ESI. 10: Write Only: All writes are send to DRAM. Reads are serviced by ESI. 11: Normal DRAM Operation: All reads and writes are serviced by DRAM.		
17:16	RW	0	PAM2_LOENABLE. OC8000-0CBFFF Attribute (LOENABLE) This field controls the steering of read and write cycles that address the BIOS area from 0C8000 to 0CBFFF. O0: DRAM Disabled: All accesses are directed to ESI. O1: Read Only: All reads are sent to DRAM. All writes are forwarded to ESI. 10: Write Only: All writes are send to DRAM. Reads are serviced by ESI. 11: Normal DRAM Operation: All reads and writes are serviced by DRAM.		
13:12	RW	0	PAM1_HIENABLE. 0C4000-0C7FFF Attribute (HIENABLE) This field controls the steering of read and write cycles that address the BIOS area from 0C4000 to 0C7FFF. O0: DRAM Disabled: All accesses are directed to ESI. O1: Read Only: All reads are sent to DRAM. All writes are forwarded to ESI. 10: Write Only: All writes are send to DRAM. Reads are serviced by ESI. 11: Normal DRAM Operation: All reads and writes are serviced by DRAM.		
9:8	RW	0	PAM1_LOENABLE. 0C0000-0C3FFF Attribute (LOENABLE) This field controls the steering of read and write cycles that address the BIOS area from 0C0000 to 0C3FFF. 00: DRAM Disabled: All accesses are directed to ESI. 01: Read Only: All reads are sent to DRAM. All writes are forwarded to ESI. 10: Write Only: All writes are send to DRAM. Reads are serviced by ESI. 11: Normal DRAM Operation: All reads and writes are serviced by DRAM.		
5:4	RW	0	PAMO_HIENABLE. 0F0000-0FFFFF Attribute (HIENABLE) This field controls the steering of read and write cycles that address the BIOS area from 0F0000 to 0FFFFF. 00: DRAM Disabled: All accesses are directed to ESI. 01: Read Only: All reads are sent to DRAM. All writes are forwarded to ESI. 10: Write Only: All writes are send to DRAM. Reads are serviced by ESI. 11: Normal DRAM Operation: All reads and writes are serviced by DRAM.		



2.7.2 SAD_PAM456

Register for legacy dev0func0 94h-97h address space.

Device: 0 Function: 1 Offset: 44h Access as a Dword

Bit	Туре	Reset Value	Description
21:20	RW	0	PAM6_HIENABLE. OECO00-0EFFFF Attribute (HIENABLE) This field controls the steering of read and write cycles that address the BIOS area from 0EC000 to 0EFFFF. O0: DRAM Disabled: All accesses are directed to ESI. O1: Read Only: All reads are sent to DRAM. All writes are forwarded to ESI. 10: Write Only: All writes are send to DRAM. Reads are serviced by ESI. 11: Normal DRAM Operation: All reads and writes are serviced by DRAM.
17:16	RW	0	PAM6_LOENABLE. 0E8000-0EBFFF Attribute (LOENABLE) This field controls the steering of read and write cycles that address the BIOS area from 0E8000 to 0EBFFF. O0: DRAM Disabled: All accesses are directed to ESI. O1: Read Only: All reads are sent to DRAM. All writes are forwarded to ESI. 10: Write Only: All writes are send to DRAM. Reads are serviced by ESI. 11: Normal DRAM Operation: All reads and writes are serviced by DRAM.
13:12	RW	0	PAM5_HIENABLE. 0E4000-0E7FFF Attribute (HIENABLE) This field controls the steering of read and write cycles that address the BIOS area from 0E4000 to 0E7FFF. O0: DRAM Disabled: All accesses are directed to ESI. O1: Read Only: All reads are sent to DRAM. All writes are forwarded to ESI. 10: Write Only: All writes are send to DRAM. Reads are serviced by ESI. 11: Normal DRAM Operation: All reads and writes are serviced by DRAM.
9:8	RW	0	PAM5_LOENABLE. 0E0000-0E3FFF Attribute (LOENABLE) This field controls the steering of read and write cycles that address the BIOS area from 0E0000 to 0E3FFF. 00: DRAM Disabled: All accesses are directed to ESI. 01: Read Only: All reads are sent to DRAM. All writes are forwarded to ESI. 10: Write Only: All writes are send to DRAM. Reads are serviced by ESI. 11: Normal DRAM Operation: All reads and writes are serviced by DRAM.
5:4	RW	0	PAM4_HIENABLE. ODC000-ODFFFF Attribute (HIENABLE) This field controls the steering of read and write cycles that address the BIOS area from ODC000 to ODFFFF. O0: DRAM Disabled: All accesses are directed to ESI. O1: Read Only: All reads are sent to DRAM. All writes are forwarded to ESI. 10: Write Only: All writes are send to DRAM. Reads are serviced by ESI. 11: Normal DRAM Operation: All reads and writes are serviced by DRAM.
1:0	RW	0	PAM4_LOENABLE. OD8000-ODBFFF Attribute (LOENABLE) This field controls the steering of read and write cycles that address the BIOS area from 0D8000 to 0DBFFF. O0: DRAM Disabled: All accesses are directed to ESI. O1: Read Only: All reads are sent to DRAM. All writes are forwarded to ESI. 10: Write Only: All writes are send to DRAM. Reads are serviced by ESI. 11: Normal DRAM Operation: All reads and writes are serviced by DRAM.



2.7.3 **SAD_HEN**

Register for legacy Hole Enable.

Device: 0 Function: 1 Offset: 48h Access as a Dword				
Bit	Туре	Reset Value	Description	
7	RW	0	HEN. This field enables a memory hole in DRAM space. The DRAM that lies "behind" this space is not remapped. 0: No Memory hole. 1: Memory hole from 15 MB to 16MB.	

2.7.4 SAD_SMRAM

Register for legacy 9Dh address space. Note both IOH and non-core have this now.

Device: 0 Function: 1 Offset: 4Ch Access as a Dword					
Bit	Туре	Reset Value	Description		
14	RW	0	SMM Space Open (D_OPEN). When D_OPEN=1 and D_LCK=0, the SMM space DRAM is made visible even when SMM decode is not active. This is intended to help BIOS initialize SMM space. Software should ensure that D_OPEN=1 and D_CLS=1 are not set at the same time.		
13	RW	0	SMM Space Closed (D_CLS). When D_CLS = 1 SMM space DRAM is not accessible to data references, even if SMM decode is active. Code references may still access SMM space DRAM. This will allow SMM software to reference through SMM space to update the display even when SMM is mapped over the VGA range. Software should ensure that D_OPEN=1 and D_CLS=1 are not set at the same time.		
12	RW1S	0	SMM Space Locked (D_LCK). When D_LCK is set to 1 then D_OPEN is reset to 0 and D_LCK, D_OPEN, C_BASE_SEG, G_SMRAME, PCIEXBAR, (DRAM_RULEs and INTERLEAVE_LISTs) become read only. D_LCK can be set to 1 via a normal configuration space write but can only be cleared by a Reset. The combination of D_LCK and D_OPEN provide convenience with security. The BIOS can use the D_OPEN function to initialize SMM space and then use D_LCK to "lock down" SMM space in the future so that no application software (or BIOS itself) can violate the integrity of SMM space, even if the program has knowledge of the D_OPEN function. Note that TAD does not implement this lock.		
11	RW	0	Global SMRAM Enable (G_SMRAME). If set to a 1, then Compatible SMRAM functions are enabled, providing 128 KB of DRAM accessible at the A0000h address while in SMM (ADSB with SMM decode). To enable Extended SMRAM function this bit has to be set to 1. Once D_LCK is set, this bit becomes read only.		
10:8	RO	-	Compatible SMM Space Base Segment (C_BASE_SEG). This field indicates the location of SMM space. SMM DRAM is not remapped. It is simply made visible if the conditions are right to access SMM space, otherwise the access is forwarded to HI. Only SMM space between A0000 and BFFFF is supported so this field is hardwired to 010.		



2.7.5 SAD_PCIEXBAR

Global register for PCIEXBAR address space.

Device: Function: 1 Offset: 50h Access as a Qword Reset Bit Type Description **Value** 39:20 RW 0 ADDRESS. Base address of PCIEXBAR. Must be naturally aligned to size; low order bits are ignored. SIZE. Size of the PCIEXBAR address space. (MAX bus number). 3:1 RW 000: 256MB. 001: Reserved. 010: Reserved.

100: Reserved.
101: Reserved.
110: 64MB.
111: 128MB.

0 RW 0 ENABLE. Enable for PCIEXBAR address space. Editing size should not be done without also enabling range.

2.7.6 SAD_DRAM_RULE_0

SAD_DRAM_RULE_1

SAD_DRAM_RULE_2

SAD_DRAM_RULE_3

SAD_DRAM_RULE_4

SAD_DRAM_RULE_5

SAD_DRAM_RULE_6 SAD_DRAM_RULE_7

SAD DRAM rules. Address Map for package determination.

011: Reserved.

Device: 0 Function: 1

Offset: 80h, 84h, 88h, 8Ch, 90h, 94h, 98h, 9Ch

Access as a Dword

Bit	Туре	Reset Value	Description		
19:6	RW	-	LIMIT. DRAM rule top limit address. Must be strictly greater than previous rule, even if this rule is disabled, unless this rule and all following rules are disabled. Lower limit is the previous rule (or 0 if it is first rule). This field is compared against MA[39:26] in the memory address map.		
2:1	RW	-	MODE. DRAM rule interleave mode. If a DRAM_RULE hits a 3 bit number is used to index into the corresponding interleave_list to determine which package the DRAM belongs to. This mode selects how that number is computed. 00: Address bits {8,7,6}. 01: Address bits {8,7,6} XORed with {18,17,16}. 10: Address bit {6}, MOD3(Address[396]). (Note 6 is the high order bit) 11: Reserved.		
0	RW	0	ENABLE. Enable for DRAM rule. If Enabled Range between this rule and previous rule is Directed to HOME channel (unless overridden by other dedicated address range registers). If disabled, all accesses in this range are directed in MMIO to the IOH.		



2.7.7 SAD_INTERLEAVE_LIST_0 SAD_INTERLEAVE_LIST_1 SAD_INTERLEAVE_LIST_2 SAD_INTERLEAVE_LIST_3 SAD_INTERLEAVE_LIST_4 SAD_INTERLEAVE_LIST_5 SAD_INTERLEAVE_LIST_6 SAD_INTERLEAVE_LIST_7

SAD DRAM package assignments. When the corresponding DRAM_RULE hits, a 3-bit number (determined by mode) is used to index into the interleave_list to determine which package is the HOME for this address.

00: IOH 01: Socket 0 10: Socket 1 11: Reserved

Device: 0 Function: 1 Offset: C0h, C4h, C8h, CCh, D0h, D4h, D8h, DCh

Access as a Dword

Bit	Туре	Reset Value	Description
29:28	RW	-	PACKAGE7. Package for index value 7 of interleaves.
25:24	RW	-	PACKAGE6. Package for index value 6 of interleaves.
21:20	RW	-	PACKAGE5. Package for index value 5 of interleaves.
17:16	RW	-	PACKAGE4. Package for index value 4 of interleaves.
13:12	RW	-	PACKAGE3. Package for index value 3 of interleaves.
9:8	RW	-	PACKAGE2. Package for index value 2 of interleaves.
5:4	RW	-	PACKAGE1. Package for index value 1 of interleaves.
1:0	RW	-	PACKAGEO. Package for index value 0 of interleaves.

2.8 **Intel QPI Link Registers**

QPI_QPILCP_L0 2.8.1 QPI_QPILCP_L1

Intel QPI Link Capability. Function 4 in the below table applies only to processors with two Intel QPI links.

Device: 2 Function: 0, 4 Offset: Access as a Dword

Bit	Туре	Reset Value	Description
27:26	RO	-	VNO_CRDTS_DATA. VNO Credits per Data MC 00 - 0 credits 01 - 1 10 - 2 to 8 11 - RSVD



Device: 2 Function: 0, 4 Offset: 40h Access as a Dword

		Reset	
Bit	Туре	Value	Description
23:22	RO	-	VNO_CRDTS_NDATA. VNO Credits per Non-Data MC 00 - 0 credits 01 - 1 10 - 2 to 8 11 - RSVD
21:16	RO	-	VNA_CRDTS. VNA Credits / 8, after rounding down.
11	RO	-	CRC_SUPPORT. CRC Mode Support. 0 - 8b CRC. 1 - RSVD
9:8	RO	-	FLIT_INTERLEAVE. Flit Interleave. 00 - Idle/Null flit only. 01 - Command Insert Interleave. 10 - RSVD. 11 - RSVD.
7:0	RO	-	QPI_VER. Intel QPI Version Number 0 - Rev 1.0 !0 - RSVD.

2.8.2 QPI_QPILCL_L0 QPI_QPILCL_L1

Intel QPI Link Control.

Device: 2 Function: 0, 4 Offset: 48h Access as a Dword

Access	Access as a Dword				
Bit	Туре	Reset Value	Description		
21	RW	0	L1_MASTER. Indicates that this end of the link is the L1 master. This link transmitter bit is an L1 power state master and can initiate an L1 power state transition. If this bit is not set, then the link transmitter is an L1 power state slave and should respond to L1 transitions with an ACK or NACK. If the link power state of L1 is enabled, then there is one master and one slave per link. The master may only issue single L1 requests, while the slave can only issue single L1_Ack or L1_NAck responses for the corresponding request.		
20	RW	0	L1_ENABLE. Enables L1 mode at the transmitter. This bit should be ANDed with the receive L1 capability bit received during parameter exchange to determine if a transmitter is allowed to enter into L1. This is NOT a bit that determines the capability of a device.		
18	RW	0	LOS_ENABLE. Enables LOs mode at the transmitter. This bit should be ANDed with the receive LOs capability bit received during parameter exchange to determine if a transmitter is allowed to enter into LOs. This is NOT a bit that determines the capability of a device.		



2.8.3 QPI_QPILS_L0 QPI_QPILS_L1

Intel QPI Link Status.

Device: 2
Function: 0, 4
Offset: 50h
Access as a Dword

Bit Type Reset Value Description

31 RO - CHIPSET_LINK. Indicates that the local physical link is connected to the IOH.

2.8.4 QPI_DEF_RMT_VN_CREDITS_L0 QPI_DEF_RMT_VN_CREDITS_L1

This is the control register that houses the default values of available remote credits to be transmitted to the remote agent for the remote Tx use.

Device: Function: 0, 4 Offset: 58h Access as a Dword Reset Bit **Type** Description Value 18:12 RW 100 VNA. VNA Credits. 11:10 RW 1 NCS. NCS Channel VNO Credits. 9:8 RW 1 NCB. NCB Channel VNO Credits. 7:6 RW 1 DRS. DRS Channel VN0 Credits. 5:4 RW 1 NDR. NDRChannel VN0 Credits. 3:2 RW 1 SNP. SNP Channel VNO Credits. 1:0 RW HOM. HOMChannel VNO Credits.

2.8.5 QPI_RMT_QPILP0_STAT_L0 QPI_RMT_QPILP0_STAT_L1

Remote's QPI Parameter 0 Value register.

Device: Function: 0, 4 COh Offset: Access as a Dword Reset Bit **Type** Description Value 23:16 RO LLR_WRAP_VALUE. Value after which the LLR sequence counter wraps. 14:8 RO -NodeID_OFFSET. Node ID offset for the sending agent. 7:5 RO Nodel D. Number of Node IDs of the transmitting agent. 4:0 RO PORT_NUMBER. Sender's port number.



2.8.6 QPI_RMT_QPILP1_STAT_L0 QPI_RMT_QPILP1_STAT_L1

Remote's QPI Parameter 1 Value register.

Device: 2 Function: 0, 4 Offset: C4h Access as a Dword

Bit	Туре	Reset Value	Description		
9	RO	-	L1_SUPPORT. Indicates the remote agent's ability to support L1 state.		
8	RO	-	LOP_SUPPORT. Indicates the remote agent's ability to support LOP state.		
7	RO	-	LOS_SUPPORT. Indicates the remote agent's ability to support LOS state.		
6	RO	-	RX_CII_SUPPORT . Indicates the remote agent's ability to receive CII data.		
5	RO	-	PREFERRED_TX_SDI_MODE. Indicates the ability of the remote agent transmitter to send scheduled data interleave data.		
4	RO	-	RCV_SDI_SUPPORT. Indicates remote agent can receive scheduled data interleave data.		
3:2	RO	-	PREFERRED_TX_CRC_MODE. Preferred send mode for the remote transmitter. 00: No CRC 01: 8b CRC 10: 16b rolling CRC 11: RSVD		
1:0	RO	-	RCV_CRC_MODE_SUPPORTED. CRC modes that the remote agent supports. 00: RSVD 01: 8b CRC 10: 16b and 8b CRC 11: RSVD		

2.8.7 QPI_RMT_QPILP2_STAT_L0 QPI_RMT_QPILP2_STAT_L1

Remote's QPI Parameter 2 Value register.

Device: 2 Function: 0, 4 Offset: C8h Access as a Dword

Access as	Access as a Dword					
Bit	Туре	Reset Value	Description			
31	RO	-	Agent_000_Caching. Indicates agent 000 is a caching agent.			
30	RO	-	Agent_000_Home. Indicates agent 000 is a home agent.			
29	RO	-	Agent_000_IO_Proxy. Indicates agent 000 is an IO Proxy agent.			
28	RO	-	RSVD.			
26	RO	-	Agent_000_Router. Indicates agent 000 is a router agent.			
25	RO	-	Agent_000_Firmware. Indicates agent 000 is a firmware agent.			
24	RO	-	Agent_000_Config. Indicates agent 000 is a configuration agent.			
23	RO	-	Agent_001_Caching. Indicates agent 001 is a caching agent.			
22	RO	-	Agent_001_Home. Indicates agent 001 is a home agent.			
21	RO	-	Agent_001_IO_Proxy. Indicates agent 001 is an IO Proxy agent.			



Device: 2 Function: 0, 4 Offset: C8h Access as a Dword

Bit	Туре	Reset Value	Description
20	RO	-	RSVD.
18	RO	-	Agent_001_Router. Indicates agent 001 is a router agent.
17	RO	-	Agent_001_Firmware. Indicates agent 001 is a firmware agent.
16	RO	-	Agent_001_Config. Indicates agent 001 is a configuration agent.
15	RO	-	Agent_010_Caching. Indicates agent 010 is a caching agent.
14	RO	-	Agent_010_Home. Indicates agent 010 is a home agent.
13	RO	-	Agent_010_IO_Proxy. Indicates agent 010 is an IO Proxy agent.
12	RO	-	RSVD.
10	RO	-	Agent_010_Router. Indicates agent 010 is a router agent.
9	RO	-	Agent_010_Firmware. Indicates agent 010 is a firmware agent
8	RO	-	Agent_010_Config. Indicates agent 010 is a configuration agent.
7	RO	-	Agent_011_Caching. Indicates agent 011 is a caching agent.
6	RO	-	Agent_011_Home. Indicates agent 011 is a home agent.
5	RO	-	Agent_011_IO_Proxy. Indicates agent 011 is an IO Proxy agent.
4	RO	-	RSVD.
2	RO	-	Agent_011_Router. Indicates agent 011 is a router agent.
1	RO	-	Agent_011_Firmware. Indicates agent 011 is a firmware agent.
0	RO	-	Agent_011_Config. Indicates agent 011 is a configuration agent.

2.8.8 QPI_RMT_QPILP3_STAT_L0 QPI_RMT_QPILP3_STAT_L1

Remote's QPI Parameter 3 Value register.

Device: 2 Function: 0, 4 Offset: CCh Access as a Dword

Access as a Dword				
Bit	Туре	Reset Value	Description	
31	RO	-	Agent_100_Caching. Indicates agent 100 is a caching agent.	
30	RO	-	Agent_100_Home. Indicates agent 100 is a home agent.	
29	RO	-	Agent_100_IO_Proxy. Indicates agent 100 is an IO Proxy agent.	
28	RO	-	RSVD.	
26	RO	-	Agent_100_Router. Indicates agent 100 is a router agent.	
25	RO	-	Agent_100_Firmware. Indicates agent 100 is a firmware agent.	
24	RO	-	Agent_100_Config. Indicates agent 100 is a configuration agent.	
23	RO	-	Agent_101_Caching. Indicates agent 101 is a caching agent.	
22	RO	-	Agent_101_Home. Indicates agent 101 is a home agent.	
21	RO	-	Agent_101_IO_Proxy. Indicates agent 101 is an IO Proxy agent.	
20	RO	-	RSVD.	



Device: 2 Function: 0, 4 Offset: CCh Access as a Dword

Bit	Туре	Reset Value	Description
18	RO	-	Agent_101_Router. Indicates agent 101 is a router agent.
17	RO	-	Agent_101_Firmware. Indicates agent 101 is a firmware agent.
16	RO	-	Agent_101_Config. Indicates agent 101 is a configuration agent.
15	RO	-	Agent_110_Caching. Indicates agent 110 is a caching agent.
14	RO	-	Agent_110_Home. Indicates agent 110 is a home agent.
13	RO	-	Agent_110_IO_Proxy. Indicates agent 110 is an IO Proxy agent.
12	RO	-	RSVD.
10	RO	-	Agent_110_Router. Indicates agent 110 is a router agent.
9	RO	-	Agent_110_Firmware. Indicates agent 110 is a firmware agent
8	RO	-	Agent_110_Config. Indicates agent 110 is a configuration agent.
7	RO	-	Agent_111_Caching. Indicates agent 111 is a caching agent.
6	RO	-	Agent_111_Home. Indicates agent 111 is a home agent.
5	RO	-	Agent_111_IO_Proxy. Indicates agent 111 is an IO Proxy agent.
4	RO	-	RSVD.
2	RO	-	Agent_111_Router. Indicates agent 111 is a router agent.
1	RO	-	Agent_111_Firmware. Indicates agent 111 is a firmware agent.
0	RO	-	Agent_111_Config. Indicates agent 111 is a configuration agent.

2.9 Intel QPI Physical Layer Registers

2.9.1 QPI_0_PH_CPR QPI_1_PH_CPR

Intel QPI Physical Layer Capability Register.

Device: 2 Function: 1, 5 Offset: 68h Access as a Dword

Bit	Туре	Reset Value	Description
29	RO	-	LFSR_POLYNOMIAL. Agent's ITU polynomial capability for loopback.
28:24	RO	,	NUMBER_OF_TX_LANES. Number of Tx lanes with which an implementation can operate for full width. Bit 28 - If set, 20 lanes. The bit indicating the maximum lanes will determine the number of control/status bits implemented in Tx/Rx Data lane Control/Status Registers.
23	RO	-	PRBS_CAPABILITY. If set, implementation is capable of using specified pattern in bitlock/retraining.
22	RO	-	SCRAMBLE_CAPABILITY. If set, implementation is capable of data scrambling/descrambling with LFSR.



Device: 2 Function: 1, 5 Offset: 68h Access as a Dword

Bit	Туре	Reset Value	Description
21:20	RO	1	RAS_CAPABILITY. Any of these bits set indicates Alternate Clock RAS capability available and that corresponding control bits in QPI_*_PH_CTR are implemented.
17:16	RO	-	DETERMINISM_SUPPORT. Determinism supported mode of operations. Bit17: If set, Master mode of operation supported. Component Specification or equivalent document should contain the information about PhyLOSynch. Bit16: If set, Slave mode of operation supported.
10:8	RO	-	LINK_WIDTH_CAPABILITY. Bit8: If set, Full Width capable.
7:5	RO	0	DEBUG_CAPABILITY. Bit7: If set, an implementation is not capable of extracting slave electrical parameter from TS.Loopback and apply during the test. Bit6: If set, an implementation is not capable of running in Compliance slave mode as well as transitioning to Loopback.Pattern from Compliance state. Bit5: If set, an implementation is not capable of doing Loopcount Stal
4	RO	0	RETRAIN_GRANULARITY . If set, implementation is capable of 16UI granularity in retraining duration.
3:0	RO	-	PHY_VERSION. This is the Intel QPI Phy version. 0: Current Intel QPI version 0. Rest are reserved.

2.9.2 QPI_0_PH_CTR QPI_1_PH_CTR

Intel QPI Physical Layer Control Register.

Device: 2 Function: 1, 5 Offset: 6Ch Access as a Dword

Access as a Dword				
Bit	Туре	Reset Value	Description	
27	RW	0	LA_LOAD_DISABLE. Disables the loading of the effective values of the Intel QPI CSRs when set.	
23	RW	0	ENABLE_PRBS. Enables LFSR pattern during bitlock/training. 1 - use pattern in bitlock/retraining. 0 - use clock pattern for bitlock/retraining.	
22	RW	0	ENABLE_SCRAMBLE. Enables data scrambling through LFSR. 1 - data scrambled/descrambled with LFSR 0 - data not scrambled/descrambled.	
15:14	RW	2	DETERMINISM_MODE. Sets determinism mode of operation. 00 - Non-deterministic initialization. 01 - Slave mode initialization. 10 - Master mode of initialization - valid only if a component can generate its PhyL0Synch.	
13	RW	1	DISABLE_AUTO_COMP. Disables automatic entry into compliance. 0 - path from detect.clkterm to compliance is allowed. 1 - path from detect.clkterm to compliance is disabled.	
12	RW	0	INIT_FREEZE. When set, freezes the FSM when initialization aborts.	



Device: 2 Function: 1, 5 Offset: 6Ch Access as a Dword

Bit	Туре	Reset Value	Description
11	RW	0	DISABLE_ISI_CHECK. Defeature mode to disable ISI checking during Polling.LaneDeskew state.
10:8	RW	0	INIT_MODE. Initialization mode that determines altered initialization modes.
7	RW	0	LINK_SPEED. Identifies slow speed or at-speed operation for the Intel QPI port. 1 - Force direct operational speed initialization. 0 - Slow speed initialization.
5	RW	1	PHYINITBEGIN. Instructs the port to start initialization.
4	RW	0	SINGLE_STEP. Enables single step mode.
3	RW	0	LAT_FIX_CTL. If set, instructs the remote agent to fix the latency.
2	RW	0	BYPASS_CALIBRATION. Indicates the physical layer to bypass calibration.
1	RW	0	RESET_MODIFIER. Modifies soft reset to default reset when set.
0	RW1S	0	PHY_RESET. Physical Layer Reset.

2.9.3 QPI_0_PH_PIS QPI_1_PH_PIS

Intel QPI Physical Layer Initialization Status Register.

Device: 2 Function: 1, 5 Offset: 80h Access as a Dword

Access a	Access as a Dword				
Bit	Туре	Reset Value	Description		
29	RO	-	GLOBAL_ERROR. Set upon any error detected on the link during Loopback Pattern.		
28	RO	-	TEST_BUSY. Test busy bit indicating that a test is in progress.		
27	RW1C	0	STATE_HOLD. State machine hold bit for single step and init freeze modes.		
26	RO	-	INIT_SPEED. Current initialization speed. 1 - Operational Speed Initialization. 0 - Slow Speed Initialization.		
25	RO	-	PORT_RMT_ACK. Port Remote ACK status.		
24	RO	-	PORT_TX_RDY. Port Tx Ready status.		
20:16	RO	-	RX_STATE. Current state of the local Rx.		
12:8	RO	-	TX_STATE. Current state of the local Tx.		
1	RW1C	0	CALIBRATION_DONE. Indicates that calibration has been completed for the Intel QPI link.		
0	RW1C	0	LINKUP_IDENTIFIER. Link up identifier for the Intel QPI link. Set to 0 during Default Reset. Set to 1 when initialization completes and link enters L0.		



2.9.4 QPI_0_PH_PTV QPI_1_PH_PTV

Intel QPI Physical Layer Initialization Primary Timeout Value Register.

Device: 2 Function: 1, 5 Offset: 94h Access as a Dword					
Bit	Bit Type Reset Value Description				
19:16	RW	0	POLLING_BITLOCK . Exponential count for Polling Bitlock. Timeout value is 2^(count in this field)*128 TSL.		
11:8	RW	1	INBAND_RESET. Exponential count for Inband_Reset_Init. Time-out value is 2^(count in this field)*128 TSL.		
3:0	RW	2	DEBOUNCE. Exponential count for debounce.		

2.9.5 QPI_0_PH_LDC QPI_1_PH_LDC

Intel QPI Physical Layer Link Determinism Control Register.

Function Offset:	Device: 2 Function: 1, 5 Offset: 9Ch Access as a Dword					
Bit	Туре	Reset Value	Description			
23:16	RW	0	TARGET_LINK_LATENCY. This field specifies the target link latency value in UI that the remote port needs to adjust to.			
11:8	RW	5	DRIFT_BUF_DEPTH . The default pointer separation for the Intel QPI Rx PI FIFO.			
3:0	RW	2	DRIFT_ALARM_THRESHOLD. Intel QPI RX PI FIFO alarm threshold.			



2.9.6 QPI_0_PH_PRT QPI_1_PH_PRT

Intel QPI Periodic Retraining Timing Register

Device: 2 Function: 1, 5 Offset: A4h Access as a Dword						
Bit	Туре	Reset Value	Description			
22	RW	0	DURATION_GRANULARITY. 1 indicates agent is using 16 UI granularity 0 indicates agent is using 64 UI granularity.			
21:14	RW	-	RETRAIN_PKT_CNT. Retraining packet count.			
13:10	RW	-	EXP_RETRAIN_INTERVAL. Exponential count for retraining interval. Interval value is multiplied by 2^(count in this field). Although these values are specified in exponential form, counting still needs to be accurate to single UI.			
7:0	RW	-	RETRAIN_INTERVAL. Periodic retraining interval. A value of 0 indicates periodic retraining is disabled. Retraining must be disabled in Slow Mode. Value to be programmed by firmware. Each count represents 1024 UI (16 TSL)			

2.9.7 QPI_0_PH_PMR0 QPI_1_PH_PMR0

Intel QPI Physical Layer Power Management Register.

Device: 2 Function: 1, 5 Offset: D0h Access as a Dword Reset Bit Туре Description Value LOs_SLEEP_MIN_REM. 27:26 RW Remote agent's minimum LOS time. 00 -> 32 UI 01 -> 48 UI 10 -> 64 UI 11 -> 96 UI LOs_WAKE_REM. Remote agent's LOS wake time in effect. Value is 21:16 RW 0 (field+1)*16 UI. 11:10 RW LOs_SLEEP_MIN. Minimum time local Tx on a port initiating L0s entry should stay in LOs. 00 -> 32 UI 01 -> 48 UI 10 -> 64 UI 11 -> 96 UI 5:0 RW LOs_WAKE. LOs Wake-up time to be used by remote Tx. This parameter value is derived from field value as (field + 1)*16 UI. Field value of 0 (parameter value of 16) means L0s is not supported.



2.9.8 QPI_0_EP_SR QPI_1_EP_SR

Intel QPI Physical Layer Electrical Parameter Select Register. This register enables the equalization coefficient setting functionality of the QPI_[0,1]_EP_MCTR register when QPI_[0,1]_EP_SR is set to 6.

Device: 2 Function: 1, 5 Offset: E0h Access as a Dword						
Bit	Туре	Reset Value	Description			
23:16	RW	0	EPARAM_SEL. Select electrical parameter. Set to 6 to enable equalization coefficient setting functionality of QPI_[0,1]_EP_MCTR register.			

2.9.9 QPI_0_EP_MCTR QPI_1_EP_MCTR

Intel QPI Electrical Parameter Miscellaneous Control Register. This register holds equalization coefficient parameters.

Device: 2 Function: 1, 5 Offset: F4h Access as a Dword						
Bit	Туре	Reset Value	Description			
31:8	RW	0	MISC_EPARAM_CTL. Miscellaneous electrical-parameter specific control.			
7:3	RW	12	TX_EQUALIZATION . Sets the equalization coefficient of the QPI transmitter based on value obtained from SISTAI simulations.			
2	RW	1	EN. Enables or disables custom TEQ setting. 1 - Enable 0 - Disable			
1:0	RW	0	RSVD.			



2.10 Intel QPI Miscellaneous Registers

2.10.1 QPI_0_PLL_STATUS QPI_1_PLL_STATUS

This register provides the current and available operating conditions for the Intel QPI PLLs.

Device: 2 Function: 1, 5 Offset: 50h Access as a Dword Reset Bit **Type** Description Value 30:24 RO MAX_CCLK_RATIO. Maximum CCLK (The Intel® QuickPath Interconnect Forwarded Clock for at speed operation) supported on this part (Value 133Mhz). 22:16 RO MIN_CCLK_RATIO. Minimum CCLK (The Intel® QuickPath Interconnect Forwarded Clock for at speed operation) supported on this part (Value *

133Mhz).

14:8 RO - CCLK_RATIO_MASK. Mask that will be applied to the QPI_[0,1]_PLL_RATIO.NEXT_PLL_RATIO field on reset to obtain the current ratio (I.E. mask of 1 will force only even ratios; mask of 3 forces every 4th ratio).

6:0 RO - CURRENT_CCLK_RATIO. The current CCLK (The Intel® QuickPath Interconnect Forwarded Clock for at speed operation) (Value * 133Mhz).

2.10.2 QPI_0_PLL_RATIO QPI_1_PLL_RATIO

This register holds the next PLL multiplier. The write to one link will affect the mirror port as well as both Intel QPI links. The reads are link specific.

Device: 2
Function: 1, 5
Offset: 54h
Access as a Dword

Bit	Туре	Reset Value	Description
6:0	RW	12	NEXT_PLL_RATIO. The next Intel QPI PLL ratio to be adopted.



2.11 Integrated Memory Controller Control Registers

The registers in section 2.11 apply only to processors supporting registered DIMMs.

2.11.1 MC_CONTROL

Primary control register.

Device: 3 Function: 0 Offset: 48h Access as a Dword

Access as a Dword						
Bit	Туре	Reset Value	Description			
10	RW	0	CHANNEL2_ACTIVE. When set, indicates MC channel 2 is active. This bit is controlled (set/reset) by software only. This bit is required to be set for any active channel when INIT_DONE is set by software.			
9	RW	0	CHANNEL1_ACTIVE. When set, indicates MC channel 1 is active. This bit is controlled (set/reset) by software only. This bit is required to be set for any active channel when INIT_DONE is set by software. Channel 0 AND Channel 1 active must both be set for a lockstep or mirrored pair.			
8	RW	0	CHANNELO_ACTIVE. When set, indicate MC channel 0 is active. This bit is controlled (set/reset) by software only. This bit is required to be set for any active channel when INIT_DONE is set by software. Channel 0 AND Channel 1 active must both be set for a lockstep or mirrored pair.			
7	WO	0	INIT_DONE. MC initialize complete signal. Setting this bit will exit the training mode of the Integrated Memory Controller and begin normal operation including all enabled maintenance operations. Any CHANNNEL_ACTIVE bits not set when writing a 1 to INIT_DONE will cause the corresponding channel to be disabled.			
6	RW	0	DIVBY3EN. Divide By 3 enable. When set, MAD would use the longer pipeline for transactions that are 3 or 6 way interleaved and shorter pipeline for all other transactions. The SAG registers must be appropriately programmed as well.			
5	RW	0	CHANNELRESET2. Reset only the state within the channel. Equivalent to pulling warm reset for that channel.			
4	RW	0	CHANNELRESET1. Reset only the state within the channel. Equivalent to pulling warm reset for that channel.			
3	RW	0	CHANNELRESETO. Reset only the state within the channel. Equivalent to pulling warm reset for that channel.			
2	RW	0	AUTOPRECHARGE. Autoprecharge enable. This bit should be set with the closed page bit. If it is not set with closed page, address decode will be done without setting the autoprecharge bit.			
1	RW	0	ECCEN. ECC Checking enables. When this bit is set in lockstep mode the ECC checking is for the x8 SDDC. ECCEN without Lockstep enables the x4 SDDC ECC checking.			
0	RW	0	CLOSED_PAGE. When set, the MC supports a Closed Page policy. The default is Open Page but BIOS should always configure this bit.			



2.11.2 MC_STATUS

MC Primary Status register.

Device: Function: 0 Offset: 4Ch Access as a Dword Reset Bit Description Type Value 4 RO 1 ECC_ENABLED. ECC is enabled. CHANNEL2_DISABLED. Channel 2 is disabled. This can be factory configured 2 RO 0 or if Init done is written without the channel_active being set. Clocks in the channel will be disabled when this bit is set. **CHANNEL1_DI SABLED.** Channel 1 is disabled. This can be factory configured or if Init done is written without the channel_active being set. Clocks in the channel will be disabled when this bit is set. RO 0 CHANNELO_DI SABLED. Channel 0 is disabled. This can be factory configured 0 RO 0 or if Init done is written without the channel_active being set. Clocks in the channel will be disabled when this bit is set.

2.11.3 MC_SMI_DIMM_ERROR_STATUS

SMI DIMM error threshold overflow status register. This bit is set when the per-DIMM error counter exceeds the specified threshold. The bit is reset by BIOS.

Function Offset:	Device: 3 Function: 0 Offset: 50h Access as a Dword						
Bit	Туре	Reset Value	Description				
13:12	RWOC	0	REDUNDANCY_LOSS_FAILING_DIMM. The ID for the failing DIMM when redundancy is lost.				



Device: Function: 0 50h Offset: Access as a Dword Reset Bit **Type** Description **Value** DIMM_ERROR_OVERFLOW_STATUS. This 12-bit field is the per dimm error 11:0 RWOC 0 overflow status bits. The organization is as follows: If there are three or more DIMMS on the channel: Bit 0 : Dimm 0 Channel 0 Bit 1: Dimm 1 Channel 0 Bit 2: Dimm 2 Channel 0 Bit 3: Dimm 3 Channel 0 Bit 4: Dimm 0 Channel 1 Bit 5: Dimm 1 Channel 1 Bit 6: Dimm 2 Channel 1 Bit 7: Dimm 3 Channel 1 Bit 8: Dimm 0 Channel 2 Bit 9: Dimm 1 Channel 2 Bit 10: Dimm 2 Channel 2 Bit 11: Dimm 3 Channel 2 If there are one or two DIMMS on the channel: Bit 0: Dimm 0, Ranks 0 and 1, Channel 0 Bit 1: Dimm 0, Ranks 2 and 3, Channel 0 Bit 2: Dimm 1, Ranks 0 and 1, Channel 0 Bit 3: Dimm 1, Ranks 2 and 3, Channel 0 Bit 4: Dimm 0, Ranks 0 and 1, Channel 1 Bit 5: Dimm 0, Ranks 2 and 3, Channel 1 Bit 6: Dimm 1, Ranks 0 and 1, Channel 1 Bit 7: Dimm 1, Ranks 2 and 3, Channel 1 Bit 8: Dimm 0, Ranks 0 and 1, Channel 2 Bit 9: Dimm 0, Ranks 2 and 3, Channel 2 Bit 10: Dimm 1, Ranks 0 and 1, Channel 2

Bit 11: Dimm 1, Ranks 2 and 3, Channel 2

2.11.4 MC_SMI_CNTRL

System Management Interrupt control register.

Device: 3 Function: 0 Offset: 54h Access as a Dword

Bit	Туре	Reset Value	Description
16	RW	0	INTERRUPT_SELECT_NMI. NMI enable. Set to enable NMI signaling. Clear to disable NMI signaling. If both NMI and SMI enable bits are set, then only SMI is sent.
15	RW	0	INTERRUPT_SELECT_SMI. SMI enable. Set to enable SMI signaling. Clear to disable SMI signaling. If both NMI and SMI enable bits are set, then only SMI is sent. This bit functions the same way in Mirror and Independent Modes. The possible SMI events enabled by this bit are: Any one of the error counters MC_COR_ECC_CNT_X meets the value of SMI_ERROR_THRESHOLD field of this register. MC_RAS_STATUS.REDUNDANCY_LOSS bit is set to 1.
14:0	RW	0	SMI_ERROR_THRESHOLD. Defines the error threshold to compare against the per-DIMM error counters MC_COR_ECC_CNT_X, which are also 15 bits.



2.11.5 MC_RESET_CONTROL

DIMM Reset enabling controls.

Device: 3
Function: 0
Offset: 5Ch
Access as a Dword

Bit Type Reset Value Description

Bit	Туре	Reset Value	Description
0	WO	0	BIOS_RESET_ENABLE. When set, MC takes over control of driving RESET to the DIMMs. This bit is set on S3 exit and cold boot to take over RESET driving responsibility from the physical layer.

2.11.6 MC_CHANNEL_MAPPER

Channel mapping register. The sequence of operations to update this register is:

Read MC_Channel_Mapper register

Compare data read to data to be written. If different then write.

Poll MC_Channel_Mapper register until the data read matches data written.

Device: 3
Function: 0
Offset: 60h
Access as a Dword

Bit	Туре	Reset Value	Description
17:15	RW	0	RDLCH2. Mapping of Logical Channel 2 to physical channel for Reads.
			001 - Maps to physical Channel 0
			010 - Maps to physical Channel 1
			100 - Maps to physical Channel 2
14:12	RW	0	WRLCH2. Mapping of Logical Channel 2 to physical channel for Writes.
			001 - Maps to physical Channel 0
			010 - Maps to physical Channel 1
			100 - Maps to physical Channel 2
11:9	RW	0	RDLCH1. Mapping of Logical Channel 1 to physical channel for Reads.
			001 - Maps to physical Channel 0
			010 - Maps to physical Channel 1
			100 - Maps to physical Channel 2
8:6	RW	0	WRLCH1. Mapping of Logical Channel 1 to physical channel for Writes.
			001 - Maps to physical Channel 0
			010 - Maps to physical Channel 1
			100 - Maps to physical Channel 2
5:3	RW	0	RDLCHO. Mapping of Logical Channel 0 to physical channel for Read.
			001 - Maps to physical Channel 0
			010 - Maps to physical Channel 1
			100 - Maps to physical Channel 2
2:0	RW	0	WRLCHO. Mapping of Logical Channel 0 to physical channel for Writes.
			001 - Maps to physical Channel 0
			010 - Maps to physical Channel 1
			100 - Maps to physical Channel 2



2.11.7 MC_MAX_DOD

Defines the MAX number of DIMMS, RANKS, BANKS, ROWS, COLS among all DIMMS populating the three channels. The Memory Init logic uses this register to cycle through all the memory addresses writing all 0's to initialize all locations. This register is also used for scrubbing and must always be programmed if any DODs are programmed.

Offset:	Function: 0						
Bit	Туре	Reset Value	Description				
10:9	RW	0	MAXNUMCOL. Maximum Number of Columns. 00: 2^10 columns 01: 2^11 columns 10: 2^12 columns 11: RSVD.				
8:6	RW	0	MAXNUMROW. Maximum Number of Rows. 000: 2^12 Rows 001: 2^13 Rows 010: 2^14 Rows 011: 2^15 Rows 100: 2^16 Rows Others: RSVD.				
5:4	RW	0	MAXNUMBANK. Max Number of Banks. 00: Four-banked 01: Eight-banked 10: Sixteen-banked.				
3:2	RW	0	MAXNUMRANK. Maximum Number of Ranks. 00: Single Ranked 01: Double Ranked 10: Quad Ranked.				
1:0	RW	0	MAXNUMDIMMS. Maximum Number of Dimms. 00: 1 Dimm 01: 2 Dimms 10: 3 Dimms 11: RSVD.				

2.11.8 MC_RD_CRDT_INIT

These registers contain the initial read credits available for issuing memory reads. TAD read credit counters are loaded with the corresponding values at reset and anytime this register is written. BIOS must initialize this register with appropriate values depending on the level of Isoch support in the platform. It is illegal to write this register while TAD is active (has memory requests outstanding), as the write will break TAD's outstanding credit count values.

Register programming rules:

- Total read credits (CRDT_RD + CRDT_RD_HIGH + CRDT_RD_CRIT) must not exceed 31.
- CRDT_RD_HIGH value must correspond to the number of high RTIDs reserved at the IOH.
- CRDT_RD_CRIT value must correspond to the number of critical RTIDs reserved at the IOH.



- CRDT_RD_HIGH + CRDT_RD must be less than or equal to 13 if High or Critical credits are nonzero.
- CRDT_RD_HIGH + CRDT_RD_CRIT must be less than or equal to 8.
- CRDT_RD_CRIT must be less than or equal to 6. Set CRDT_RD to (16 CRDT_RD_CRIT CRDT_RD_HIGH).
- If (Mirroring enabled) then Max for CRDT_RD is 14, otherwise it is 15.
- If (Isoch not enabled) then CRDT_RD_HIGH and CRDT_RD_CRIT are set to 0.

Function Offset:	Device: 3 Function: 0 Offset: 70h Access as a Dword						
Bit	Туре	Reset Value	Description				
20:16	RW	3	CRDT_RD_CRIT. Critical Read Credits.				
12:8	RW	1	CRDT_RD_HIGH. High Read Credits.				
4:0	RW	13	CRDT_RD. Normal Read Credits.				

2.11.9 MC_CRDT_WR_THLD

Memory Controller Write Credit Thresholds. A Write threshold is defined as the number of credits reserved for this priority (or higher) request. It is required that High threshold be greater than or equal to Crit threshold, and that both be lower than the total Write Credit init value. BIOS must initialize this register with appropriate values depending on the level of Isoch support in the platform. The new values take effect immediately upon being written.

Register programming rules:

- CRIT threshold value must correspond to the number of critical RTIDs reserved at the IOH.
- HIGH threshold value must correspond to the sum of critical and high RTIDs reserved at the IOH (which must not exceed 30).
- Set MC_Channel_*_WAQ_PARAMS.ISOCENTRYTHRESHHOLD equal to (31-CRIT).

Function Offset:	Device: 3 Function: 0 Offset: 74h Access as a Dword					
Bit	Туре	Reset Value	Description			
12:8	RW	4	HIGH. High Credit Threshold.			
4:0	RW	3	CRIT. Critical Credit Threshold.			



2.11.10 MC_SCRUBADDR_LO

This register contains part of the address of the last patrol scrub request issued. When running Memtest, the failing address is logged in this register on Memtest errors. Software can write the next address to be scrubbed into this register. Patrol scrubs must be disabled to reliably write this register.

Function Offset:	Device: 3 Function: 0 Offset: 78h Access as a Dword						
Bit	Туре	Reset Value	Description				
29:14	RW	0	PAGE. Contains the row of the last scrub issued. Can be written to specify the next scrub address with STARTSCRUB in the MC_SCRUB_CONTROL register.				
13:0	RW	0	COLUMN. Contains the column of the last scrub issued. Can be written to specify the next scrub address with STARTSCRUB in the MC_SCRUB_CONTROL register.				

2.11.11 MC_SCRUBADDR_HI

This register pair contains part of the address of the last patrol scrub request issued. When running memtest, the failing address is logged in this register on memtest errors. Software can write the next address into this register. Scrubbing must be disabled to reliably read and write this register.

Functio Offset:	Device: 3 Function: 0 Offset: 7Ch Access as a Dword							
Bit	Туре	Reset Value	Description					
12	RO	0	MEMBIST_INPROGRESS. When this bit is asserted by hardware MemTest/MemInit is in progress.					
11	RO	0	MEMBIST_CMPLT. When this bit is asserted by hardware MemTest/MemInit is complete.					
10	WO	0	RESET_MEMBIST_STATUS . When this bit is written to a 1, the status field MEMBIST_CMPLT is cleared.					
9:8	RW	0	CHNL. Can be written to specify the next scrub address with STARTSCRUB in the MC_SCRUB_CONTROL register. This register is not updated with channel address of the last scrub address issued.					
7:6	RW	0	DIMM. Contains the dimm of the last scrub issued. Can be written to specify the next scrub address with STARTSCRUB in the MC_SCRUB_CONTROL register.					
5:4	RW	0	RANK. Contains the rank of the last scrub issued. Can be written to specify the next scrub address with STARTSCRUB in the MC_SCRUB_CONTROL register.					
3:0	RW	0	BANK . Contains the bank of the last scrub issued. Can be written to specify the next scrub address with STARTSCRUB in the MC_SCRUB_CONTROL register.					



2.12 TAD - Target Address Decoder Registers

2.12.1 TAD_DRAM_RULE_0 TAD_DRAM_RULE_1 TAD_DRAM_RULE_2 TAD_DRAM_RULE_3 TAD_DRAM_RULE_4 TAD_DRAM_RULE_5 TAD_DRAM_RULE_6 TAD_DRAM_RULE_7

0

RW

0

TAD DRAM rules. Address map for channel determination within a package. All addresses sent to this HOME agent must hit a valid enabled DRAM_RULE. No error will be generated if they do not and memory aliasing will happen.

Device: Function: 1 80h, 84h, 88h, 8Ch, 90h, 94h, 98h, 9Ch Offset: Access as a Dword Reset Bit Type Description Value 19:6 RW **LIMIT.** DRAM rule top limit address. Must be strictly greater than previous rule, even if this rule is disabled, unless this rule and all following rules are disabled. Lower limit is the previous rule (or 0 if it is the first rule) 2:1 RW MODE. DRAM rule interleave mode. If a DRAM_RULE hits, a 3-bit number is used to index into the corresponding interleave_list to determine which channel the DRAM belongs to. This mode selects how that number is computed. 00: Address bits {8,7,6}. 01: Address bits {8,7,6} XORed with {18,17,16}. 10: Address bit {6}, MOD3(Address[39..6]). (Note 6 is the high order bit)

11: reserved.

ENABLE. Enable for DRAM rule.



2.12.2 TAD_INTERLEAVE_LIST_0
TAD_INTERLEAVE_LIST_1
TAD_INTERLEAVE_LIST_2
TAD_INTERLEAVE_LIST_3
TAD_INTERLEAVE_LIST_4
TAD_INTERLEAVE_LIST_5
TAD_INTERLEAVE_LIST_6

TAD DRAM package assignments. When the corresponding DRAM_RULE hits, a 3-bit number (determined by mode) is used to index into the Interleave_List Branches to determine which channel the DRAM request belongs to.

Device: 3 Function: 1 Offset: C0h, C4h, C8h, CCh, D0h, D4h, D8h, DCh

TAD_INTERLEAVE_LIST_7

Bit	Type	Reset Value	Description
29:28	RW	-	Logical Channel7. Index 111 of the Interleave List. Bits determined from the matching TAD_DRAM_RULE mode.
			00 – Logical channel 0 01 – Logical channel 1 10 – Logical channel 2 11 – Reserved
25:24	RW	-	Logical Channel6. Index 110 of the Interleave List. Bits determined from the matching TAD_DRAM_RULE mode.
			00 – Logical channel 0 01 – Logical channel 1 10 – Logical channel 2 11 – Reserved
21:20	RW	-	Logical Channel5. Index 101 of the Interleave List. Bits determined from the matching TAD_DRAM_RULE mode.
			00 – Logical channel 0 01 – Logical channel 1 10 – Logical channel 2 11 – Reserved
17:16	RW	-	Logical Channel4. Index 100 of the Interleave List. Bits determined from the matching TAD_DRAM_RULE mode.
			00 – Logical channel 0 01 – Logical channel 1 10 – Logical channel 2 11 – Reserved
13:12	RW	-	Logical Channel3. Index 011 of the Interleave List. Bits determined from the matching TAD_DRAM_RULE mode.
			00 – Logical channel 0 01 – Logical channel 1 10 – Logical channel 2 11 – Reserved



Device: Function: 1

Offset: Coh, C4h, C8h, CCh, D0h, D4h, D8h, DCh Access as a Dword

Bit	Туре	Reset Value	Description
9:8	RW	-	Logical Channel2. Index 010 of the Interleave List. Bits determined from the matching TAD_DRAM_RULE mode. 00 – Logical channel 0 01 – Logical channel 1 10 – Logical channel 2 11 – Reserved
5:4	RW	-	Logical Channel1. Index 001 of the Interleave List. Bits determined from the matching TAD_DRAM_RULE mode. 00 – Logical channel 0 01 – Logical channel 1 10 – Logical channel 2 11 – Reserved
1:0	RW	-	Logical ChannelO. Index 000 of the Interleave List. Bits determined from the matching TAD_DRAM_RULE mode. 00 – Logical channel 0 01 – Logical channel 1 10 – Logical channel 2 11 – Reserved

Integrated Memory Controller RAS Registers 2.13

MC_SSRCONTROL 2.13.1

Scrubbing control. This register allows the enabling of patrol scrubbing and demand scrubbing.

Device: Function: 2 Offset: 48h Access as a Dword

Bit	Туре	Reset Value	Description
14:7	RW	0	SCRATCHPAD. This field is available as a scratchpad for Scrubbing operations.
6	RW	0	DEMAND_SCRUB_EN. Enable Demand Scrubs.
1:0	RW	0	SSR_MODE. Patrol scrub enable. 00: Disable Patrol Scrub 01: Enable Patrol Scrub 10: RSVD.



2.13.2 MC_SCRUB_CONTROL

Contains the Scrub control parameters and status.

Device: 3 Function: 2 Offset: 4Ch Access as a Dword				
Bit	Туре	Reset Value	Description	
26	RW	0	SCRUBISSUED. When Set, the scrub address registers contain the last scrub address issued.	
25	RW	0	ISSUEONCE. When Set, the patrol scrub engine will issue the address in the scrub address registers only once and stop.	
24	RW	0	STARTSCRUB. When Set, the Patrol scrub engine will start from the address in the scrub address registers. Once the scrub is issued this bit is reset.	
23:0	RW	0	SCRUBINTERVAL. Defines the interval in DCLKS between patrol scrub requests. The calculation for this register to get a scrub to every line in 24 hours is: ((36400)/(memory capacity/64))/cycle time of DCLK.	

For 512MB at DDR3-800: (36400/((2^29)/64))/1.25 x 10^-9 = 3471374 = 0x34F80E.

2.13.3 MC_RAS_ENABLES

RAS enables register.

Function: Offset:	Function: 2				
Bit	Туре	Reset Value	Description		
1	RW	0	LOCKSTEPEN. Lockstep enable. When set, channel 0 and 1 are tied together in lockstep. The channel mapper register must be appropriately programmed as well.		
0	RW	0	MIRROREN. Mirror mode enable. The channel mapping must be set up before this bit will have an effect on Integrated Memory Controller operation. This changes the error policy and alternates reads between channels.		

2.13.4 MC_RAS_STATUS

RAS status register.

Offset:	Function: 2				
Bit	Туре	Reset Value	Description		
0	RW	0	REDUNDANCY_LOSS. One channel of a mirrored pair had an uncorrectable error and redundancy has been lost. This bit is set by hardware and must be cleared by software performing a channel reset to regain mirrored status.		



2.13.5 MC_SSRSTATUS

Provides the status of the operation specified in MC_SSRCONTROL.SSR_Mode.

Device: 3 Function: 2 Offset: 60h Access as a Dword				
Bit	Туре	Reset Value	Description	
1	RO	0	INPROGRESS. Patrol Scrub operation in progress. This bit is set by hardware once scrubbing operation has started. It is cleared once operation is complete or fails.	
0	RO	0	CMPLT. Patrol Scrub operation complete. Set by hardware once operation is complete. Bit is cleared by hardware when a new operation is enabled.	

2.13.6 MC_COR_ECC_CNT_0 MC_COR_ECC_CNT_1 MC_COR_ECC_CNT_2 MC_COR_ECC_CNT_3

MC_COR_ECC_CNT_3
MC_COR_ECC_CNT_4

MC_COR_ECC_CNT_5

Per Dimm counters of correctable ECC errors. The register organization is as follows. For example, if there are three DIMMS on the channel, MC_COR_ECC_CNT_0 contains the error counter information for DIMM 0 and DIMM1 on Channel 0. MC_COR_ECC_CNT_1 contains the error counter information for DIMM2 on Channel 0.

The lower 16-bit of MC_COR_ECC_CNT_0 contains the errors for DIMM0 and the upper 16-bit field contains the errors for DIMM1. The lower 16-bit of MC_COR_ECC_CNT_1 contains the errors for DIMM2. The upper 16 bits of MC_COR_ECC_CNT_1 are not used. The same organization applies to Channel 1 and Channel 2.

MC_COR_ECC_CNT_0 : Channel 0 Dimm 0/1
MC_COR_ECC_CNT_1 : Channel 0 Dimm 2/Rsvd
MC_COR_ECC_CNT_2 : Channel 1 Dimm 0/1
MC_COR_ECC_CNT_3 : Channel 1 Dimm 2/Rsvd
MC_COR_ECC_CNT_4 : Channel 2 Dimm 0/1
MC_COR_ECC_CNT_5 : Channel 2 Dimm 2/Rsvd

If there are one or two DIMMS on the channel, the lower 16-bit field of MC_COR_ECC_CNT_0 contains the errors for DIMMO on Ranks 0 and 1 on Channel 0. The upper 16-bit field contains information for DIMMO on Ranks 2 and 3 for a quad rank DIMM. The same organization follows for DIMM1 for MC_COR_ECC_CNT_1.

MC_COR_ECC_CNT_0: Channel 0 Dimm 0 Ranks 0,1/2,3 MC_COR_ECC_CNT_1: Channel 0 Dimm 1 Ranks 0,1/2,3 MC_COR_ECC_CNT_2: Channel 1 Dimm 0 Ranks 0,1/2,3 MC_COR_ECC_CNT_3: Channel 1 Dimm 1 Ranks 0,1/2,3 MC_COR_ECC_CNT_4: Channel 2 Dimm 0 Ranks 0,1/2,3 MC_COR_ECC_CNT_5: Channel 2 Dimm 1 Ranks 0,1/2,3



Device: 3 Function: 2 Offset: 80h, 84h, 88h, 8Ch, 90h, 94h Access as a Dword					
Bit	Туре	Reset Value	Description		
31	RW	0	DIMM1_ERR_OVERFLOW. Correctable error overflow on DIMM 1/Rsvd.		
30:16	RW	0	DIMM1_COR_ERR. Correctable error count from DIMM 1/Rsvd.		
15	RW	0	DIMMO_ERR_OVERFLOW. Correctable error overflow on DIMM 0/2.		
14:0	RW	0	DIMMO_COR_ERR. Correctable error count from DIMM 0/2.		

2.14 Integrated Memory Controller Test Registers

2.14.1 MC_TEST_ERR_RCV1

Memory test error recovery and detection. This is another address to access COR_ECC_CNT register. This is the ecc error information for DIMM 2.

Function Offset:	Device: 3 Function: 4 Offset: 60h Access as a Dword				
Bit	Туре	Reset Value	Description		
15	RW	0	DIMM2_ERR_OVERFLOW. Correctable error overflow on DIMM 2.		
14:0	RW	0	DIMM2_COR_ERR. Correctable error count from DIMM 2.		

2.14.2 MC_TEST_ERR_RCVO

Memory test error recovery and detection. This is another address to access COR_ECC_CNT register. This is the ecc error information for DIMM 0 and DIMM 1.

Function Offset:	Device: 3 Function: 4 Offset: 64h Access as a Dword				
Bit	it Type Reset Value Description				
31	RW	0	DIMM1_ERR_OVERFLOW. Correctable error overflow on DIMM 1.		
30:16	RW	0	DIMM1_COR_ERR. Correctable error count from DIMM 1.		
15	RW	0	DIMMO_ERR_OVERFLOW. Correctable error overflow on DIMM 0.		
14:0	RW	0	DIMMO_COR_ERR. Correctable error count from DIMM 0.		



2.14.3 MC_TEST_PH_CTR

Memory test Control Register

Device: 3 Function: 4 Offset: 6Ch Access as a Dword				
Bit	Туре	Reset Value	Description	
10:8	RW	0	INIT_MODE: Initialization Mode Idle: 000 Loopback: 001 Memtest: 110 Meminit: 111	

2.14.4 MC_TEST_PH_PIS

Memory test physical layer initialization status

Function Offset:	Device: 3 Function: 4 Offset: 80h Access as a Dword				
Bit	Туре	Reset Value	Description		
29	RO	-	GLOBAL_ERROR: Indication that an error was detected during a memory test.		

2.14.5 MC_TEST_PAT_GCTR

Pattern Generator Control

Offset:	Function: 4					
Bit	Туре	Reset Value	Description			
28:24	RW	6	EXP_LOOP_CNT: Sets the length of the test, defined as 2^(EXP_LOOP_CNT)			
21	RW	0	ERROR_COUNT_STALL: Masks all detected errors until cleared			
20	RW1S	0	STOP_TEST: Force exit from Loopback.Pattern			
19	RW	0	DRIVE_DC_ZERO: Drive 0 on lanes with PAT_DCD asserted			
13:12	RW	0	PATBUF_WD_SEL: Select word within pattern buffer to be written			
10:9	RW	0	PATBUF_SEL: Select which pattern buffer will be written when MC_TEST_PAT_BA is written			
5	RW	0	IGN_REM_PARAM: Slave will ignore remote parameters transmitted in Loopback.Marker			
4	RW	0	ENABLE_LFSR2: Use scrambled output of Pattern Buffer 2			
3	RW	0	ENABLE_LFSR1: Use scrambled output of Pattern Buffer 1			
2	RW	1	ENABLE_AUTOINV : Inversion pattern register will rotate automatically once per loop			
1	RW	0	STOP_ON_ERROR: Exit Loopback.Pattern upon first detected error			
0	RW1S	0	START_TEST: Initiate transition to Loopback.Pattern			



2.14.6 MC_TEST_PAT_BA

Memory Test Pattern Generator Buffer

Function Offset:	Device: 3 Function: 4 Offset: B0h Access as a Dword			
Bit	Туре	Reset Value	Description	
31:0	RW	0	DATA: 32-bit window into the indirectly-addressed pattern buffer register space.	

2.14.7 MC_TEST_PAT_IS

Memory test pattern inversion selection register

Function Offset:	Device: 3 Function: 4 Offset: BCh Access as a Dword		
Bit	Туре	Reset Value	Description
7:0	RW	1	LANE_INVERT: Per-lane selection of normal or inverted pattern

2.14.8 MC_TEST_PAT_DCD

Memory test DC drive register

Device: Function Offset: Access a	_	rd	
Bit	Туре	Reset Value	Description
7:0	RW	0	LANE_DRIVE_DC: Per-lane selection of DC pattern



2.15 Integrated Memory Controller Channel Control Registers

2.15.1 MC_CHANNEL_O_DIMM_RESET_CMD MC_CHANNEL_1_DIMM_RESET_CMD MC_CHANNEL_2_DIMM_RESET_CMD

Integrated Memory Controller DIMM reset command register. This register is used to sequence the reset signals to the DIMMs.

4, 5, 6 Device: Function: 0 Offset: 50h Access as a Dword Reset Type Bit Description Value RW O BLOCK_CKE. When set, CKE will be forced to be deasserted. 2 1 RW 0 ASSERT_RESET. When set, Reset will be driven to the DIMMs. 0 WO RESET. Reset the DIMMs. Setting this bit will cause the Integrated Memory 0 Controller DIMM Reset state machine to sequence through the reset sequence using the parameters in MC_DIMM_INIT_PARAMS.

2.15.2 MC_CHANNEL_O_DIMM_INIT_CMD MC_CHANNEL_1_DIMM_INIT_CMD MC_CHANNEL_2_DIMM_INIT_CMD

Integrated Memory Controller DIMM initialization command register. This register is used to sequence the channel through the physical layer training required for DDR.

Device: 4, 5, 6
Function: 0
Offset: 54h
Access as a Dword

Bit Type Reset Value

Description

17 WO 0 ASSERT_CKE. When set, all CKE will be asserted. Write a 0 to this bit to stop the init block from driving CKE. This bit has no effect once MC_CONTROL.INIT_DONE is set. This bit must be used during INITIALIZATION only and be cleared out before MC_CONTROL.INIT_DONE is set. This bit must not be asserted during initialization for S3 resume.

16 RW 0 DO_RCOMP. When set, an RCOMP will be issued to the rank specified in the RANK field.

			the init block from driving CKE. This bit has no effect once MC_CONTROL.INIT_DONE is set. This bit must be used during INITIALIZATION only and be cleared out before MC_CONTROL.INIT_DONE is set. This bit must not be asserted during initialization for S3 resume.
16	RW	0	DO_RCOMP. When set, an RCOMP will be issued to the rank specified in the RANK field.
15	RW	0	DO_ZQCL . When set, a ZQCL will be issued to the rank specified in the RANK field.
14	RW	0	WRDQDQS_MASK. When set, the Write DQ-DQS training will be skipped.
13	RW	0	WRLEVEL_MASK. When set, the Write Levelization step will be skipped.
12	RW	0	RDDQDQS_MASK. When set, the Read DQ-DQS step will be skipped.
11	RW	0	RCVEN_MASK. When set, the RCVEN step will be skipped.
10	WO	0	RESET_FIFOS. When set, the TX and RX FIFO pointers will be reset at the next BCLK edge. The Bubble Generators will also be reset.
9	RW	0	IGNORE_RX. When set, the read return datapath will ignore all data coming from the RX FIFOS. This is done by gating the early valid bit.
8	RW	0	STOP_ON_FAIL . When set along with the AUTORESETDIS not being set, the phyinit FSM will stop if a step has not completed after timing out.



Device: 4, 5, 6 Function: 0 Offset: 54h Access as a Dword

					
Bit	Туре	Reset Value	Description		
7:5	RW	0	RANK. The rank currently being tested. The Phylnit FSM must be sequenced for every rank present in the channel. The rank value is set to the rank being trained.		
4:2	RW	0	NXT_PHYINIT_STATE. Set to sequence the physical layer state machine. 000: IDLE 001: RD DQ-DQS 010: RcvEn Bitlock 011: Write Level 100: WR DQ-DQS.		
1	RW	0	AUTODIS. Disables the automatic training where each step is automatically incremented. When set, the physical layer state machine must be sequenced with software. The training FSM must be sequenced using the NXT_PHYINIT_STATE field.		
0	WO	0	TRAIN. Cycle through the training sequence for the rank specified in the RANK field.		

2.15.3 MC_CHANNEL_O_DIMM_INIT_PARAMS MC_CHANNEL_1_DIMM_INIT_PARAMS MC_CHANNEL_2_DIMM_INIT_PARAMS

Initialization sequence parameters are stored in this register. Each field is 2ⁿ count.

Bits [24:22] control the logical to physical rank mapping. The Integrated Memory Controller needs to know the location of different ranks in order to drive the proper chip selects (CS#) and Clock Enable (CKE). Each valid combination results in a different mapping of CS or CKE connections to the logical ranks. The table below summarizes the supported combinations.

3DP[24]	SQRP[23]	QRP[22]	Notes
1	0	0	3 DIMMs Per Channel (60DT/6CS)
0	1	1	Single Quad Rank (20DT/4CS)
0	0	1	Quad Rank plus another DIMM (40DT/8CS)
0	0	0	All other configurations.



Device: 4, 5, 6 Function: 0 Offset: 58h Access as a Dword

Bit	Туре	Reset Value	Description
26	RW	0	DIS_3T. When set, 3T mode will not be enabled as a part of the MRS write to the RDIMM. The RC2 write to switch to 3T and back to 1T timing before and after an MRS write will not be done if the bit is set. This bit should be set if the RDIMM supports auto MRS cycles where the dimm takes care of the 3T switching on MRS writes.
25	RW	0	DIS_AI. When set, address inversion will not be disabled as a part of the MRS write to the RDIMM. The RCO write to disable and enable address inversion will not be done. This bit should be set if the RDIMM supports auto MRS cycles where the dimm takes care of disabling address inversion for MRS writes.
24	RW	0	THREE_DIMMS_PRESENT. Set when channel contains three DIMMs. THREE_DIMMS_PRESENT=1 and QUAD_RANK_PRESENT=1 (or SINGLE_QUAD_RANK_PRESENT=1) are mutually exclusive.
23	RW	0	SINGLE_QUAD_RANK_PRESENT. Set when channel contains a single quad rank DIMM.
22	RW	0	QUAD_RANK_PRESENT. Set when channel contains 1 or 2 quad rank DIMMs.
21:17	RW	15	WRDQDQS_DELAY. Specifies the delay in DCLKs between reads and writes for WRDQDQS training.
16	RW	0	WRLEVEL_DELAY. Specifies the delay used between write CAS indications for write leveling training. 0: 16 DCLKs. 1: 32 DCLKs.
15	RW	0	REGISTERED_DIMM. Set when channel contains registered DIMMs.
14:10	RW	0	PHY_FSM_DELAY. Global timer used for bounding the physical layer training. If the timer expires, the FSM will go to the next step and the counter will be reloaded with PHY_FSM_DELAY value. Units are 2^n dclk.
9:5	RW	0	BLOCK_CKE_DELAY. Delay in ns from when clocks and command are valid to the point CKE is allowed to be asserted. Units are in 2^n uclk.
4:0	RW	0	RESET_ON_TIME. Reset will be asserted for the time specified. Units are 2^n Uclk.



2.15.4 MC_CHANNEL_O_DIMM_INIT_STATUS MC_CHANNEL_1_DIMM_INIT_STATUS MC_CHANNEL_2_DIMM_INIT_STATUS

The initialization state is stored in this register. This register is cleared on a new training command.

Device: 4, 5, 6 Function: 0 Offset: 5Ch Access as a Dword

Access	Access as a Dword					
Bit	Туре	Reset Value	Description			
9	RO	0	RCOMP_CMPLT. When set, indicates that RCOMP command has complete. This bit is cleared by hardware on command issuance and set once the command is complete.			
8	RO	0	INIT_CMPLT. This bit is cleared when a new training command is issued. It is set once the sequence is complete regardless of whether all steps passed or not.			
7	RO	0	ZQCL_CMPLT. When set, indicates that ZQCL command has completed. This bit is cleared by hardware on command issuance and set once the command is complete.			
6	RO	0	WR_DQ_DQS_PASS. Set after a training command when the Write DQ-DQS training step passes. The bit is cleared by hardware when a new training command is sent.			
5	RO	0	WR_LEVEL_PASS. Set after a training command when the write leveling training step passes. The bit is cleared by hardware when a new training command is sent.			
4	RO	0	RD_RCVEN_PASS. Set after a training command when the Read Receive Enable training step passes. The bit is cleared by hardware when a new training command is sent.			
3	RO	0	RD_DQ_DQS_PASS. Set after a training command when the Read DQ-DQS training step passes. The bit is cleared by hardware when a new training command is sent.			
2:0	RO	0	PHYFSMSTATE. The current state of the top level training FSM. 000: IDLE 001: RD DQ-DQS 010: RcvEn Bitlock 011: Write Level 100: WR DQ-DQS			



2.15.5 MC_CHANNEL_0_DDR3CMD MC_CHANNEL_1_DDR3CMD MC_CHANNEL_2_DDR3CMD

DDR3 Configuration Command. This register is used to issue commands to the DIMMs such as MRS commands. The register is used by setting one of the *_VALID bits along with the appropriate address and destination RANK. The command is then issued directly to the DIMM. Care must be taken in using this register as there is no enforcement of timing parameters related to the action taken by a DDR3CMD write. This register has no effect after MC_CONTROL.INIT_DONE is set.

Device: 4, 5, 6 Function: 0 Offset: 60h Access as a Dword

Access	Access as a Dword				
Bit	Туре	Reset Value	Description		
28	RW	0	PRECHARGE_VALID. Indicates current command is for a precharge command.		
27	RW	0	ACTIVATE_VALID. Indicates current command is for an activate command.		
26	RW	0	REG_VALID. Indicates current command is for a registered DIMM config write Bit is cleared by hardware on issuance. This bit applies only to processors supporting registered DIMMs.		
25	RW	0	WR_VALID. Indicates current command is for a write CAS. Bit is cleared by hardware on issuance.		
24	RW	0	RD_VALID. Indicates current command is for a read CAS. Bit is cleared by hardware on issuance.		
23	RW	0	MRS_VALID. Indicates current command is an MRS command. Bit is cleared by hardware on issuance.		
22:20	RW	0	RANK. Destination rank for command.		
19:16	RW	0	MRS_BA. Address bits driven to DDR_BA[2:0] pins for the DRAM command being issued due to a valid bit being set in this register.		
15:0	RW	0	MRS_ADDR. Address bits driven to DDR_MA pins for the DRAM command being issued due to a valid bit being set in this register.		



2.15.6 MC_CHANNEL_O_REFRESH_THROTTLE_SUPPORT MC_CHANNEL_1_REFRESH_THROTTLE_SUPPORT MC_CHANNEL_2_REFRESH_THROTTLE_SUPPORT

This register supports Self Refresh and Thermal Throttle functions.

Device: 4, 5, 6 Function: 0 68h Offset: Access as a Dword Reset Bit Description Type Value INC_ENTERPWRDWN_RATE. Powerdown rate will be increased during 3.2 RW O thermal throttling based on the following configurations 00: tRANKIDLE (Default) 01: 16 10: 24 11: 32 DIS_OP_REFRESH. When set, the refresh engine will not issue opportunistic RW 0 1 0 RW 0 ASR_PRESENT. When set, indicates DRAMs on this channel can support Automatic Self Refresh. If the DRAM is not supporting ASR (Auto Self Refresh), then Self Refresh entry will be delayed until the temperature is below the 2x refresh temperature.

2.15.7 MC_CHANNEL_O_MRS_VALUE_O_1 MC_CHANNEL_1_MRS_VALUE_O_1 MC_CHANNEL_2_MRS_VALUE_O_1

The initial MRS register values for MRO, and MR1 can be specified in this register. These values are used for the automated MRS writes used as a part of the training FSM. The remaining values of the MRS register must be specified here.

Device: 4, 5, 6 Function: 0 70h Offset: Access as a Dword Reset Bit Type Description **Value** 31:16 RW 0 MR1. The values to write to MR1 for A15:A0 15:0 RW 0 MRO. The values to write to MRO for A15:A0.



2.15.8 MC_CHANNEL_0_MRS_VALUE_2 MC_CHANNEL_1_MRS_VALUE_2 MC_CHANNEL_2_MRS_VALUE_2

The initial MRS register values for MR2. This register also contains the values used for RCO and RC2 writes for registered DIMMs. These values are used during the automated training sequence when MRS writes or registered DIMM RC writes are used. The RC fields do not need to be programmed if the address inversion and 3T/1T transitions are disabled.

Device: 4, 5, 6 Function: 0 Offset: 74h Access as a Dword

Bit	Туре	Reset Value	Description
23:20	RW	0	RC2. The values to write to the RC2 register on RDIMMS. This value will be written whenever 3T or 1T timings are enabled by hardware. For this reason bit 1 of the RC2 field (bit 21 of this register) will be controlled by hardware. [23:22] and [20] will be driven with the RDIMM register write command for RC2.
19:16	RW	0	RCO. The values to write to the RCO register on RDIMMS. This value will be written whenever address inversion is enabled or disabled by hardware. For this reason bit 0 of the RCO field (bit 16 of this register) will be controlled by hardware. [19:17] will be driven with the RDIMM register write command for RCO.
15:0	RW	0	MR2. The values to write to MR2 for A15:A0.

2.15.9 MC_CHANNEL_O_RANK_PRESENT MC_CHANNEL_1_RANK_PRESENT MC_CHANNEL_2_RANK_PRESENT

This register provides the rank present vector.

Device: 4, 5, 6 Function: 0 Offset: 7Ch Access as a Dword

Bit	Туре	Reset Value	Description
7:0	RW	0	RANK_PRESENT. Vector that represents the ranks that are present. Each bit represents a logical rank. When two or fewer DIMMs are present, [3:0] represents the four possible ranks in DIMMO and [7:4] represents the ranks that are possible in DIMM1. When three DIMMs are present, then the following applies: [1:0] represents ranks 1:0 in Slot 0 [3:2] represents ranks 3:2 in Slot 1 [5:4] represents ranks 5:4 in Slot 2



2.15.10 MC_CHANNEL_O_RANK_TIMING_A MC_CHANNEL_1_RANK_TIMING_A MC_CHANNEL_2_RANK_TIMING_A

This register contains parameters that specify the rank timing used. All parameters are in DCLK .

Device: 4, 5, 6
Function: 0
Offset: 80h

Access a	Access as a Dword				
Bit	Туре	Reset Value	Description		
28:26	RW	0	tddWrTRd. Minimum delay between a write followed by a read to different DIMMs. 000: 1 001: 2 010: 3 011: 4 100: 5 101: 6 110: 7 111: 8		
25:23	RW	0	tdrWrTRd. Minimum delay between a write followed by a read to different ranks on the same DIMM. 000: 1 001: 2 010: 3 011: 4 100: 5 101: 6 110: 7 111: 8		
22:19	RW	0	tsrWrTRd. Minimum delay between a write followed by a read to the same rank. 0000: 10 0001: 11 0010: 12 0011: 13 0100: 14 0101: 15 0110: 16 0111: 17 1000: 18 1001: 19 1010: 20 1011: 21 1110: 22 1101: RSVD 1111: RSVD		



Device: 4, 5, 6 Function: 0 Offset: 80h Access as a Dword

Bit	Туре	Reset Value	Description
18:15	RW	0	tddRdTWr. Minimum delay between Read followed by a Write to different DIMMs. 0000: 2 0001: 3 0010: 4 0011: 5 0100: 6 0101: 7 0110: 8 0111: 9 1000: 10 1001: 11 1010: 12 1011: 13 1100: 14 1101: RSVD 1111: RSVD
14:11	RW	0	tdrRdTWr. Minimum delay between Read followed by a write to different ranks on the same DIMM. 0000: 2 0001: 3 0010: 4 0011: 5 0100: 6 0101: 7 0110: 8 0111: 9 1000: 10 1001: 11 1010: 12 1011: 13 1100: 14 1101: RSVD 1111: RSVD
10:7	RW	0	tsrRdTWr. Minimum delay between Read followed by a write to the same rank. 0000: RSVD 0001: RSVD 0010: RSVD 0011: 5 0100: 6 0101: 7 0110: 8 0111: 9 1000: 10 1001: 11 1010: 12 1011: 13 1100: 14 1101: RSVD 1111: RSVD



Device: 4, 5, 6 Function: 0 Offset: 80h Access as a Dword

Bit	Туре	Reset Value	Description
6:4	RW	0	tddRdTRd. Minimum delay between reads to different DIMMs. 000: 2 001: 3 010: 4 011: 5 100: 6 101: 7 110: 8 111: 9
3:1	RW	0	tdrRdTRd. Minimum delay between reads to different ranks on the same DIMM. 000: 2 001: 3 010: 4 011: 5 100: 6 101: 7 110: 8 111: 9
0	RW	0	tsrRdTRd. Minimum delay between reads to the same rank. 0: 4 1: 6



2.15.11 MC_CHANNEL_O_RANK_TIMING_B MC_CHANNEL_1_RANK_TIMING_B MC_CHANNEL_2_RANK_TIMING_B

This register contains parameters that specify the rank timing used. All parameters are in DCLK .

Device: 4, 5, 6 Function: 0 Offset: 84h Access as a Dword

Bit	Туре	Reset Value	Description
20:16	RW	0	B2B_CAS_DELAY . Controls the delay between CAS commands in DCLKS. The minimum spacing is 4 DCLKS. Values below 3 have no effect. A value of 0 disables the logic. Setting the value between 3-31 also spaces the read data by 0-29 DCLKS. The value entered is one less than the spacing required, i.e. a spacing of 5 DCLKS between CAS commands (or 1 DCLK on the read data) requires a setting of 4.
15:13	RW	0	tddWrTWr. Minimum delay between writes to different DIMMs. 000: 2 001: 3 010: 4 011: 5 100: 6 101: 7 110: 8 111: 9
12:10	RW	0	tdrWrTWr. Minimum delay between writes to different ranks on the same DIMM. 000: 2 001: 3 010: 4 011: 5 100: 6 101: 7 110: 8 111: 9
9	RW	0	tsrWrTWr. Minimum delay between writes to the same rank. 0: 4 1: 6
8:6	RW	0	tRRD. Specifies the minimum time between activate commands to the same rank.
5:0	RW	0	tFAW. Four Activate Window. Specifies the time window in which four activates are allowed the same rank.



2.15.12 MC_CHANNEL_O_BANK_TIMING MC_CHANNEL_1_BANK_TIMING MC_CHANNEL_2_BANK_TIMING

This register contains parameters that specify the bank timing parameters. These values are in DCLK. The values in these registers are encoded where noted. All of these values apply to commands to the same rank only.

Device: 4, 5, 6 Function: 0 Offset: 88h Access as a Dword Reset Bit Description Type Value 21:17 RW 0 tWTPr. Minimum Write CAS to Precharge command delay. 16:13 tRTPr. Minimum Read CAS to Precharge command delay. RW 0 12.9 0 RW tRCD. Minimum delay between Activate and CAS commands. 8:4 RW 0 tRAS. Minimum delay between Activate and Precharge commands. 3:0 RW 0 tRP. Minimum delay between Precharge command and Activate command.

2.15.13 MC_CHANNEL_O_REFRESH_TIMING MC_CHANNEL_1_REFRESH_TIMING MC_CHANNEL_2_REFRESH_TIMING

This register contains parameters that specify the refresh timings. Units are in DCLK.

Device: 4, 5, 6 Function: 0 Offset: 8Ch Access as a Dword Reset Bit Type Description Value 29:19 RW tTHROT_OPPREF. The minimum time between two opportunistic refreshes. Should be set to tRFC in DCLKS. Zero is an invalid encoding. A value of 1 should be programmed to disable the throttling of opportunistic refreshes. By setting this field to tRFC, current to a single DIMM can be limited to that required to support this scenario without significant performance impact: - 8 panic refreshes in tREFI to one rank - 1 opportunistic refresh every tRFC to another rank - full bandwidth delivered by the third and fourth ranks Platforms that can supply peak currents to the DIMMs should disable opportunistic refresh throttling for max performance. 18:9 RW 0 tREFI_8. Average periodic refresh interval divided by 8. 8:0 RW tRFC. Delay between the refresh command and an activate or refresh command.



2.15.14 MC_CHANNEL_O_CKE_TIMING MC_CHANNEL_1_CKE_TIMING MC_CHANNEL_2_CKE_TIMING

This register contains parameters that specify the CKE timings. All units are in DCLK.

Device: 4, 5, 6 Function: 0 90h Offset: Access as a Dword Reset Description Bit Type Value 31.24 RW O tRANKIDLE. Rank will go into powerdown after it has been idle for the specified number of dclks. tRANKIDLE covers max(txxxPDEN). Minimum value is tWRAPDEN. If CKE is being shared between ranks then both ranks must be idle for this amount of time. A Power Down Entry command will be requested for a rank after this number of DCLKs if no request to the rank is in the MC. 23:21 RW **tXP.** Minimum delay from exit power down with DLL and any valid command. 0 Exit Precharge Power Down with DLL frozen to commands not requiring a locked DLL. Slow exit precharge powerdown is not supported. 20:11 RW 0 tXSDLL. Minimum delay between the exit of self refresh and commands that require a locked DLL. tXS. Minimum delay between the exit of self refresh and commands not 10:3 RW O requiring a DLL.

2.15.15 MC_CHANNEL_O_ZQ_TIMING MC_CHANNEL_1_ZQ_TIMING MC_CHANNEL_2_ZQ_TIMING

RW

2:0

This register contains parameters that specify ZQ timing. All units are DCLK unless otherwise specified. The register encodings are specified where applicable.

tCKE. CKE minimum pulse width.

Device: 4, 5, 6 Function: 0 Offset: 94h Access as a Dword Reset Bit Description **Type** Value 30 RW Parallel_ZQ. Enable ZQ calibration to different ranks in parallel. 29 RW 1 tZQenable. Enable the issuing of periodic ZQCS calibration commands. 16410 28:8 RW **ZQ_Interval**. Nominal interval between periodic ZQ calibration in increments of maintenance counter intervals. 7:5 RW 4 tZQCS. Specifies ZQCS cycles in increments of 16. This is the minimum delay between ZQCS and any other command. This register should be programmed to at least 64/16=4='100' to conform to the DDR3 spec. tZQInit. Specifies ZQInit cycles in increments of 32. This is the minimum delay RW 0 4:0 between ZQCL and any other command. This register should be programmed to at least 512/32=16='10000' to conform to the DDR3 spec.



2.15.16 MC_CHANNEL_O_RCOMP_PARAMS MC_CHANNEL_1_RCOMP_PARAMS MC_CHANNEL_2_RCOMP_PARAMS

This register contains parameters that specify Rcomp timings.

Device: 4, 5, 6 Function: 0 98h Offset: Access as a Dword Reset Bit Description Type Value 16 RW RCOMP_EN. Enable Rcomp. When set, the Integrated Memory Controller will do the programmed blocking of requests and send indications. 15:10 RW 2 RCOMP_CMD_DCLK. Delay from the start of an RCOMP command blocking period in which the command rcomp update is done. Program this field to 15 for all configurations. RCOMP_LENGTH. Number of Dclks during which all commands are blocked for an RCOMP update. Data RCOMP update is done on the last DCLK of this period. 9:4 RW 9

Program this field to 31 for all configurations.

RCOMP_INTERVAL. Duration of interval between Rcomp in increments of

maintenance counter intervals. Register value is (maintenance counter intervals-1). For example, a setting of 0 will produce one maintenance counter

2.15.17 MC_CHANNEL_0_ODT_PARAMS1 MC_CHANNEL_1_ODT_PARAMS1 MC_CHANNEL_2_ODT_PARAMS1

0

interval.

3:0

RW

This register contains parameters that specify ODT timings. All values are in DCLK.

Device: 4, 5, 6 Function: 0 9Ch Offset: Access as a Dword Reset Bit Description **Type** Value RW TAOFD. ODT turn off delay. 26:24 0 MCODT_DURATION. Controls the duration of MC ODT activation. BL/2 + 2. 23:20 RW 6 19:16 RW 4 MCODT_DELAY. Controls the delay from Rd CAS to MC ODT activation. This value is tCAS-1 15:12 RW ODT_RD_DURATION. Controls the duration of Rd ODT activation. This value 5 is BL/2 + 2. 11:8 RW 0 ODT_RD_DELAY. Controls the delay from Rd CAS to ODT activation. This value is tCAS-tWL. ODT_WR_DURATION. Controls the duration of Wr ODT activation. value is 7:4 RW 5 ODT_WR_DELAY. Controls the delay from Wr CAS to ODT activation. This 3:0 RW 0 value is always 0



2.15.18 MC_CHANNEL_0_ODT_PARAMS2 MC_CHANNEL_1_ODT_PARAMS2 MC_CHANNEL_2_ODT_PARAMS2

The FORCE_ODT fields are directly mapped to pins. When the force bits are set, the corresponding pin on the interface is always driven high regardless of the cycle that is being generated. This register is used in debug only and not during normal operation.

Device: 4, 5, 6 Function: 0 Offset: A0h Access as a Dword Reset Bit Description **Type Value** 9 RW 0 MCODT_Writes. Drive MC ODT on reads and writes. 8 0 FORCE_MCODT. Force MC ODT to always be asserted. RW 0 RSVD. 7 RW 6 RW 0 RSVD. 5 RW 0 FORCE_ODT5. Force ODT pin 5 to always be asserted. FORCE_ODT4. Force ODT pin 4 to always be asserted. 0 4 RW FORCE_ODT3. Force ODT pin 3 to always be asserted. 3 RW 0 2 RW 0 FORCE_ODT2. Force ODT pin 2 to always be asserted. RW 0 FORCE_ODT1. Force ODT pin 1 to always be asserted. 1 RW FORCE_ODTO. Force ODT pin 0 to always be asserted. 0 0

2.15.19 MC_CHANNEL_O_ODT_MATRIX_RANK_O_3_RD MC_CHANNEL_1_ODT_MATRIX_RANK_O_3_RD MC_CHANNEL_2_ODT_MATRIX_RANK_O_3_RD

This register contains the ODT activation matrix for RANKS 0 to 3 for Reads.

Device: 4, 5, 6 Function: 0 A4h Offset: Access as a Dword Reset Bit Type Description Value 31:24 RW ODT_RD3. Bit patterns driven out onto ODT pins when Rank3 is read. 1 23:16 RW 1 ODT_RD2. Bit patterns driven out onto ODT pins when Rank2 is read. 15:8 RW 4 ODT_RD1. Bit patterns driven out onto ODT pins when Rank1 is read. 7:0 RW 4 ODT_RDO. Bit patterns driven out onto ODT pins when RankO is read.



2.15.20 MC_CHANNEL_0_ODT_MATRIX_RANK_4_7_RD MC_CHANNEL_1_ODT_MATRIX_RANK_4_7_RD MC_CHANNEL_2_ODT_MATRIX_RANK_4_7_RD

This register contains the ODT activation matrix for RANKS 4 to 7 for Reads.

Device: 4, 5, 6 Function:)0 Offset: A8h Access as a Dword			
Bit	Туре	Reset Value	Description
31:24	RW	1	ODT_RD7. Bit patterns driven out onto ODT pins when Rank7 is read.
23:16	RW	1	ODT_RD6. Bit patterns driven out onto ODT pins when Rank6 is read.
15:8	RW	4	ODT_RD5. Bit patterns driven out onto ODT pins when Rank5 is read.
7:0	RW	4	ODT_RD4. Bit patterns driven out onto ODT pins when Rank4 is read.

2.15.21 MC_CHANNEL_0_ODT_MATRIX_RANK_0_3_WR MC_CHANNEL_1_ODT_MATRIX_RANK_0_3_WR MC_CHANNEL_2_ODT_MATRIX_RANK_0_3_WR

This register contains the ODT activation matrix for RANKS 0 to 3 for Writes.

Device: 4, 5, 6 Function: 0 Offset: ACh Access as a Dword			
Bit	Туре	Reset Value	Description
31:24	RW	9	ODT_WR3. Bit patterns driven out onto ODT pins when Rank3 is written.
23:16	RW	5	ODT_WR2. Bit patterns driven out onto ODT pins when Rank2 is written.
15:8	RW	6	ODT_WR1. Bit patterns driven out onto ODT pins when Rank1 is written.
7:0	RW	5	ODT_WRO. Bit patterns driven out onto ODT pins when Rank0 is written.

2.15.22 MC_CHANNEL_0_ODT_MATRIX_RANK_4_7_WR MC_CHANNEL_1_ODT_MATRIX_RANK_4_7_WR MC_CHANNEL_2_ODT_MATRIX_RANK_4_7_WR

This register contains the ODT activation matrix for RANKS 4 to 7 for Writes.

Device: 4, 5, 6 Function: 0 Offset: B0h Access as a Dword			
Bit	Туре	Reset Value	Description
31:24	RW	9	ODT_WR7. Bit patterns driven out onto ODT pins when Rank7 is written.
23:16	RW	5	ODT_WR6. Bit patterns driven out onto ODT pins when Rank6 is written.
15:8	RW	6	ODT_WR5. Bit patterns driven out onto ODT pins when Rank5 is written.
7:0	RW	5	ODT_WR4. Bit patterns driven out onto ODT pins when Rank4 is written



2.15.23 MC_CHANNEL_O_WAQ_PARAMS MC_CHANNEL_1_WAQ_PARAMS MC_CHANNEL_2_WAQ_PARAMS

This register contains parameters that specify settings for the Write Address Queue.

Device: 4, 5, 6 Function: 0 Offset: B4h Access as a Dword				
Bit	Туре	Reset Value	Description	
29:25	RW	6	PRECASWRTHRESHOLD. Threshold above which Medium-Low Priority reads cannot PRE-CAS write requests.	
24:20	RW	31	PARTWRTHRESHOLD. Threshold used to raise the priority of underfill requests in the scheduler. Set to 31 to disable.	
19:15	RW	31	ISOCEXITTHRESHOLD. Write Major Mode ISOC Exit Threshold. When the number of writes in the WAQ drops below this threshold, the MC will exit write major mode in the presence of a read.	
14:10	RW	31	ISOCENTRYTHRESHOLD. Write Major Mode ISOC Entry Threshold. When the number of writes in the WAQ exceeds this threshold, the MC will enter write major mode in the presence of a read.	
9:5	RW	22	WMENTRYTHRESHOLD. Write Major Mode Entry Threshold. When the number of writes in the WAQ exceeds this threshold, the MC will enter write major mode.	
4:0	RW	22	WMEXITTHRESHOLD. Write Major Mode Exit Threshold. When the number of writes in the WAQ drop below this threshold, the MC will exit write major mode.	

2.15.24 MC_CHANNEL_O_SCHEDULER_PARAMS MC_CHANNEL_1_SCHEDULER_PARAMS MC_CHANNEL_2_SCHEDULER_PARAMS

These are the parameters used to control parameters within the scheduler.

Device: 4, 5, 6 Function: 0 Offset: B8h Access as a Dword			
Bit	Туре	Reset Value	Description
12	RW	1	CS_FOR_CKE_TRANSITION. Specifies if chip select is to be asserted when CKE transitions with PowerDown entry/exit and SelfRefresh exit.
11	RW	0	FLOAT_EN . When set, the address and command lines will float to save power when commands are not being sent out. This setting may not work with RDIMMs.
10:6	RW	7	PRECASRDTHRESHOLD. Threshold above which Medium-Low Priority reads can PRE-CAS write requests.
5	RW	0	DISABLE_ISOC_RBC_RESERVE . When set this bit will prevent any RBC's from being reserved for ISOC.
3	RW	0	ENABLE2N. Enable 2n Timing.
2:0	RW	0	PRIORITYCOUNTER. Upper 3 MSB of 8 bit priority time out counter.



2.15.25 MC_CHANNEL_O_MAINTENANCE_OPS MC_CHANNEL_1_MAINTENANCE_OPS MC_CHANNEL_2_MAINTENANCE_OPS

This register enables various maintenance operations such as ZQ, RCOMP, etc.

Device: 4, 5, 6 Function: 0 BCh Offset: Access as a Dword Reset Bit Description **Type** Value 12.0 RW O MAINT CNTR. Value to be loaded in the maintenance counter. This counter sequences the rate to ZQ, RCOMP in increments of maintenance counter

2.15.26 MC_CHANNEL_O_TX_BG_SETTINGS MC_CHANNEL_1_TX_BG_SETTINGS MC_CHANNEL_2_TX_BG_SETTINGS

These are the parameters used to set the Start Scheduler for TX clock crossing. This is used to send commands to the DIMMs.

The NATIVE RATIO is UCLK multiplier of BCLK = U

ALIEN RATION is DCLK multiplier of BCLK = D

PIPE DEPTH = 8 UCLK (design dependent variable)

MIN SEP DELAY = 670ps (design dependent variable, Internally this is logic delay of FIFO + clock skew between U and D)

TOTAL EFFECTIVE DELAY = PIPE DEPTH * UCLK PERIOD in ps + MIN SEP DELAY

DELAY FRACTION = (TOTAL EFFECTIVE DELAY * D) / (UCLK PERIOD in ps * G.C.D(U,D)

Determine OFFSET MULTIPLE using the equation

FLOOR ((OFFSET MULTIPLE +1) / G.C.D (U,D)) > DELAY FRACTION

OFFSET VALUE = MOD (OFFSET MULTIPLE, U) <= Final answer for OFFSET MULTIPLE

Device: 4, 5, 6 Function: 0 COh Offset: Access as a Dword Reset Bit Type Description Value RW 2 23:16 OFFSET. TX offset setting 15:8 RW 1 ALIENRATIO. Dclk ratio to BCLK. TX Alien Ratio setting 7:0 RW 4 NATIVERATIO. Uclk ratio to BCLK. TX Native Ratio setting.



2.15.27 MC_CHANNEL_O_RX_BGF_SETTINGS MC_CHANNEL_1_RX_BGF_SETTINGS MC_CHANNEL_2_RX_BGF_SETTINGS

These are the parameters used to set the Rx clock crossing BGF.

Device: 4, 5, 6 Function: 0 C8h Offset: Access as a Dword Reset Bit Description Type Value PTRSEP. RX FIFO pointer separation settings. THIS FIELD IS NOT USED BY 26:24 RW 2 HARDWARE. RX Pointer separation can be modified via the round trip setting (larger value causes a larger pointer separation). 23:16 RW 0 OFFSET. RX offset setting. 15:8 RW 1 ALIENRATIO. Qclk to BCLK ratio. RX Alien Ratio setting. 2 NATIVERATIO. Uclk to BCLK ratio. RX Native Ratio setting. 7:0 RW

2.15.28 MC_CHANNEL_O_EW_BGF_SETTINGS MC_CHANNEL_1_EW_BGF_SETTINGS MC_CHANNEL_2_EW_BGF_SETTINGS

These are the parameters used to set the early warning RX clock crossing BGF.

Device: 4, 5, 6
Function: 0
Offset: CCh
Access as a Dword

Bit Type Reset Value Description

15:8 RW 1 ALIENRATIO. Dclk to Bclk ratio. Early warning Alien Ratio setting.

2.15.29 MC_CHANNEL_O_EW_BGF_OFFSET_SETTINGS MC_CHANNEL_1_EW_BGF_OFFSET_SETTINGS MC_CHANNEL_2_EW_BGF_OFFSET_SETTINGS

These are the parameters to set the early warning RX clock crossing BGF.

4, 5, 6 Device: Function: 0 D0h Offset: Access as a Dword Reset Bit **Type** Description Value 15:8 RW EVENOFFSET. Early warning even offset setting. 7:0 RW 0 **ODDOFFSET**. Early warning odd offset setting



2.15.30 MC_CHANNEL_O_ROUND_TRIP_LATENCY MC_CHANNEL_1_ROUND_TRIP_LATENCY MC_CHANNEL_2_ROUND_TRIP_LATENCY

These are the parameters to set the early warning RX clock crossing the Bubble Generator FIFO (BGF) used to go between different clocking domains. These settings provide the gearing necessary to make that clock crossing.

Device: 4, 5, 6 Function: 0 Offset: D4h Access as a Dword Reset Bit Туре Description Value 7:0 RW 0 ROUND_TRIP_LATENCY. Round trip latency for reads. Units are in UCLK. This register must be programmed with the appropriate time for read data to be retuned from the pads after a READ CAS is sent to the DIMMs.

2.15.31 MC_CHANNEL_O_PAGETABLE_PARAMS1 MC_CHANNEL_1_PAGETABLE_PARAMS1 MC_CHANNEL_2_PAGETABLE_PARAMS1

These are the parameters used to control parameters for page closing policies.

Device: 4, 5, 6 Function: 0 Offset: D8h Access as a Dword Reset Bit Type Description **Value** RSVD. 15:8 RW 0 7:0 RW 0 ADAPTIVETIMEOUTCOUNTER. Upper 8 MSBs of a 12-bit counter. This counter adapts the interval between assertions of the page close flag. For a less aggressive page close, the length of the count interval is increased and vice versa for a more aggressive page close policy.

2.15.32 MC_TX_BG_CMD_DATA_RATIO_SETTINGS_CHO MC_TX_BG_CMD_DATA_RATIO_SETTINGS_CH1 MC_TX_BG_CMD_DATA_RATIO_SETTINGS_CH2

Channel Bubble Generator ratios for CMD and DATA.

Device: 4, 5, 6 Function: 0 Offset: **E0h** Access as a Dword Reset Bit Description **Type Value** ALIENRATIO. DCLK to BCLK ratio. 15:8 RW 1 NATIVERATIO. UCLK to BCLK ratio. 7.0 RW 4



2.15.33 MC_TX_BG_CMD_OFFSET_SETTINGS_CHO MC_TX_BG_CMD_OFFSET_SETTINGS_CH1 MC_TX_BG_CMD_OFFSET_SETTINGS_CH2

Integrated Memory Controller Channel Bubble Generator Offsets for CMD FIFO. The Data command FIFOs share the settings for channel 0 across all three channels. The register in Channel 0 must be programmed for all configurations.

Device: 4, 5, 6 Function: 0 Offset: E4h Access as a Dword Reset Bit Description **Type Value** 9:8 RW 0 PTROFFSET. FIFO pointer offset. 7:0 RW BGOFFSET. BG offset.

2.15.34 MC_TX_BG_DATA_OFFSET_SETTINGS_CH0 MC_TX_BG_DATA_OFFSET_SETTINGS_CH1 MC_TX_BG_DATA_OFFSET_SETTINGS_CH2

Integrated Memory Controller Channel Bubble Generator Offsets for DATA FIFO.

Device: 4, 5, 6 Function: 0 E8h Offset: Access as a Dword Reset Bit Description **Type** 16:14 RW RDPTROFFSET. Read FIFO pointer offset. 13:10 RW 0 WRTPTROFFSET. Write FIFO pointer offset. 0 PTROFFSET. FIFO pointer offset. 9:8 RW 7:0 RW 0 **BGOFFSET**. BG offset.



2.16 Integrated Memory Controller Channel Address Registers

2.16.1 MC_DOD_CHO_0 MC_DOD_CHO_1 MC_DOD_CHO_2

Channel 0 DIMM Organization Descriptor Register.

Device: 4 Function: 1 Offset: 48h, 4Ch, 50h Access as a Dword

Access a	Access as a Dword				
Bit	Туре	Reset Value	Description		
12:10	RW	0	RANKOFFSET. Rank Offset for calculating RANK. This corresponds to the first logical rank on the DIMM. The rank offset is always programmed to 0 for the DIMM 0 DOD registers. (DIMM 0 rank offset is always 0.) DIMM 1 DOD rank offset is either 4 for two DIMMs per channel or 2 if there are three DIMMs per channel. DIMM2 DOD rank offset is always 4 as it is only used in three DIMMs per channel case.		
9	RW	0	DIMMPRESENT. DIMM slot is populated.		
8:7	RW	0	NUMBANK. Defines the number of (real, not shadow) banks on these DIMMs. 00: Four-banked 01: Eight-banked 10: Sixteen-banked		
6:5	RW	0	NUMRANK. Number of Ranks. Defines the number of ranks on these DIMMs. 00: Single Ranked 01: Double Ranked 10: Quad Ranked		
4:2	RW	0	NUMROW. Number of Rows. Defines the number of rows within these DIMMs. 000: 2^12 Rows 001: 2^13 Rows 010: 2^14 Rows 011: 2^15 Rows 1100: 2^16 Rows		
1:0	RW	0	NUMCOL. Number of Columns. Defines the number of columns within on these DIMMs. 00: 2^10 columns 01: 2^11 columns 10: 2^12 columns 11: RSVD.		



MC_DOD_CH1_0 2.16.2 MC_DOD_CH1_1 MC_DOD_CH1_2

Channel 1 DIMM Organization Descriptor Register.

Device: 5 Function: 1 Offset: 48h, 4Ch, 50h

Access as a Dword					
Bit	Туре	Reset Value	Description		
12:10	RW	0	RANKOFFSET. Rank Offset for calculating RANK. This corresponds to the first logical rank on the DIMM. The rank offset is always programmed to 0 for the DIMM 0 DOD registers. (DIMM 0 rank offset is always 0.) DIMM 1 DOD rank offset is either 4 for two DIMMs per channel or 2 if there are three DIMMs per channel. DIMM2 DOD rank offset is always 4 as it is only used in three DIMMs per channel case.		
9	RW	0	DIMMPRESENT. DIMM slot is populated.		
8:7	RW	0	NUMBANK. Defines the number of (real, not shadow) banks on these DIMMs. 00: Four-banked 01: Eight-banked 10: Sixteen-banked		
6:5	RW	0	NUMRANK. Number of Ranks. Defines the number of ranks on these DIMMs. 00: Single Ranked 01: Double Ranked 10: Quad Ranked		
4:2	RW	0	NUMROW. Number of Rows. Defines the number of rows within these DIMMs. 000: 2^12 Rows 001: 2^13 Rows 010: 2^14 Rows 011: 2^15 Rows 100: 2^16 Rows		
1:0	RW	0	NUMCOL. Number of Columns. Defines the number of columns within on these DIMMs. 00: 2^10 columns 01: 2^11 columns 10: 2^12 columns 11: RSVD.		



MC_DOD_CH2_0 2.16.3 MC_DOD_CH2_1 MC_DOD_CH2_2

Channel 2 DIMM Organization Descriptor Register.

Device: 6 Function: 1 Offset: 48h, 4Ch, 50h

Access a	Access as a Dword				
Bit	Туре	Reset Value	Description		
12:10	RW	0	RANKOFFSET. Rank Offset for calculating RANK. This corresponds to the first logical rank on the DIMM. The rank offset is always programmed to 0 for the DIMM 0 DOD registers. (DIMM 0 rank offset is always 0.) DIMM 1 DOD rank offset is either 4 for two DIMMs per channel or 2 if there are three DIMMs per channel. DIMM2 DOD rank offset is always 4 as it is only used in three DIMMs per channel case.		
9	RW	0	DIMMPRESENT. DIMM slot is populated.		
8:7	RW	0	NUMBANK. Defines the number of (real, not shadow) banks on these DIMMs. 00: Four-banked 01: Eight-banked 10: Sixteen-banked		
6:5	RW	0	NUMRANK. Defines the number of ranks on these DIMMs. 00: Single Ranked 01: Double Ranked 10: Quad Ranked		
4:2	RW	0	NUMROW. Defines the number of rows within these DIMMs. 000: 2^12 Rows 001: 2^13 Rows 010: 2^14 Rows 011: 2^15 Rows 100: 2^16 Rows		
1:0	RW	0	NUMCOL. Defines the number of columns within on these DIMMs. 00: 2^10 columns 01: 2^11 columns 10: 2^12 columns 11: RSVD		



2.16.4 MC_SAG_CHO_O MC_SAG_CHO_1 MC SAG CHO 2 MC SAG CHO 3 MC_SAG_CHO_4 MC_SAG_CHO_5 MC_SAG_CHO_6 MC_SAG_CHO_7 MC_SAG_CH1_0 MC SAG CH1 1 MC_SAG_CH1_2 MC SAG CH1 3 MC_SAG_CH1_4 MC SAG CH1 5 MC_SAG_CH1_6 MC_SAG_CH1_7 MC SAG CH2 0 MC_SAG_CH2_1 MC SAG CH2 2 MC_SAG_CH2_3 MC_SAG_CH2_4 MC_SAG_CH2_5 MC SAG_CH2_6 MC_SAG_CH2_7

Channel Segment Address Registers. For each of the 8 interleave ranges, they specify the offset between the System Address and the Memory Address and the System Address bits used for level 1 interleave, which should not be translated to Memory Address bits. Memory Address is calculated from System Address and the contents of these registers by the following algorithm:

```
m[39:16] = SystemAddress[39:16] + (sign extend {Offset[23:0]});
m[15:6] = SystemAddress[15:6];
If (Removed[2]) {bit 8 removed};
If (Removed[1]) {bit 7 removed};
If (Removed[0]) {bit 6 removed};
MemoryAddress[36:6] = m[36:6];
```

The table below summarizes the combinations of removed bits and divide-by-3 operations for the various supported interleave configurations. All other combinations are not supported.

Note: If any of bits [8:6] are removed, the higher order bits are shifted down.

Removed [8:6]	Divide-By-3	Interleave
000	0	None
001	0	2-Way
011	0	4-Way
000	1	3-Way
001	1	6-Way



Device: **Function:** Offset: 80h, 84h, 88h, 8Ch, 90h, 94h, 98h, 9Ch Access as a Dword Reset Bit **Type** Description Value 27 RW 0 DIVBY3. This bit indicates the rule is a 3 or 6 way interleave. 26:24 RW 0 REMOVED. These are the bits to be removed after offset subtraction. These bits correspond to System Address [8,7,6]. OFFSET. This value should be subtracted from the current system address to 23:0 0 RW create a contiguous address space within a channel. BITS 9:0 ARE RESERVED AND MUST ALWAYS BE SET TO 0.

2.17 Integrated Memory Controller Channel Rank Registers

MC_RIR_LIMIT_CHO_0 2.17.1 MC_RIR_LIMIT_CHO_1 MC RIR LIMIT CHO 2 MC_RIR_LIMIT_CHO_3 MC_RIR_LIMIT_CHO_4 MC_RIR_LIMIT_CHO_5 MC_RIR_LIMIT_CHO_6 MC_RIR_LIMIT_CHO_7 MC RIR LIMIT CH1 0 MC_RIR_LIMIT_CH1_1 MC RIR LIMIT CH1 2 MC RIR LIMIT CH1 MC_RIR_LIMIT_CH1_4 MC RIR LIMIT CH1 5 MC_RIR_LIMIT_CH1_6 MC_RIR_LIMIT_CH1_7 MC RIR LIMIT CH2 0 MC_RIR_LIMIT_CH2_1 MC_RIR_LIMIT_CH2_2 MC RIR LIMIT CH2 3 MC_RIR_LIMIT_CH2_4 MC_RIR_LIMIT_CH2_5 MC_RIR_LIMIT_CH2_6 MC_RIR_LIMIT_CH2_7



Channel Rank Limit Range Registers.

```
Device: 4
Function: 2
Offset: 40h, 44h, 48h, 4Ch, 50h, 54h, 58h, 5Ch
Access as a Dword

Bit Type Reset Value Description

9:0 RW 0 LIMIT. This specifies the top of the range being mapped to the ranks specified in the MC_RIR_WAY_CH registers. The most significant bits of the lowest address in this range is one greater than the limit field in the RIR register with the next lower index. This field is compared against MA[37:28].
```

```
2.17.2
       MC_RIR_WAY_CHO_0
       MC_RIR_WAY_CHO_1
       MC RIR WAY CHO 2
       MC_RIR_WAY_CHO_
       MC RIR WAY CHO 4
       MC_RIR_WAY_CHO_5
       MC RIR WAY CHO 6
       MC RIR WAY CHO 7
       MC RIR WAY CHO 8
       MC_RIR_WAY_CHO_9
       MC RIR WAY CHO 10
       MC_RIR_WAY_CHO_11
       MC RIR WAY CHO 12
       MC_RIR_WAY_CHO_13
       MC_RIR_WAY_CHO_14
       MC RIR WAY CHO 15
       MC_RIR_WAY_CHO_16
       MC RIR WAY CHO 17
       MC_RIR_WAY_CHO_18
       MC RIR WAY CHO 19
       MC RIR WAY CHO 20
       MC RIR WAY CHO 21
       MC_RIR_WAY_CHO_22
       MC RIR WAY CHO 23
       MC_RIR_WAY_CHO_24
       MC_RIR_WAY_CHO_25
       MC RIR WAY CHO 26
       MC_RIR_WAY_CHO_27
       MC_RIR_WAY_CHO_28
       MC_RIR_WAY_CHO_29
       MC RIR WAY CHO 30
       MC_RIR_WAY_CHO_31
```

Channel Rank Interleave Way Range Registers. These registers allow the user to define the ranks and offsets that apply to the ranges defined by the LIMIT in the MC_RIR_LIMIT_CH registers. The mappings are as follows:

RIR_LIMIT_CH{chan}[0] -> RIR_WAY_CH{chan}[3:0]



```
RIR_LIMIT_CH{chan}[1] -> RIR_WAY_CH{chan}[7:6]

RIR_LIMIT_CH{chan}[2] -> RIR_WAY_CH{chan}[11:10]

RIR_LIMIT_CH{chan}[3] -> RIR_WAY_CH{chan}[15:14]

RIR_LIMIT_CH{chan}[4] -> RIR_WAY_CH{chan}[19:18]

RIR_LIMIT_CH{chan}[5] -> RIR_WAY_CH{chan}[23:22]

RIR_LIMIT_CH{chan}[6] -> RIR_WAY_CH{chan}[27:26]

RIR_LIMIT_CH{chan}[7] -> RIR_WAY_CH{chan}[31:28]
```

Device: 4
Function: 2
Offset: 80h, 84h, 88h, 8Ch, 90h, 94h, 98h, 9Ch, A0h, A4h, A8h, ACh, B0h, B4h, B8h, BCh, C0h, C4h, C8h, CCh, D0h, D4h, D8h, DCh, E0h, E4h, E8h, ECh, F0h, F4h, F8h, FCh
Access as a Dword

Bit	Туре	Reset Value	Description
13:4	RW	0	OFFSET. Defines the offset used in the rank interleave. This is a 2's complement value.
3:0	RW	0	RANK. Defines which rank participates in WAY(n). If MC_CONTROL.CLOSED_PAGE=1, this field defines the DRAM rank selected when MemoryAddress[7:6]=(n). If MC_CONTROL.CLOSED_PAGE=0, this field defines which rank is selected when MemoryAddress[13:12]=(n). (n) is the instantiation of the register. This field is organized by physical rank. Bits [3:2] are the encoded DIMM ID(slot). Bits [1:0] are the rank within that DIMM.

2.17.3 MC RIR WAY CH1 0 MC_RIR_WAY_CH1_1 MC RIR WAY CH1 2 MC RIR WAY CH1 MC_RIR_WAY_CH1_4 MC RIR WAY CH1 5 MC RIR WAY CH1 MC_RIR_WAY_CH1_7 MC RIR WAY CH1 8 MC_RIR_WAY_CH1_9 MC_RIR_WAY_CH1_10 MC RIR WAY CH1 11 MC_RIR_WAY_CH1_12 MC RIR WAY CH1 13 MC_RIR_WAY_CH1_14 MC RIR WAY CH1 15 MC RIR WAY CH1 16 MC RIR WAY CH1 17 MC_RIR_WAY_CH1_18 MC RIR WAY CH1 19 MC_RIR_WAY_CH1_20 MC_RIR_WAY_CH1_21 MC_RIR_WAY_CH1_22

MC_RIR_WAY_CH1_23



```
MC_RIR_WAY_CH1_24
MC_RIR_WAY_CH1_25
MC_RIR_WAY_CH1_26
MC_RIR_WAY_CH1_27
MC_RIR_WAY_CH1_28
MC_RIR_WAY_CH1_29
MC_RIR_WAY_CH1_30
MC_RIR_WAY_CH1_31
```

Device:

Channel Rank Interleave Way Range Registers. These registers allow the user to define the ranks and offsets that apply to the ranges defined by the LIMIT in the MC_RIR_LIMIT_CH registers. The mappings are as follows:

```
RIR_LIMIT_CH{chan}[0] -> RIR_WAY_CH{chan}[3:0]
RIR_LIMIT_CH{chan}[1] -> RIR_WAY_CH{chan}[7:6]
RIR_LIMIT_CH{chan}[2] -> RIR_WAY_CH{chan}[11:10]
RIR_LIMIT_CH{chan}[3] -> RIR_WAY_CH{chan}[15:14]
RIR_LIMIT_CH{chan}[4] -> RIR_WAY_CH{chan}[19:18]
RIR_LIMIT_CH{chan}[5] -> RIR_WAY_CH{chan}[23:22]
RIR_LIMIT_CH{chan}[6] -> RIR_WAY_CH{chan}[27:26]
RIR_LIMIT_CH{chan}[7] -> RIR_WAY_CH{chan}[31:28]
```

Function: 2
Offset: 80h, 84h, 88h, 8Ch, 90h, 94h, 98h, 9Ch, A0h, A4h, A8h, ACh, B0h, B4h, B8h, BCh, C0h, C4h, C8h, CCh, D0h, D4h, D8h, DCh, E0h, E4h, E8h, ECh, F0h, F4h, F8h, FCh Access as a Dword

Bit	Туре	Reset Value	Description
13:4	RW	0	OFFSET. Defines the offset used in the rank interleave. This is a 2's complement value.
3:0	RW	0	RANK. Defines which rank participates in WAY(n). If MC_CONTROL.CLOSED_PAGE=1, this field defines the DRAM rank selected when MemoryAddress[7:6]=(n). If MC_CONTROL.CLOSED_PAGE=0, this field defines which rank is selected when MemoryAddress[13:12]=(n). (n) is the instantiation of the register. This field is organized by physical rank. Bits [3:2] are the encoded DIMM ID(slot). Bits [1:0] are the rank within that DIMM.



```
2.17.4
       MC_RIR_WAY_CH2_0
       MC_RIR_WAY_CH2_1
       MC RIR WAY CH2 2
       MC RIR WAY CH2 3
       MC_RIR_WAY_CH2_4
       MC_RIR_WAY_CH2_5
       MC_RIR_WAY_CH2_6
       MC RIR WAY CH2 7
       MC_RIR_WAY_CH2_8
       MC RIR WAY CH2 9
       MC RIR WAY CH2 10
       MC RIR WAY CH2 11
       MC RIR WAY CH2 12
       MC RIR WAY CH2 13
       MC_RIR_WAY_CH2_14
       MC RIR WAY CH2 15
       MC RIR WAY CH2 16
       MC_RIR_WAY_CH2_17
       MC RIR WAY CH2 18
       MC_RIR_WAY_CH2_19
       MC RIR WAY CH2 20
       MC RIR WAY CH2 21
       MC RIR WAY CH2 22
       MC_RIR_WAY_CH2_23
       MC RIR WAY CH2 24
       MC RIR WAY CH2 25
       MC_RIR_WAY_CH2_26
       MC RIR WAY CH2 27
       MC RIR WAY CH2 28
       MC_RIR_WAY_CH2_29
       MC RIR WAY CH2 30
       MC_RIR_WAY_CH2_31
```

Channel Rank Interleave Way Range Registers. These registers allow the user to define the ranks and offsets that apply to the ranges defined by the LIMIT in the MC_RIR_LIMIT_CH registers. The mappings are as follows:

```
RIR_LIMIT_CH{chan}[0] -> RIR_WAY_CH{chan}[3:0]

RIR_LIMIT_CH{chan}[1] -> RIR_WAY_CH{chan}[7:6]

RIR_LIMIT_CH{chan}[2] -> RIR_WAY_CH{chan}[11:10]

RIR_LIMIT_CH{chan}[3] -> RIR_WAY_CH{chan}[15:14]

RIR_LIMIT_CH{chan}[4] -> RIR_WAY_CH{chan}[19:18]

RIR_LIMIT_CH{chan}[5] -> RIR_WAY_CH{chan}[23:22]

RIR_LIMIT_CH{chan}[6] -> RIR_WAY_CH{chan}[27:26]

RIR_LIMIT_CH{chan}[7] -> RIR_WAY_CH{chan}[31:28]
```



Device: Function: 2

Offset: 80h, 84h, 88h, 8Ch, 90h, 94h, 98h, 9Ch, A0h, A4h, A8h, ACh, B0h, B4h, B8h, BCh, C0h, C4h, C8h, CCh, D0h, D4h, D8h, DCh, E0h, E4h, E8h, ECh, F0h, F4h, F8h, FCh

Bit	Туре	Reset Value	Description
13:4	RW	0	OFFSET. Defines the offset used in the rank interleave. This is a 2's complement value.
3:0	RW	0	RANK. Defines which rank participates in WAY(n). If MC_CONTROL.CLOSED_PAGE=1, this field defines the DRAM rank selected when MemoryAddress[7:6]=(n). If MC_CONTROL.CLOSED_PAGE=0, this field defines which rank is selected when MemoryAddress[13:12]=(n). (n) is the instantiation of the register. This field is organized by physical rank. Bits [3:2] are the encoded DIMM ID(slot). Bits [1:0] are the rank within that DIMM.

Memory Thermal Control 2.18

2.18.1 MC_THERMAL_CONTROLO MC_THERMAL_CONTROL1 MC_THERMAL_CONTROL2

Controls for the Integrated Memory Controller thermal throttle logic for each channel.

Device: 4, 5, 6 Function: 3 Offset: 48h Access as a Dword

Bit	Туре	Reset Value	Description
2	RW	1	APPLY_SAFE. Enable the application of safe values while MC_THERMAL_PARAMS_B.SAFE_INTERVAL is exceeded.
1:0	RW	0	THROTTLE_MODE. Selects throttling mode. When in lockstep mode, this field should only be non-zero for Channelo. 0: Throttle disabled 1: Open Loop: Throttle when Virtual Temperature is greater than MC_THROTTLE_OFFSET. 2: Closed Loop: Throttle when MC_CLOSED_LOOP.THROTTLE_NOW is set. 3: Closed Loop: Throttle when MC_DDR_THERM_COMMAND.THROTTLE is set and the MC_DDR_THERM pin is asserted OR OLTT will be implemented (Condition 1).



2.18.2 MC_THERMAL_STATUS0 MC_THERMAL_STATUS1 MC_THERMAL_STATUS2

Status registers for the thermal throttling logic for each channel.

Device: 4, 5, 6 Function: 3 4Ch Offset: Access as a Dword Reset Bit Description Type Value **CYCLES_THROTTLED.** The number of throttle cycles, in increments of 256 Dclks, triggered in any rank in the last SAFE_INTERVAL number of ZQs. 29:4 RO 0 3:0 RO 0 RANK_TEMP. The bit specifies whether the rank is above throttling threshold.

2.18.3 MC_THERMAL_DEFEATURE0 MC_THERMAL_DEFEATURE1 MC_THERMAL_DEFEATURE2

Thermal Throttle defeature register for each channel.

4, 5, 6 Device: Function: 3 Offset: 50h Access as a Dword Reset Bit Type Description Value Λ THERM_REG_LOCK. When set, no further modification of all thermal throttle O RW1S registers are allowed. This bit must be set to the same value for all channels.

2.18.4 MC_THERMAL_PARAMS_A0 MC_THERMAL_PARAMS_A1 MC_THERMAL_PARAMS_A2

Parameters used by Open Loop Throughput Throttling (OLTT) and Closed Loop Thermal Throttling (CLTT).

4, 5, 6 Device: Function: 3 60h Offset: Access as a Dword Reset Bit Description **Type** Value CKE_ASSERT_ENERGY. Energy of having CKE asserted when no command is 31:24 RW 0 issued. CKE_DEASSERT_ENERGY. Energy of having CKE de-asserted when no 23:16 RW 0 command is issued. WRCMD_ENERGY. Energy of a write including data transfer. 15:8 RW 0 7:0 RW 0 RDCMD_ENERGY. Energy of a read including data transfer.



2.18.5 MC_THERMAL_PARAMS_B0 MC_THERMAL_PARAMS_B1 MC_THERMAL_PARAMS_B2

Parameters used by the thermal throttling logic.

Device: 4, 5, 6 Function: 3 Offset: 64h Access as a Dword

Bit	Туре	Reset Value	Description			
31:26	RW	1	SAFE_INTERVAL. Safe values for cooling coefficient and duty cycle will be applied while the SAFE_INTERVAL is exceeded. This interval is the number of ZQ intervals since the last time the MC_COOLING_COEF or MC_CLOSED_LOOP registers have been written. A register to write to MC_COOLING_COEF or MC_CLOSED_LOOP will re-apply the normal MC_COOLING_COEF and MC_CLOSED_LOOP.MIN_THROTTLE_DUTY_CYC values. The register value written need not be different; writing the current value will suffice. The MC_THERMAL_STATUS.CYCLES_THROTTLED field is reloaded when the number of ZQ intervals exceeds this value. This field must not be programmed to 0; this value is illegal.			
25:16	RW	255	SAFE_DUTY_CYC. This value replaces MC_CLOSED_LOOP.MIN_THROTTLE_DUTY_CYC while the MC_THERMAL_PARAMS_B.SAFE_INTERVAL is exceeded.			
15:8	RW	1	SAFE_COOL_COEF. This value replaces MC_COOLING_COEF while the THERMAL_PARAMS_B.SAFE_INTERVAL is exceeded.			
7:0	RW	0	ACTCMD_ENERGY. Energy of an Activate/Precharge Cycle.			

2.18.6 MC_COOLING_COEF0 MC_COOLING_COEF1 MC_COOLING_COEF2

Heat removed from DRAM 8 DCLKs. This should be scaled relative to the per command weights and the initial value of the throttling threshold. This includes idle command and refresh energies. If 2X refresh is supported, the worst case of 2X refresh must be assumed.

When there are more than 4 ranks attached to the channel, the thermal throttle logic is shared.

Device: 4, 5, 6 Function: 3 Offset: 80h Access as a Dword

Bit	Туре	Reset Value	Description
31:24	RW	255	RANK3. Rank 3 Cooling Coefficient.
23:16	RW	255	RANK2. Rank 2 Cooling Coefficient.
15:8	RW	255	RANK1. Rank 1 Cooling Coefficient.
7:0	RW	255	RANKO. Rank 0 Cooling Coefficient.



2.18.7 MC_CLOSED_LOOP0 MC_CLOSED_LOOP1 MC_CLOSED_LOOP2

This register controls the closed loop thermal response of the DRAM thermal throttle logic. It supports immediate thermal throttle and 2X refresh. In addition, the register is used to configure the throttling duty cycle.

Device: 4, 5, 6 Function: 3 Offset: 84h Access as a Dword

Bit	Туре	Reset Value	Description
17:8	RW	64	MIN_THROTTLE_DUTY_CYC. This parameter represents the minimum number of DCLKs of operation allowed after throttling. In order to provide actual command opportunities, the number of clocks between CKE de-assertion and first command should be considered. When in Lockstep, this field may not be changed when throttling is possible. This includes THROTTLE_NOW or DDR_THERM# pin assertion, depending on throttling mode selected.
4	RW	0	REF_2X_NOW. Direct control of dynamic 2X refresh if MC_THERMAL_CONTROL.THROTTLE_MODE = 2. This bit can be set only when MC_CHANNEL_X_REFRESH_THROTTLE_SUPPORT.ASR_PRESENT bit is set.
3:0	RW	0	THROTTLE_NOW. Throttler Vector to directly control throttling if MC_THERMAL_CONTROL.THROTTLE_MODE = 2.

2.18.8 MC_THROTTLE_OFFSET0 MC_THROTTLE_OFFSET1 MC_THROTTLE_OFFSET2

Compared against bits [36:29] of virtual temperature of each rank stored in RANK_VIRTUAL_TEMP to determine the throttle point. Recommended value for each rank is 255.

When there are more than 4 ranks attached to the channel, the thermal throttle logic is shared.

Device: 4, 5, 6 Function: 3 Offset: 88h Access as a Dword

Bit	Туре	Reset Value	Description			
31:24	RW	0	RANK3. Rank 3 throttle offset.			
23:16	RW	0	RANK2. Rank 2 throttle offset.			
15:8	RW	0	RANK1. Rank 1 throttle offset.			
7:0	RW	0	RANKO. Rank 0 throttle offset.			



2.18.9 MC_RANK_VIRTUAL_TEMPO MC_RANK_VIRTUAL_TEMP1 MC_RANK_VIRTUAL_TEMP2

This register contains the 8 most significant bits [37:30] of the virtual temperature of each rank. The difference between the virtual temperature and the sensor temperature can be used to determine how fast fan speed should be increased. The value stored is right shifted one bit to the right with respect to the corresponding MC_Throttle_Offset register value. For example when When a rank throttle offset is set to 0x40, the value read from the corresponding in MC_RANK_VIRTUAL_TEMP register is 0x20.

When there are more than 4 ranks attached to the channel, the thermal throttle logic is shared.

Device: 4, 5, 6 Function: 3 Offset: 98h Access as a Dword						
Bit	Туре	Reset Value	Description			
31:24	RO	0	RANK3. Rank 3 virtual temperature.			
23:16	RO	0	RANK2. Rank 2 virtual temperature.			
15:8	RO	0	RANK1. Rank 1 virtual temperature.			
7:0	RO	0	RANKO. Rank 0 virtual temperature.			

2.18.10 MC_DDR_THERM_COMMAND0 MC_DDR_THERM_COMMAND1 MC_DDR_THERM_COMMAND2

This register contains the command portion of the DDR_THERM# functionality as described in the *Intel® Xeon® Processor 5500 Series Datasheet, Volume 1* (i.e. what an assertion of the pin does).

Function Offset:	4, 5, 6 n: 3 9Ch as a Dwor	-d	
Bit	Туре	Reset Value	Description
3	RW	0	THROTTLE. Force throttling when DDR_THERM# pin is asserted.
2	RW	0	RSVD.
1	RW	0	DISABLE_EXTTS. Response to DDR_THERM# pin is disabled. ASSERTION and DEASSERTION fields in the register MC_DDR_THERM_STATUS are frozen.
0	RW1S	0	LOCK. When set, all bits in this register are RO and cannot be written. Reset will clear the lock.



2.18.11 MC_DDR_THERM_STATUS0 MC_DDR_THERM_STATUS1 MC_DDR_THERM_STATUS2

This register contains the status portion of the DDR_THERM# functionality as described in the *Intel® Xeon® Processor 5500 Series Datasheet, Volume 1* (i.e. what is happening or has happened with respect to the pin).

Device: 4, 5, 6 Function: 3 Offset: A4h Access as a Dword Reset Bit Description Type **Value** 2 RO 0 ASSERTION. An assertion edge was seen on DDR_THERM#. Write-1-to-clear. RO 0 **DEASSERTION.** A de-assertion edge was seen on DDR_THERM#. Write-1-to-STATE. Present logical state of DDR_THERM# bit. This is a static indication of 0 RO 0 the pin, and may be several clocks out of date due to the delay between the pin and the signal. STATE = 0 means DDR_THERM# is deasserted STATE = 1 means DDR_THERM# is asserted

2.19 Integrated Memory Controller Miscellaneous Registers

2.19.1 MC_DIMM_CLK_RATIO_STATUS

Contains status information about DIMM clock ratio.

Device: Function: 4 50h Offset: Access as a Dword Reset Bit Type Description Value 28:24 RO MAX_RATIO. Maximum ratio allowed by the part. Value - Qclk 00000 - RSVD 00110 - 800Mhz 01000 - 1066Mhz 01010 - 1333Mhz QCLK_RATIO. Current ratio of Qclk. 4:0 RO 0 Value - Qclk. 00000 - RSVD 00110 - 800Mhz 01000 - 1066Mhz 01010 - 1333Mhz



2.19.2 MC_DIMM_CLK_RATIO

Requested DIMM clock ratio (Qclk). This is the data rate going to the dimm. The clock sent to the DIMM is 1/2 of QCLK rate.

Device: 3 Function: 4 Offset: 54h Access as a Dword						
Bit	Туре	Reset Value	Description			
4:0	RW	6	QCLK_RATIO. Requested ratio of Qclk/Bclk. 00000 - RSVD 00110 - 800Mhz 01000 - 1066Mhz 01010 - 1333Mhz			





3 DIMM Population Requirements

3.1 General Population Requirements

The Intel® 5500 platform offers a wide variety of DIMM configurations. Key parameters used in defining various DIMM configurations are listed in Table 3-1.

Table 3-1. Key Parameters for DIMM Configurations

Parameter	Possible Values
# of Channels	1, 2, or 3
# of DIMM Slots per channel	Two DIMM slots or Three DIMM slots
# of DIMMs Populated per channel	1DPC, 2DPC, or 3DPC (required three DIMM slots per channel)
DIMM Type	RDIMM (w/ECC), UDIMM (w/ or w/o ECC) MetaSDRAM* R-DIMM (8 GB module only)
DIMM Raw Cards	RDIMM Raw Cards as defined by JEDEC: A(1Rx8), B (2Rx8), C (1Rx4), D (2Rx4), E/J (2Rx4), F (4Rx4), or H (4Rx8) UDIMM Raw Cards as defined by JEDEC: A (1Rx8), B (2Rx8), C (1Rx16 ¹), D (1Rx8 w/ECC), E (2Rx8 w/ECC)
DIMM Frequencies	DDR3-800, DDR3-1066, or DDR3-1333

Notes:

Following are generic population requirements:

- All DIMMs must be DDR3 DIMMs.
- The Intel® Xeon® processor 5500 series does not support low voltage (1.35V) DDR3 memory. If 1.35V (DDR3L) and 1.50V (DDR3) DIMMs are mixed, the DIMMs will run at 1.50V.
- Registered DIMMs must be ECC only, Unbuffered DIMMs can be ECC or non-ECC.
- · Mixing of Registered and Unbuffered DIMMs is not allowed.
- Mixing of MetaSDRAM* R-DIMM with any other DIMM type is not allowed.
- It is allowed to mix ECC and non-ECC Unbuffered DIMMs. The presence of a single non-ECC Unbuffered DIMM will result in disabling ECC functionality.
- DIMMs with different timing parameters can be installed on different slots within
 the same channel, but only timings that support the slowest DIMM will be applied
 to all. As a consequence, faster DIMMs will be operated at timings supported by the
 slowest DIMM populated. The same interface frequency (DDR3-800, DDR3-1066,
 or DDR3-1333) will be applied to all DIMMs on all channels on the platform (both
 processors).
- DIMMs with DDR3-1333 speed are allowed only when one DIMM Per Channel (1DPC) is populated. If two 1333 MT/s capable UDIMMs or RDIMMs are detected in the same channel, BIOS would flag this as a warning and force the speed to 1066 MT/s.
- DIMMs with DDR3-1066 speed are allowed only when two DIMMs Per Channel (2DPC) are populated. If three 1066 MT/s capable UDIMMs or RDIMMs are detected in the same channel, BIOS will force the speed to 800 MT/s.

^{1.} UDIMM Raw Card C(1Rx16) is not supported in RDIMM/UDIMM combo designs (a combo platform can support either RDIMM only or UDIMM only but not a mix of both types).



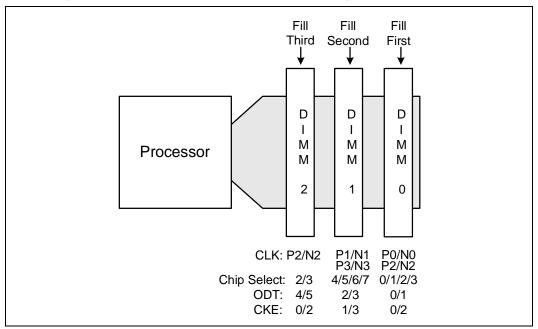
- When one quad rank DIMMs is used, it must be populated in DIMM slot0 (farthest away from the CPU) of a given channel
- Mixing of quad ranks DIMMs (RDIMM Raw Cards F and H) in one channel and three DIMMs in other channel (3DPC) on the same CPU socket is not allowed. If such configuration is detected on a CPU socket, BIOS would flag this as a warning and disable the QR DIMM channel(s).

3.2 Populating DIMMs Within a Channel

3.2.1 DIMM Population for Three Slots per Channel

For three slot per channel configurations, the Intel 5500 platform requires DIMMs within a channel to be populated starting with the DIMMs farthest from the processor in a "fill-farthest" approach (see Figure 3-1). In addition, when populating a Quad-rank DIMM with a Single- or Dual-rank DIMM in the same channel, the Quad-rank DIMM must be populated farthest from the processor. Note that Quad-rank DIMMs and UDIMMs are not allowed in three slots populated configurations. Intel recommends checking for correct DIMM placement during BIOS initialization. Additionally, Intel strongly recommends that all designs follow the DIMM ordering, command clock, and control signal routing documented in Figure 3-1. This addressing must be maintained to be compliant with the reference BIOS code supplied by Intel. All allowed DIMM population configurations for three slots per channel are shown in Table 3-2 and Table 3-3.

Figure 3-1. DIMM Population within a Channel for Three Slots per Channel



Note: ODT[5:4] is muxed with CS[7:6]#.



Table 3-2. RDIMM Population Configurations within a Channel for Three Slots per Channel

Configuration Number	Maximum Supported Speed ¹	1N or 2N	DIMM2	DIMM1	DIMMO
1	DDR3-1333	1N	Empty	Empty	Single-rank
2	DDR3-1333	1 N	Empty	Empty	Dual-rank
3	DDR3-1066	1 N	Empty	Empty	Quad-rank
4	DDR3-1066	1N	Empty	Single-rank	Single-rank
5	DDR3-1066	1N	Empty	Single-rank	Dual-rank
6	DDR3-1066	1N	Empty	Dual-rank	Single-rank
7	DDR3-1066	1 N	Empty	Dual-rank	Dual-rank
8	DDR3-800	1 N	Empty	Single-rank	Quad-rank
9	DDR3-800	1 N	Empty	Dual-rank	Quad-rank
10	DDR3-800	1N	Empty	Quad-rank	Quad-rank
11	DDR3-800	1N	Single-rank	Single-rank	Single-rank
12	DDR3-800	1 N	Single-rank	Single-rank	Dual-rank
13	DDR3-800	1 N	Single-rank	Dual-rank	Single-rank
14	DDR3-800	1 N	Dual-rank	Single-rank	Single-rank
15	DDR3-800	1N	Single-rank	Dual-rank	Dual-rank
16	DDR3-800	1 N	Dual-rank	Single-rank	Dual-rank
17	DDR3-800	1N	Dual-rank	Dual-rank	Single-rank
18	DDR3-800	1N	Dual-rank	Dual-rank	Dual-rank

Notes:

Table 3-3. UDIMM Population Configurations within a Channel for Three Slots per Channel

Configuration Number	Maximum Supported Speed ¹	1N or 2N	DIMM2	DIMM1	DIMMO
1	DDR3-1333	1N	Empty	Empty	Single-rank
2	DDR3-1333	1N	Empty	Empty	Dual-rank
3	DDR3-1066	2N	Empty	Single-rank	Single-rank
4	DDR3-1066	2N	Empty	Single-rank	Dual-rank
5	DDR3-1066	2N	Empty	Dual-rank	Single-rank
6	DDR3-1066	2N	Empty	Dual-rank	Dual-rank

Notes:

1. If a DIMM faster than the maximum supported speed is populated, BIOS will force the memory to run at the maximum supported speed.

^{1.} If a DIMM faster than the maximum supported speed is populated, BIOS will force the memory to run at the maximum supported speed.



Table 3-4. MetaSDRAM* R-DIMM¹ Population Configurations within a Channel for Three Slots per Channel

Configuration Number	Maximum Supported Speed ²	1N or 2N	DIMM2	DIMM1	DIMMO
1	DDR3-1066	1N	Empty	Empty	Dual-rank
2	DDR3-1066	1N	Empty	Dual-rank	Dual-rank
3	DDR3-1066	1N	Dual-rank	Dual-rank	Dual-rank

Notes:

- 8 GB DDR3 MetaSDRAM R-DIMM only. Designers considering the support of MetaSDRAM R-DIMM are recommended to review the platform VR design guidelines as the DC/AC load requirement may be different from that of RDIMM/UDIMM.
- 2. If a DIMM faster than the maximum supported speed is populated, BIOS will force the memory to run at the maximum supported speed.

3.2.2 DIMM Population for Two Slots per Channel

For two slot per channel configurations, the Intel 5500 platform requires DIMMs within a channel to be populated starting with the DIMMs farthest from the processor in a "fill-farthest" approach (see Figure 3-2). In addition, when populating a Quad-rank DIMM with a Single- or Dual-rank DIMM in the same channel, the Quad-rank DIMM must be populated farthest from the processor. Intel recommends checking for correct DIMM placement during BIOS initialization. Additionally, Intel strongly recommends that all designs follow the DIMM ordering, command clock, and control signal routing documented in Figure 3-2. This addressing must be maintained to be compliant with the reference BIOS code supplied by Intel. All allowed DIMM population configurations for two slots per channel are shown in Table 3-5 and Table 3-6.

Figure 3-2. DIMM Population Within a Channel for Two Slots per Channel

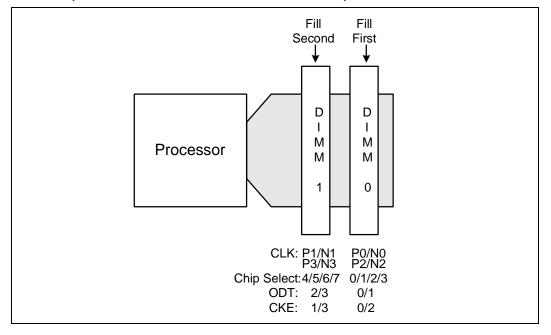




Table 3-5. RDIMM Population Configurations Within a Channel for Two Slots per Channel

Configuration Number	Maximum Supported Speed ¹	1N or 2N	DIMM1	DIMMO
1	DDR3-1333	1N	Empty	Single-rank
2	DDR3-1333	1N	Empty	Dual-rank
3	DDR3-1066	1N	Empty	Quad-rank
4	DDR3-1066	1N	Single-rank	Single-rank
5	DDR3-1066	1N	Single-rank	Dual-rank
6	DDR3-1066	1N	Dual-rank	Single-rank
7	DDR3-1066	1N	Dual-rank	Dual-rank
8	DDR3-800	1N	Single-rank	Quad-rank
9	DDR3-800	1N	Dual-rank	Quad-rank
10	DDR3-800	1N	Quad-rank	Quad-rank

Notes:

Table 3-6. UDIMM Population Configurations within a Channel for Two Slots per Channel

Configuration Number	Maximum Supported Speed ¹	1N or 2N	DIMM1	DIMMO
1	DDR3-1333	1N	Empty	Single-rank
2	DDR3-1333	1N	Empty	Dual-rank
3	DDR3-1066	2N	Single-rank	Single-rank
4	DDR3-1066	2N	Single-rank	Dual-rank
5	DDR3-1066	2N	Dual-rank	Single-rank
6	DDR3-1066	2N	Dual-rank	Dual-rank

Notes:

Table 3-7. MetaSDRAM R-DIMM¹ Population Configurations within a Channel for Two Slots per Channel

Configuration Number	Maximum Supported Speed ²	1N or 2N	DIMM1	DIMMO
1	DDR3-1066	1N	Empty	Dual-rank
2	DDR3-1066	1N	Dual-rank	Dual-rank

Notes:

- 1. 8 GB DDR3 MetaSDRAM R-DIMM only.
- If a DIMM faster than the maximum supported speed is populated, BIOS will force the memory to run at the maximum supported speed.



^{1.} If a DIMM faster than the maximum supported speed is populated, BIOS will force the memory to run at the maximum supported speed.

^{1.} If a DIMM faster than the maximum supported speed is populated, BIOS will force the memory to run at the maximum supported speed.



